



# **System Event Log (SEL)**

## ***Troubleshooting Guide***

Summary and Definition of Events Generated by Intel® Server Board D50TNP and M50CYP Families.

**Rev 1.0**

**June 2021**

<Blank page>

## ***Document Revision History***

<b>Date</b>	<b>Revision</b>	<b>Changes</b>
<b>June 2021</b>	1.0	Initial release.

## ***Disclaimers***

Intel technologies' features and benefits depend on system configuration and may require enabled hardware, software, or service activation. Performance varies depending on system configuration. No computer system can be absolutely secure. Check with your system manufacturer or retailer or learn more at [intel.com](http://intel.com).

You may not use or facilitate the use of this document in connection with any infringement or other legal analysis concerning Intel products described herein. You agree to grant Intel a non-exclusive, royalty-free license to any patent claim thereafter drafted which includes subject matter disclosed herein.

No license (express or implied, by estoppel or otherwise) to any intellectual property rights is granted by this document.

The products described may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Intel disclaims all express and implied warranties, including without limitation, the implied warranties of merchantability, fitness for a particular purpose, and non-infringement, as well as any warranty arising from course of performance, course of dealing, or usage in trade.

This document contains information on products, services and/or processes in development. All information provided here is subject to change without notice. Contact your Intel representative to obtain the latest Intel product specifications.

Copies of documents which have an order number and are referenced in this document may be obtained by calling 1-800-548-4725 or by visiting [www.intel.com/design/literature.htm](http://www.intel.com/design/literature.htm).

Intel, Xeon and the Intel logo are trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries.

\*Other names and brands may be claimed as the property of others.

© Intel Corporation

# Table of Contents

<b>1. Introduction</b>	<b>13</b>
1.1 Purpose	13
1.2 Industry Standard	13
1.2.1 Intelligent Platform Management Interface (IPMI)	13
1.2.2 Baseboard Management Controller (BMC)	14
1.2.3 Intel® Intelligent Power Node Manager Version 3.0	14
<b>2. Basic Decoding of a SEL Record</b>	<b>16</b>
2.1 Default Values in the SEL Records	16
2.2 Notes on SEL Logs and Collecting SEL Information	19
2.2.1 Example of Decoding a PCIe* Correctable Error Events	19
2.2.2 Example of Decoding a Power Supply Predictive Failure Event	19
2.2.3 Example of Decoding an NVMe* Temperature Sensor Event	20
<b>3. Sensor Cross Reference List</b>	<b>21</b>
3.1 BMC-Owned Sensors (GID = 0020h)	21
3.2 BIOS POST-Owned Sensors (GID = 0001h)	25
3.3 BIOS SMI Handler-Owned Sensors (GID = 0033h)	26
3.4 Intel® NM/Intel® ME Firmware-Owned Sensors (GID = 002Ch or 602Ch)	26
3.5 Microsoft* OS-Owned Events (GID = 0041h)	26
3.6 Linux* Kernel Panic Events (GID = 0021h)	27
<b>4. Power Subsystems</b>	<b>28</b>
4.1 Threshold-Based Voltage Sensors	28
4.2 Aggregate Voltage Fault Sensor	29
4.3 Voltage Regulator Watchdog Timer Sensor	34
4.3.1 Voltage Regulator Watchdog Timer Sensor – Next Steps	34
4.4 Power Unit	35
4.4.1 Power Unit Status Sensor	35
4.4.2 Power Unit Redundancy Sensor	36
4.4.3 Node Auto Shutdown Sensor	37
4.5 Power Supply	37
4.5.1 Power Supply Status Sensors	37
4.5.2 Power Supply Power in Sensors	39
4.5.3 Power Supply Current Out % Sensors	39
4.5.4 Power Supply Temperature Sensors	40
4.5.5 Power Supply Fan Tachometer Sensors	41
<b>5. Cooling Subsystem</b>	<b>42</b>
5.1 Fan Sensors	42
5.1.1 Fan Tachometer Sensors	42
5.1.2 Fan Presence and Redundancy Sensors	43
5.2 Temperature Sensors	45

5.2.1	Threshold-based Temperature Sensors .....	45
5.2.2	Thermal Margin Sensors .....	48
5.2.3	Processor Thermal Control Sensors .....	49
5.2.4	Processor DTS Thermal Margin Sensors.....	50
5.2.5	Aggregate VRD-Hot Sensor .....	50
5.2.6	Discrete Thermal Sensors .....	51
5.2.7	Liquid Cooling.....	52
5.2.8	DIMM Thermal Trip Sensors.....	53
5.2.9	NVMe* Thermal Status.....	54
5.3	System Airflow Monitoring Sensor .....	55
<b>6.</b>	<b>Processor Subsystem .....</b>	<b>56</b>
6.1	Processor Status Sensor .....	56
6.2	Internal Error Sensor .....	57
6.3	CPU Missing Sensor .....	58
6.3.1	CPU Missing Sensor – Next Steps .....	58
6.4	Intel® UPI Interconnect Sensors.....	58
6.4.1	Intel® UPI Link Width Reduced Sensor.....	59
6.4.2	Intel® UPI Correctable Error Sensor .....	59
6.5	Processor ERR2 Timeout Sensor.....	60
6.5.1	Processor ERR2 Timeout – Next Steps .....	60
<b>7.</b>	<b>Memory Subsystem .....</b>	<b>61</b>
7.1	Memory RAS Configuration Status .....	61
7.2	Memory RAS Mode Select.....	62
7.3	Mirroring Redundancy State.....	63
7.3.1	Mirroring Redundancy State Sensor – Next Steps .....	63
7.4	Sparing Redundancy State.....	63
7.4.1	Sparing Redundancy State Sensor – Next Steps .....	64
7.5	Memory RAS ADC/ADDDC Mode.....	64
7.6	ECC and Address Parity .....	65
7.6.1	Memory Correctable and Uncorrectable ECC Error.....	65
7.6.2	Memory Address Parity Error.....	66
<b>8.</b>	<b>PCI Express* and Legacy PCI Subsystem .....</b>	<b>68</b>
8.1	Legacy PCI Errors .....	68
8.1.1	Legacy PCI Error Sensor – Next Steps .....	68
8.2	PCIe* Errors.....	68
8.2.1	PCIe* Fatal Errors and Fatal Error #2 .....	69
8.2.2	PCIe* Correctable Errors .....	70
8.2.3	IIO Internal Error.....	71
<b>9.</b>	<b>System BIOS Events.....</b>	<b>72</b>
9.1	System Boot .....	72
9.2	System Firmware Progress (Formerly POST Error).....	72

9.2.1	System Firmware Progress (Formerly POST Error) – Next Steps.....	73
<b>10.</b>	<b>Chassis Subsystem.....</b>	<b>79</b>
10.1	Physical Security.....	79
10.1.1	Chassis Intrusion .....	79
10.1.2	LAN Leash Lost.....	79
10.2	Front Panel (NMI) Interrupt.....	80
10.2.1	Front Panel (NMI) Interrupt – Next Steps .....	80
10.3	Button Sensor.....	81
<b>11.</b>	<b>Miscellaneous Events .....</b>	<b>82</b>
11.1	IPMI Watchdog.....	82
11.2	System Management Interrupt (SMI) Timeout .....	83
11.2.1	SMI Timeout – Next Steps .....	83
11.3	System Event Log Cleared .....	83
11.4	System Event Sensor.....	84
11.4.1	System Event – PEF Action .....	84
11.4.2	System Event – OOB Update and BIOS Configuration Change .....	85
11.5	BMC Hardware Watchdog Sensor .....	85
11.5.1	BMC Watchdog Sensor – Next Steps .....	86
11.6	MTM Level Change Sensor.....	86
11.7	Add-In Module/Board Presence Sensor.....	86
11.7.1	Add-In Module Presence – Next Steps .....	87
11.8	BMC Firmware Health Sensor .....	87
11.8.1	BMC Firmware Health Sensor – Next Steps .....	87
11.9	Firmware Update Status Sensor .....	88
11.10	Sensor Data Record (SDR) Auto-Config Fault .....	89
11.10.1	SDR Auto-Config Fault Sensor – Next Steps.....	89
11.11	Invalid user name or password sensor .....	90
11.12	Remote debug sensor .....	90
11.12	System Firmware Security Sensor .....	91
11.13	KCS Policy Sensor.....	92
<b>12.</b>	<b>Hot-Swap Controller Backplane Events.....</b>	<b>94</b>
12.1	Hot-Swap Controller (HSC) Backplane Temperature Sensor.....	94
12.2	Hard Disk Drive Monitoring Sensor .....	94
<b>13.</b>	<b>Intel® Management Engine (Intel® ME) Events .....</b>	<b>96</b>
13.1	Intel® ME Firmware Health Event.....	96
13.1.1	Intel® ME Firmware Health Event – Next Steps.....	96
13.2	Intel® Node Manager Exception Event .....	98
13.2.1	Intel® Node Manager Exception Event – Next Steps.....	98
13.3	Intel® Node Manager Health Event .....	98
13.3.1	Intel® Node Manager Health Event – Next Steps .....	99
13.4	Intel® Node Manager Operational Capabilities Change .....	99

13.4.1	Intel® Node Manager Operational Capabilities Change – Next Steps .....	100
13.5	Intel® Node Manager Alert Threshold Exceeded .....	101
13.5.1	Intel® Node Manager Alert Threshold Exceeded – Next Steps .....	101
13.6	Intel® Node Manager SmarT and CLST Sensor.....	101
13.6.1	Intel® Node Manager SmarT/CLST Event – Next Steps.....	102
<b>14.</b>	<b>Microsoft Windows* Records.....</b>	<b>103</b>
14.1	Boot Up Event Records.....	103
14.2	Shutdown Event Records.....	103
14.3	Bug Check/Blue Screen Event Records .....	104
<b>15.</b>	<b>Linux* Kernel Panic Records .....</b>	<b>106</b>
<b>Appendix A.</b>	<b>Glossary.....</b>	<b>107</b>



## List of Tables

Table 1. SEL Record Format .....	16
Table 2. Event Request Message Event Data Field Contents .....	17
Table 3. OEM SEL Record (Type C0h-Dfh).....	18
Table 4. OEM SEL Record (Type E0h-Ffh).....	18
Table 5. M50CYP BMC-Owned Sensors .....	21
Table 6. D50TNP BMC.....	23
Table 7. BIOS POST Owned Sensors .....	25
Table 8. BIOS SMI Handler Owned Sensors .....	26
Table 9. Intel® Management Engine Firmware-Owned Sensors .....	26
Table 10. Microsoft* OS-Owned Events.....	26
Table 11. Linux* Kernel Panic Events .....	27
Table 12. Threshold-Based Voltage Sensors Typical Characteristics .....	28
Table 13. Threshold-Based Voltage Sensors Event Triggers.....	28
Table 14. Threshold-Based Voltage Sensors – Next Steps.....	29
Table 15. Aggregate Voltage Sensors Typical Characteristics.....	29
Table 16. Discrete Voltage Sensors – Next Steps.....	31
Table 17. Voltage Regulator Watchdog Timer Sensor Typical Characteristics .....	34
Table 18. Power Unit Status Sensors Typical Characteristics.....	35
Table 19. Power Unit Status Sensor – Sensor Specific Offsets – Next Steps .....	35
Table 20. Power Unit Redundancy Sensors Typical Characteristics .....	36
Table 21. Power Unit Redundancy Sensor – Event Trigger Offset – Next Steps.....	36
Table 22. Node Auto Shutdown Sensor Typical Characteristics.....	37
Table 23. Power Supply Status Sensors Typical Characteristics .....	37
Table 24. Power Supply Status Sensor – Sensor Specific Offsets – Next Steps.....	38
Table 25. Power Supply Power In Sensors Typical Characteristics.....	39
Table 26. Power Supply Power In Sensor – Event Trigger Offset – Next Steps.....	39
Table 27. Power Supply Current Out % Sensors Typical Characteristics .....	39
Table 28: Power Supply Current Out % Sensor – Event Trigger Offset – Next Steps.....	40
Table 29. Power Supply Temperature Sensors Typical Characteristics .....	40
Table 30. Power Supply Temperature Sensor – Event Trigger Offset – Next Steps.....	40
Table 31. Power Supply Fan Tachometer Sensors Typical Characteristics .....	41
Table 32. Fan Tachometer Sensors Typical Characteristics .....	42
Table 33. Fan Tachometer Sensor – Event Trigger Offset – Next Steps.....	42
Table 34. Fan Presence Sensors Typical Characteristics .....	43
Table 35. Fan Presence Sensors – Event Trigger Offset – Next Steps.....	43
Table 36. Fan Redundancy Sensors Typical Characteristics.....	44
Table 37. Fan Redundancy Sensor – Event Trigger Offset – Next Steps .....	44
Table 38. Temperature Sensors Typical Characteristics.....	45
Table 39. Temperature Sensors Event Triggers.....	45

Table 40. Temperature Sensors – Next Steps.....	46
Table 41. Thermal Margin Sensors Typical Characteristics .....	48
Table 42. Thermal Margin Sensors Event Triggers.....	48
Table 43. Thermal Margin Sensors – Next Steps.....	48
Table 44. Processor Thermal Control Sensors Typical Characteristics .....	49
Table 45. Processor Thermal Control Sensors Event Triggers.....	49
Table 46. Processor DTS Thermal Margin Sensors Typical Characteristics.....	50
Table 47. VRD-Hot Sensors Typical Characteristics.....	50
Table 48. PCH Thermal Trip Sensors Typical Characteristics .....	51
Table 49. VRD HOT Sensor Typical Characteristics.....	51
Table 50. Threshold-Based Voltage Sensors Typical Characteristics .....	52
Table 51. Threshold-Based Voltage Sensors Event Triggers.....	53
Table 52. DIMM Thermal Trip Typical Characteristics.....	53
Table 53. NVMe* Temperature Sensor Typical Characteristics.....	54
Table 54. NVMe* Critical Warning Sensor Typical Characteristics.....	55
Table 55. SMART Warning Bits.....	55
Table 56. Process Status Sensors Typical Characteristics.....	56
Table 57. Processor Status Sensors – Next Steps.....	57
Table 58. Internal Error Sensor Typical Characteristics .....	57
Table 59. Internal Error Sensor – Event Data 2 Values – Next Steps .....	58
Table 60. CPU Missing Sensor Typical Characteristics .....	58
Table 61. Intel® UPI Link Width Reduced Sensor Typical Characteristics.....	59
Table 62. Intel UPI® Correctable Error Sensor Typical Characteristics.....	59
Table 63. Processor ERR2 Timeout Sensor Typical Characteristics.....	60
Table 64. Memory RAS Configuration Status Sensor Typical Characteristics.....	61
Table 65. Memory RAS Configuration Status Sensor – Event Trigger Offset – Next Steps .....	62
Table 66. Memory RAS Mode Select Sensor Typical Characteristics.....	62
Table 67. Mirroring Redundancy State Sensor Typical Characteristics For Intel® Server Boards Based On Intel® Server Board Based On The 3rd Gen Intel® Scalable Processor Family.....	63
Table 68. Sparing Redundancy State Sensor Typical Characteristics .....	64
Table 69. Memory ADDDC Mode Sensor Typical Characteristics.....	64
Table 70. Correctable And Uncorrectable ECC Error Sensor Typical Characteristics.....	65
Table 71. Correctable And Uncorrectable ECC Error Sensor Event Trigger Offset – Next Steps.....	66
Table 72. Address Parity Error Sensor Typical Characteristics.....	66
Table 73. Legacy PCI Error Sensor Typical Characteristics .....	68
Table 74. PCIe* Fatal Error Sensor Typical Characteristics .....	69
Table 75. Pcie* Fatal Error #2 Sensor Typical Characteristics .....	69
Table 76. Pcie* Correctable Error Sensor Typical Characteristics.....	70
Table 77. IIO Internal Error Sensor Typical Characteristics .....	71
Table 78. System Event Sensor Typical Characteristics.....	72
Table 79. POST Error Sensor Typical Characteristics.....	72

Table 80. POST Error Codes.....	73
Table 81. Physical Security Sensor Typical Characteristics .....	79
Table 82. Physical Security Sensor Event Trigger Offset – Next Steps .....	79
Table 83. Front Panel (NMI) Interrupt Sensor Typical Characteristics.....	80
Table 84. Button Sensor Typical Characteristics .....	81
Table 85. IPMI Watchdog Sensor Typical Characteristics.....	82
Table 86. IPMI Watchdog Sensor Event Trigger Offset – Next Steps.....	82
Table 87. SMI Timeout Sensor Typical Characteristics.....	83
Table 88. System Event Log Cleared Sensor Typical Characteristics .....	83
Table 89. System Event – PEF Action Sensor Typical Characteristics .....	84
Table 90. System Event – BIOS/Intel® ME OOB Update And BIOS Configuration Change .....	85
Table 91. BMC Hardware Watchdog Sensor Typical Characteristics.....	85
Table 92. MTM Level Change Sensor .....	86
Table 93. Add-In Module Presence Sensor Typical Characteristics.....	86
Table 94. BMC Firmware Health Sensor Typical Characteristics .....	87
Table 95. Firmware Update Status Sensor Typical Characteristics .....	88
Table 96. SDR Auto-Config Fault Sensor .....	89
Table 97. Bad User PWD sensor .....	90
Table 98. Remote Debug Sensor.....	90
Table 99. System Firmware Security Sensor .....	91
Table 100. BMC KCS Policy Control Modes and KCS command service definition.....	93
Table 101. KCS Policy Sensor.....	93
Table 102. HSC Backplane Temperature Sensor Typical Characteristics.....	94
Table 103. HSC Backplane Temperature Sensor – Event Trigger Offset – Next Steps .....	94
Table 104. Hard Disk Drive Monitoring Sensor Typical Characteristics.....	94
Table 105. Hard Disk Drive Monitoring Sensor – Event Trigger Offset – Next Steps .....	95
Table 106. Intel® ME Firmware Health Event Sensor Typical Characteristics.....	96
Table 107. Intel® ME Firmware Health Event Sensor – Next Steps .....	96
Table 108. Intel® Node Manager Exception Sensor Typical Characteristics .....	98
Table 109. Intel® Node Manager Health Event Sensor Typical Characteristics .....	99
Table 110. Intel® Node Manager Operational Capabilities Change Sensor Typical Characteristics .....	100
Table 111. Intel® Node Manager Alert Threshold Exceeded Sensor Typical Characteristics .....	101
Table 112. Intel® Node Manager Smart/CLST Event Typical Characteristics .....	102
Table 113. Smart And CLST Sensor Severity Codes.....	102
Table 114. Boot Up Event Record Typical Characteristics .....	103
Table 115. Boot Up OEM Event Record Typical Characteristics .....	103
Table 116. Shutdown Reason Code Event Record Typical Characteristics.....	104
Table 117. Shutdown Reason OEM Event Record Typical Characteristics.....	104
Table 118. Shutdown Comment OEM Event Record Typical Characteristics .....	104
Table 119. Bug Check/Blue Screen – OS Stop Event Record Typical Characteristics .....	105
Table 120. Bug Check/Blue Screen Code OEM Event Record Typical Characteristics .....	105

Table 121. Linux* Kernel Panic Event Record Characteristics .....	106
Table 122. Linux* Kernel Panic String Extended Record Characteristics .....	106

# 1. Introduction

---

The server management hardware that is part of the Intel® Server Boards and Intel® Server Platforms serves as a vital part of the overall server management strategy. The server management hardware provides essential information to the system administrator and provides the administrator the ability to remotely control the server, even when the operating system is not running.

The Intel® Server Boards and Intel® Server Platforms offer comprehensive hardware and software based solutions. The server management features make the servers simple to manage and provide alerting on system events. From entry to enterprise systems, good overall server management is essential to reduce overall total cost of ownership.

This troubleshooting guide is intended to help the users better understand the events that are logged in the Baseboard Management Controllers (BMC) System Event Logs (SEL) on these Intel® Server Boards.

There is a separate user guide that covers the general server management and the server management software offered on the Intel® Server Boards and Intel® Server Platforms.

This document supports the following Intel® Server products currently supported by this document:

- Intel® Server System D50TNP and M50CYP families supporting the 3rd Gen Intel® Xeon® Scalable processor family.

## 1.1 Purpose

The purpose of this document is to list all possible events generated by the Intel platform. It may be possible that other sources (not under Intel's control) also generate events, which are not described in this document.

## 1.2 Industry Standard

### 1.2.1 Intelligent Platform Management Interface (IPMI)

The key characteristic of the Intelligent Platform Management Interface (IPMI) is that the inventory, monitoring, logging, and recovery control functions are available independently of the main processors, BIOS, and operating system. Platform management functions can also be made available when the system is in a power-down state.

IPMI works by interfacing with the BMC, which extends management capabilities in the server system and operates independently of the main processor by monitoring the on-board instrumentation. Through the BMC, IPMI also allows administrators to control power to the server and remotely access BIOS configuration and operating system console information.

IPMI defines a common platform instrumentation interface to enable interoperability between

- The baseboard management controller and chassis;
- The baseboard management controller and systems management software; and
- Between servers.

IPMI enables the following:

- Common access to platform management information, consisting of
  - Local access from systems management software;
  - Remote access from LAN;
  - Inter-chassis access from Intelligent Chassis Management Bus; and
  - Access from LAN, serial/modem, IPMB, PCI SMBus\*, or ICMB, available even if the processor is down.

- Isolation of systems management software from hardware.
- Ability to make hardware advancements without impacting the systems management software.
- Facilitation of cross-platform management software.

Find more information on IPMI at <http://www.intel.com/design/servers/ipmi>.

## 1.2.2 Baseboard Management Controller (BMC)

A baseboard management controller (BMC) is a specialized microcontroller embedded on most Intel Server Boards. The BMC is the heart of the IPMI architecture and provides the intelligence behind intelligent platform management, that is, the autonomous monitoring and recovery features implemented directly in platform management hardware and firmware.

Different types of sensors built into the computer system report to the BMC on parameters such as temperature, cooling fan speeds, power mode, operating system status, and so on. The BMC monitors the system for critical events by communicating with various sensors on the system board; it sends alerts and logs events when certain parameters exceed their preset thresholds, indicating a potential failure of the system. The administrator can also remotely communicate with the BMC to take some corrective action such as resetting or power cycling the system to get a hung OS running again. These abilities save on the total cost of ownership of a system.

For Intel Server Boards and Intel Server Platforms, the BMC supports the industry standard *IPMI 2.0 Specification*, enabling remote configuration, monitoring, and systems recovery.

### 1.2.2.1 System Event Log (SEL)

The BMC provides a centralized, non-volatile repository for critical, warning, and informational system events called the System Event Log (SEL). By having the BMC manage the SEL and logging functions, it helps to ensure that “post-mortem” logging information is available if a failure occurs that disables the system processor(s).

The BMC allows access to the SEL from in-band and out-of-band mechanisms. There are various tools and utilities that can be used to access the SEL including the SELView utility and multiple open sourced IPMI tools.

## 1.2.3 Intel® Intelligent Power Node Manager Version 3.0

Intel® Intelligent Power Node Manager version 3.0 is a platform-resident technology that enforces power and thermal policies for the platform. These policies are applied by exploiting subsystem knobs (such as processor P and T states) that can be used to control power consumption. Intel® Intelligent Power Node Manager enables data center power and thermal management by exposing an external interface to management software through which platform policies can be specified. It also enables specific data center power management usage models such as power limiting.

The configuration and control commands are used by the external management software or BMC to configure and control the Intel® Intelligent Power Node Manager feature. Because the platform firmware does not have any external interface, external commands are first received by the BMC over LAN and then relayed to the platform firmware over Intelligent Power Management Bus (IPMB) channel. The BMC acts as a relay and the transport conversion device for these commands. For simplicity, the commands from the management console might be encapsulated in a generic CONFIG packet format (configuration data length, configuration data blob) to the BMC so that the BMC does not even have to parse the actual configuration data.

The BMC provides the access point for remote commands from external management software and generates alerts to them. Intel® Intelligent Power Node Manager on Intel® Management Engine (Intel® ME) is

an IPMI satellite controller. A mechanism exists to forward commands to Intel® ME and then sends the response back to originator. Similarly events from Intel® ME are sent as alerts outside of the BMC.

## 2. Basic Decoding of a SEL Record

The System Event Log (SEL) record format is defined in the *IPMI Specification*. The following section provides a basic definition for each of the fields in a SEL. For more details, see the *IPMI Specification*.

The definitions for the standard SEL can be found in Table 1.

The definitions for the OEM defined event logs can be found in Table 3 and Table 4.

### 2.1 Default Values in the SEL Records

Unless otherwise noted in the event record description, the following are the default values for all SEL entries.

- Byte [3] = Record Type (RT) = 02h = System event record
- Byte [9:8] = Generator ID = 0020h = BMC firmware
- Byte [10] = Event Message Revision (ER) = 04h = IPMI 2.0

**Table 1. SEL Record Format**

Byte	Field	Description
1, 2	Record ID (RID)	ID used for SEL record access.
3	Record Type (RT)	[7:0] – Record type 02h = System event record (default) C0h-DFh = OEM timestamped, bytes 8–16 OEM defined (see Table 3) E0h-FFh = OEM non-timestamped, bytes 4–16 OEM defined (see Table 4)
4–7	Timestamp (TS)	Time when the event was logged. The least significant byte is first. For example, TS:[29][76][68][4C] = 4C687629h = 1281914409 = Sun, 15 Aug 2010 23:20:09 UTC <b>Note:</b> There are various websites that convert the raw number to a date/time.
8, 9	Generator ID (GID)	RqSA and LUN if event was generated from IPMB. Software ID if event was generated from system software.  <i>Byte 1</i> [7:1] – 7-bit I2C slave address, or 7-bit system software ID [0] – 0b = ID is IPMB slave address, 1b = System software ID Software ID values: 0001h – BIOS POST for POST errors, RAS configuration/state, timestamp synch, OS boot events 0033h – BIOS SMI handler 0020h – BMC firmware (default) 002Ch – Intel® ME firmware 0041h – Server management software 00C0h – HSC firmware – HSBP A 00C2h – HSC firmware – HSBP B  <i>Byte 2</i> [7:4] – Channel number. Channel that event message was received over. 0h if the event message was received from the system interface, primary IPMB, or internally generated by the BMC. [3:2] – Reserved. Write as 00b. [1:0] – IPMB device LUN if byte 1 holds slave address. 00b otherwise.
10	EvM Rev (ER)	Event message format version. 04h = IPMI v2.0 (default) 03h = IPMI v1.0
11	Sensor Type (ST)	Sensor type code for sensor that generated the event.
12	Sensor # (SN)	Number of sensors that generated the event (from SDR).



## System Event Log (SEL) Troubleshooting Guide

Byte	Field	Description
13	Event Dir/Event Type (EDIR)	<p><i>Event Dir</i> [7] – 0b = Assertion event, 1b = Deassertion event.</p> <p><i>Event Type</i> Type of trigger for the event; for example, critical threshold going high, state asserted, and so on. Also indicates class of the event; for example, discrete, threshold, or OEM. The Event Type field is encoded using the Event/Reading Type Code.</p> <p>[6:0] – Event Type Codes                      01h = Threshold (states = 0x00-0x0b)                      02h-0ch = Discrete                      6Fh = Sensor-specific                      70-7Fh = OEM</p>
14	Event Data 1 (ED1)	See Table 2.
15	Event Data 2 (ED2)	
16	Event Data 3 (ED3)	

**Table 2. Event Request Message Event Data Field Contents**

Sensor Class	Event Data
<b>Threshold</b>	<p><i>Event Data 1</i> [7:6] –                      00b = Unspecified Event Data 2                      01b = Trigger reading in Event Data 2                      10b = OEM code in Event Data 2                      11b = Sensor-specific event extension code in Event Data 2                      [5:4] –                      00b = Unspecified Event Data 3                      01b = Trigger threshold value in Event Data 3                      10b = OEM code in Event Data 3                      11b = Sensor-specific event extension code in Event Data 3                      [3:0] – Offset from Event/Reading Code for threshold event.</p> <p><i>Event Data 2</i> – Reading that triggered event, FFh or not present if unspecified.  <i>Event Data 3</i> – Threshold value that triggered event, FFh or not present if unspecified. If present, Event Data 2 must be present.</p>
<b>Discrete</b>	<p><i>Event Data 1</i> [7:6] –                      00b = Unspecified Event Data 2                      01b = Previous state and/or severity in Event Data 2                      10b = OEM code in Event Data 2                      11b = Sensor-specific event extension code in Event Data 2                      [5:4] –                      00b = Unspecified Event Data 3                      01b = Reserved                      10b = OEM code in Event Data 3                      11b = Sensor-specific event extension code in Event Data 3                      [3:0] – Offset from Event/Reading Code for discrete event state</p> <p><i>Event Data 2</i> [7:4] – Optional offset from “Severity” Event/Reading Code (0Fh if unspecified).                      [3:0] – Optional offset from Event/Reading Type Code for previous discrete event state (0Fh if unspecified).</p> <p><i>Event Data 3</i> – Optional OEM code. FFh or not present if unspecified.</p>

## System Event Log (SEL) Troubleshooting Guide

Sensor Class	Event Data
<b>OEM</b>	<p><i>Event Data 1</i></p> <p>[7:6] –</p> <ul style="list-style-type: none"> <li>00b = Unspecified in Event Data 2</li> <li>01b = Previous state and/or severity in Event Data 2</li> <li>10b = OEM code in Event Data 2</li> <li>11b = Reserved</li> </ul> <p>[5:4] –</p> <ul style="list-style-type: none"> <li>00b = Unspecified Event Data 3</li> <li>01b = Reserved</li> <li>10b = OEM code in Event Data 3</li> <li>11b = Reserved</li> </ul> <p>[3:0] – Offset from Event/Reading Type Code</p> <p><i>Event Data 2</i></p> <p>[7:4] – Optional OEM code bits or offset from “Severity” Event/Reading Type Code (0Fh if unspecified).</p> <p>[3:0] – Optional OEM code or offset from Event/Reading Type Code for previous event state (0Fh if unspecified).</p> <p><i>Event Data 3</i> – Optional OEM code. FFh or not present if unspecified.</p>

**Table 3. OEM SEL Record (Type C0h-Dfh)**

Byte	Field	Description
1, 2	Record ID (RID)	ID used for SEL Record access.
3	Record Type (RT)	[7:0] – Record Type C0h-Dfh = OEM timestamped, bytes 8–16 OEM defined
4–7	Timestamp (TS)	Time when the event was logged. The least significant byte is first. For example, TS:[29][76][68][4C] = 4C687629h = 1281914409 = Sun, 15 Aug 2010 23:20:09 UTC <b>Note:</b> There are various websites that convert the raw number to a date/time.
8–10	Manufacturer ID	The least significant byte is first. The manufacturer ID is a 20-bit value that is derived from the IANA “Private Enterprise” ID. Most significant four bits = Reserved (0000b). 000000h = Unspecified, 0FFFFFFh = Reserved. This value is binary encoded. For example, the ID for the IPMI forum is 7154 decimal, which is 1BF2h, which will be stored in this record as F2h, 1Bh, and 00h for bytes 8 through 10, respectively.
11-16	OEM Defined	Defined according to the manufacturer identified by the Manufacturer ID field.

**Table 4. OEM SEL Record (Type E0h-Ffh)**

Byte	Field	Description
1, 2	Record ID (RID)	ID used for SEL Record access.
3	Record Type (RT)	[7:0] – Record Type E0h-FFh = OEM system event record
4–16	OEM	OEM Defined. This is defined by the system integrator.

## 2.2 Notes on SEL Logs and Collecting SEL Information

When capturing the SEL log, always collect both the text/human readable version and the hex version. Because some of the data is OEM-specific, some utilities cannot decode the information correctly. In addition, with some OEM-specific data there may be additional variables that are not decoded at all.

The following section provides examples of not decoding all the information.

See section 2.2.1 for the PCIe\* errors. The type of error and the PCI Bus, Device, and Function are all a part of Event Data 1 through Event Data 3.

See section 2.2.2 for the Power Supply events. When there is a failure, predictive failure, or a configuration error, Event Data 2 and Event Data 3 hold additional information describing the Power Supply PMBus\* Command Registers and values for that particular event.

### 2.2.1 Example of Decoding a PCIe\* Correctable Error Events

The following is an example of decoding a PCIe\* correctable error event. For this particular event, it recorded a receiver error on Bus 0, Device 2, and Function 2. Correctable errors are acceptable and normal at a low rate of occurrence.

```
RID[27][00] RT[02] TS[0A][9B][2E][50] GID[33][00] ER[04] ST[13] SN[05] EDIR[71] ED1[A0] ED1[00] ED3[12]
  RID (Record ID) = 0027h
  RT (Record Type) = 02h = system event record
  TS (Timestamp) = 502E9B0Ah
  GID (Generator ID) = 0033h = BIOS SMI Handler
  ER (Event Message Revision) = 04h = IPMI v2.0
  ST (Sensor Type) = 13h = Critical Interrupt (From IPMI Specification Table 42-3, Sensor Type Codes)
  SN (Sensor Number) = 05h
  EDIR (Event Direction/Event Type) = 71h
    [7] = 0b = Assertion Event
    [6:0] = 71h = OEM Specific for PCI Express* correctable errors
  ED1 (Event Data 1) = A0h
    [7:6] = 10b = OEM code in Event Data 2
    [5:4] – 10b = OEM code in Event Data 3
    [3:0] – Event Trigger Offset = 0h = Receiver Error
  ED2 (Event Data 2) = 00h; PCI Bus number = 0h
  ED3 (Event Data 3) = 12h
    [7:3] – PCI Device number = 02h
    [2:0] – PCI Function number = 2h
```

### 2.2.2 Example of Decoding a Power Supply Predictive Failure Event

The following is an example of decoding a Power Supply predictive failure event. For this example, power supply 1 saw an AC power loss event with both the input under-voltage warning and fault events getting set. In most cases, this means that the AC power spiked under the minimum warning and fault thresholds for over 20 milliseconds but the system remained powered on. If these events continue to occur, it is advisable to check the power source.

```
RID[5D][00] RT[02] TS[D3][B1][AE][4E] GID[20][00] ER[04] ST[08] SN[50] EDIR[6F] ED1[A2] ED2[06] ED3[30]
  RID (Record ID) = 005Dh
  RT (Record Type) = 02h = system event record
  TS (Timestamp) = 4EAEB1D3h
  GID (Generator ID) = 0020h = BMC
  ER (Event Message Revision) = 04h = IPMI v2.0
  ST (Sensor Type) = 08h = Power Supply (From IPMI Specification Table 42-3, Sensor Type Codes)
  SN (Sensor Number) = 50h = Power Supply 1
```

EDIR (Event Direction/Event Type) = 6Fh

[7] = 0b = Assertion Event

[6:0] = 6fh = Sensor specific

ED1 (Event Data 1) = A2h

[7:6] = 10b = OEM code in Event Data 2

[5:4] – 10b = OEM code in Event Data 3

[3:0] – Event Trigger Offset = 2h = Predictive Failure

ED2 (Event Data 2) = 06h = Input under-voltage warning

ED3 (Event Data 3) = 30h; From *PMBus\* Specification* STATUS\_INPUT command

[5] – VIN\_UV\_WARNING (Input Under-voltage Warning) = 1b

[4] – VIN\_UV\_FAULT (Input Under-voltage Fault) = 1b

### 2.2.3 Example of Decoding an NVMe\* Temperature Sensor Event

The following is an example of decoding an NVMe\* temperature sensor event. The NVMe\* temperature SEL occurs when the aggregate temperature sensor reading reaches the upper critical threshold. To report which of several drives are over temperature, OEM extended data bytes are used. The remainder of the SEL uses standard temperature sensor decoding rules.

The NVMe\* temperature SEL uses a new format for the OEM extended data bytes. See the *Intel® Server System Integrated Baseboard Management Controller Firmware External Product Specification*.

ExtData[0] already has an established format. Bits 0–1 define the severity of the SEL. Bits 4–6 define the number of extended data bytes. Bits 2–3 and 7 are reserved. The new format is detailed below.

ExtData[0]

[7] = Extended format indicator

[6:4] = # Extended Data bytes

[3:2] = reserved

[1:0] = Existing severity encoding

ExtData[1] = Extended Format Byte Code

0 = Reserved

1 = Drive Position Format

2 = Critical Warning Format

3 = Add in card format

4-0xff = Reserved

ExtData[2]

For Format = 1 (Drive Position Format), ExtData[2] is a bitfield indicating which drives are over temperature. Bit 0 set indicates Drive 0 is over temp. Bit 7 set indicates Drive 7 is over temp.

Exertion example:

RID:0099 RT:02 TS:558BEF64 GID:0020 ER:04 ST:01 S#:92 ET:01 ED:59 01 00 OEM:A2 01 20 FF FF FF FF FF

ExtData[0] = 0xA2

Bit 7 set, so ExtData[1] is format indicator

Bit 6-4 = 2, indicating 2 more OEM bytes (format, bitfield)

Bit 1-0 = 2, indicating this is a Critical SEL

ExtData[1] = 0x01, indicating Drive Position Format

ExtData[2] = 0x20, indicating drive slot 5 (zero based) is over temp

### 3. Sensor Cross Reference List

This chapter contains a cross reference to help find details on any specific SEL entry.

#### 3.1 BMC-Owned Sensors (GID = 0020h)

The following table can be used to find the details of sensors owned by the BMC.

**Table 5. M50CYP BMC-Owned Sensors**

Sensor #	Sensor Name	Details Section	Next Steps
01h	Power Unit Status (Pwr Unit Status)	4.4.1	Table 19
02h	Power Unit Redundancy (Pwr Unit Redund)	4.4.2	Table 21
03h	IPMI Watchdog (IPMI Watchdog)	11.1	Table 86
04h	Physical Security (Physical Scrty)	10.1	Table 82
05h	FP Interrupt (FP NMI Diag Int)	10.2	Section 10.2.1
06h	SMI Timeout (SMI Timeout)	11.2	Section 11.2.1
07h	System Event Log (System Event Log)	11.3	Not applicable
08h	System Event (System Event)	11.4	Section 11.4.1
09h	Button Sensor (Button)	10.3	Not applicable
0Ah	BMC Watchdog (BMC Watchdog)	11.5	Section 11.5.1
0Bh	Voltage Regulator Watchdog (VR Watchdog)	4.3	Section 4.3.1
0Ch	Fan Redundancy (Fan Redundancy)	5.1.2	Table 37
0Dh	SSB Thermal Trip (SSB Thermal Trip)	5.2.6.1	Section 5.2.6.3
0Eh	OCM Module Presence (OCM Mod Presence)	11.7	Section 11.7.1
0Fh	SAS Module Presence (SAS Mod Presence)	11.7	Section 11.7.1
10h	BMC Firmware Health (BMC FW Health)	11.8	Section 11.8.1
11h	System Airflow (System Airflow)	5.3	Not applicable
12h	Firmware Update Status (FW Update Status)	11.9	Not applicable
14h	Baseboard Temperature 5 (BB Lft Rear Temp)	5.2.1	Table 40
1Ah	Firmware Security(FW Security)	11.13	Not applicable
20h	Baseboard Temperature 1 (BB P0 VR Temp)	5.2.1	Table 40
21h	Front Panel Temperature (Front Panel Temp)	5.2.1	Table 40
22h	PCH Temperature(PCH Temp)	5.2.1	Table 40
23h	Baseboard Temperature 2 (BB P1 VR Temp)	5.2.1	Table 40
24h	Baseboard Temperature 3 (BB BMC Temp)	5.2.1	Table 40
25h	Baseboard Temperature 4 (BB M.2 Temp)	5.2.1	Table 40
26h	OCM Module Temperature (OCM Mod Temp)	5.2.1	Table 40
27h	Hot-swap Backplane 1 Temperature (1U HSBP Temp)	12.1	Table 103
29h	Hot-swap Backplane 1 Temperature (2U HSBP 1 Temp)	12.1	Table 103
2Ah	Hot-swap Backplane 2 Temperature (2U HSBP 2 Temp)	12.1	Table 103
2Bh	Hot-swap Backplane 3 Temperature (2U HSBP 3 Temp)	12.1	Table 103
2Ch	PCI Riser 1 Temperature (Riser 1 Temp)	5.2.1	Table 40
2Dh	PCI Riser 2 Temperature (Riser 2 Temp)	5.2.1	Table 40
2Eh	Exit Air Temperature (Exit Air Temp)	5.2.1	Table 40
2Fh	PCI Riser 3 Temperature (Riser 3 Temp)	5.2.1	Table 40
30h-3Fh	Fan Tachometer Sensors (Chassis specific sensor names)	5.1.1	Table 33
40h-45h	Fan Present Sensors (Fan x Present)	5.1.2	Table 35

## System Event Log (SEL) Troubleshooting Guide

Sensor #	Sensor Name	Details Section	Next Steps
4Ch	Processor 1 VR controller temp (P0 VR Ctrl Temp)	5.2.1	Table 40
4Dh	Processor 2 VR controller temp (P1 VR Ctrl Temp)	5.2.1	Table 40
50h	Power Supply 1 Status (PS1 Status)	4.5.1	Table 19
51h	Power Supply 2 Status (PS2 Status)	4.5.1	Table 19
54h	Power Supply 1 AC Power Input (PS1 Input Power)	4.5.2	Table 26
55h	Power Supply 2 AC Power Input (PS2 Input Power)	4.5.2	Table 26
58h	Power Supply 1 +12V % of Maximum Current Output (PS1 Curr Out %)	4.5.3	Table 28
59h	Power Supply 2 +12V % of Maximum Current Output (PS2 Curr Out %)	4.5.3	Table 28
5Ch	Power Supply 1 Temperature (PS1 Temperature)	4.5.4	Table 30
5Dh	Power Supply 2 Temperature (PS2 Temperature)	4.5.4	Table 30
5Eh	PCIe* Aggregate Thermal Margin (PCIe* Aggr Margin)	5.2.2	Table 43
60h–68h	Hard Disk Drive 15–23 Status (HDD 15–23 Status)	12.2	Table 105
69h	Midplane 1 Temp (Left Swch Temp)	5.2.1	Table 40
6Ah	Midplane 2 Temp (Right Swch Temp)	5.2.1	Table 40
6Bh	SAS Module Temperature (SAS Mod Temp)	5.2.1	Table 40
70h	Processor 1 Status (P1 Status)	6.1	Table 57
71h	Processor 2 Status (P2 Status)	6.1	Table 57
78h	Processor 1 Thermal Control % (P0 D1 Thm Ctrl %)	5.2.3	Section 5.2.3.1
7Ah	Processor 2 Thermal Control % (P1 D1 Thm Ctrl %)	5.2.3	Section 5.2.3.1
7Ch	Processor ERR2 Timeout (CPU ERR2)	6.5	Section 6.5.1
81h	MTM Level Change (MTM Lvl Change)	11.6	Not applicable
82h	Processor Population Fault (CPU Missing)	6.3	Section 6.3.1
83h	Processor 1 DTS Thermal Margin (P0 D1 DTS Th Mgn)	5.2.4	Not applicable
85h	Processor 1 DTS Temperature (P0 D1 Abs Temp)	5.2.1	Table 40
87h	Auto Config Status (AutoCfg Status)	11.10	Section 11.10.1
88h	Processor 2 DTS Thermal Margin (P1 D1 DTS Th Mgn)	5.2.4	Not applicable
8Ah	Processor 2 DTS Temperature (P1 D1 Abs Temp)	5.2.1	Table 40
90h	VRD Over Temperature (VRD Hot)	5.2.5	Section 5.2.6.3
91h	NVMe* 1 Therm Mgn	5.2.9.1	Section 5.2.9.1
92h	NVMe* 2 Therm Mgn	5.2.9.1	Section 5.2.9.1
93h	NVMe* 3 Therm Mgn	5.2.9.1	Section 5.2.9.1
94h	NVMe* 1 Crit Warn	5.2.9.2	Table 55
95h	NVMe* 2 Crit Warn	5.2.9.2	Table 55
96h	NVMe* 3 Crit Warn	5.2.9.2	Table 55
A0h	Power Supply 1 Fan Fail <sup>3</sup> (PS1 Fan Fail)	4.5.5	Section 4.5.5.1
A4h	Power Supply 2 Fan Fail <sup>3</sup> (PS2 Fan Fail)	4.5.5	Section 4.5.5.1
B0h	Processor 1 DIMM Aggregate Thermal Margin 1 (DIMM Thrm Mrgn 1)	5.2.2	Table 43
B1h	Processor 1 DIMM Aggregate Thermal Margin 2 (DIMM Thrm Mrgn 2)	5.2.2	Table 43
B2h	Processor 2 DIMM Aggregate Thermal Margin 3 (DIMM Thrm Mrgn 3)	5.2.2	Table 43
B3h	Processor 2 DIMM Aggregate Thermal Margin 4 (DIMM Thrm Mrgn 4)	5.2.2	Table 43
C0h	Processor 1 DIMM Thermal Trip (Mem P1 Thrm Trip)	5.2.8	Section 5.2.8.1
C1h	Processor 2 DIMM Thermal Trip (Mem P2 Thrm Trip)	5.2.8	Section 5.2.8.1
C8h	Global Aggregate Temperature Margin 1 (Agg Therm Mgn 1)	5.2.2	Table 43
C9h	Global Aggregate Temperature Margin 2 (Agg Therm Mgn 2)	5.2.2	Table 43
D0h	Baseboard +12V Right (BB +12.0V_R)	4.1	Table 14
D1h	Voltage Fault (Voltage Fault)	4.2	Table 16

## System Event Log (SEL) Troubleshooting Guide

Sensor #	Sensor Name	Details Section	Next Steps
D7h	Bad User Password Entered (Bad User PWD)	11.11	Section 11.11
DAh	KCS Policy	11.14	Section 11.14
DBh	Remote Debug	11.12	Section 11.12
DEh	Baseboard CMOS Battery (BB +3.3V Vbat)	4.1	Table 14
E0h	Hot-swap Backplane 4 Temperature (HSBP 4 Temp)	12.1	Table 103
E2h-E3h	Rear Hard Disk Drive 0 -1 Status (Rear HDD 0-1 Stat)	12.2	Table 105
F0h-FEh	Hard Disk Drive 0-14 Status (HDD 0-14 Status)	12.2	Table 105

1. Redundancy sensors will be only present on systems with appropriate hardware to support redundancy (for instance, fan or power supply). Note that power supply redundancy may be lost even when both supplies are operational if the system is loaded beyond the capacity of a single power supply.
2. This is only applicable when the system doesn't support redundant fans. When fan redundancy is supported, then the contribution to system state is driven by the fan redundancy sensor, not individual sensors. On a system with fan redundancy, the individual sensor severities will read the same as the fan redundancy sensor's severity.
3. This is only applicable when the system doesn't support redundant power supplies. When redundancy is supported, then the contribution to system state is driven by the power unit redundancy sensor. On a system with power supply redundancy, the individual sensor severities will read the same as the power unit redundancy sensor's severity.

**Table 6. D50TNP BMC**

Sensor #	Sensor Name	Details Section	Next Steps
01h	Power Unit Status (Pwr Unit Status)	4.4.1	Table 19
02h	Power Unit Redundancy (Pwr Unit Redund)	4.4.2	Table 21
03h	IPMI Watchdog (IPMI Watchdog)	11.1	Table 86
04h	Physical Security (Physical Scrtcy)	10.1	Table 82
05h	FP Interrupt (FP NMI Diag Int)	10.2	Section 10.2.1
06h	SMI Timeout (SMI Timeout)	11.2	Section 11.2.1
07h	System Event Log (System Event Log)	11.3	Not applicable
08h	System Event (System Event)	11.4	Section 11.4.1
09h	Button Sensor (Button)	10.3	Not applicable
0Ah	BMC Watchdog (BMC Watchdog)	11.5	Section 11.5.1
0Bh	Voltage Regulator Watchdog (VR Watchdog)	4.3	Section 4.3.1
0Dh	PCH Thermal Trip (PCH Therm Trip)	5.2.6.1	Section 5.2.6.3
10h	BMC Firmware Health (BMC FW Health)	11.7	Section 11.8.1
11h	System Airflow (System Airflow)	5.3	Not applicable
12h	Firmware Update Status (FW Update Status)	11.9	Not applicable
14h	Baseboard Temperature 5 (BB Outlet Temp)	5.2.1	Table 40
1Ah	Firmware Security(FW Security)	11.13	Not applicable
21h	Baseboard Temperature 2 (BB inlet Temp)	5.2.1	Table 40
22h	PCH Temperature (PCH Temp)	5.2.1	Table 40
24h	Baseboard Temperature3 (CPU0 VR Temp)	5.2.1	Table 40
25h	Network Interface Controller Temperature (LAN Temp)	5.2.1	Table 40
26h	Baseboard Temperature (CPU1 VR Temp)	5.2.1	Table 40
27h	PCI Riser 1 Temperature (Riser 1 Temp)	5.2.1	Table 40
28h	U.2 NVMe* Temperature (U.2 SSD Temp1)	5.2.1	Table 40
29h	M.2 NVMe* Temperature (M.2 Temp1)	5.2.1	Table 40
2Ah	PDB Temperature (PDB Temperature)	5.2.1	Table 40
2Ch	PCI Riser 2 Temperature (Riser 2 Temp)	5.2.1	Table 40
2Dh	U.2 NVMe* Temperature (U.2 SSD Temp2)	5.2.1	Table 40



System Event Log (SEL) Troubleshooting Guide

Sensor #	Sensor Name	Details Section	Next Steps
2Eh	Exit Air Temperature (Exit Air Temp)	5.2.1	Table 40
2Fh	Network Interface Controller Temperature (LAN NIC Temp)	5.2.1	Table 40
30h	Fan Tachometer Sensors <sup>2</sup> (Sys Fan 1A)	5.1.1	Table 33
30h	Fan Tachometer Sensors <sup>2</sup> (Sys Fan 4A)	5.1.1	Table 33
31h	Fan Tachometer Sensors <sup>2</sup> (Sys Fan 1B)	5.1.1	Table 33
31h	Fan Tachometer Sensors <sup>2</sup> (Sys Fan 4B)	5.1.1	Table 33
32h	Fan Tachometer Sensors <sup>2</sup> (Sys Fan 2A)	5.1.1	Table 33
32h	Fan Tachometer Sensors <sup>2</sup> (Sys Fan 5A)	5.1.1	Table 33
33h	Fan Tachometer Sensors <sup>2</sup> (Sys Fan 2B)	5.1.1	Table 33
33h	Fan Tachometer Sensors <sup>2</sup> (Sys Fan 5B)	5.1.1	Table 33
34h	Fan Tachometer Sensors <sup>2</sup> (Sys Fan 3A)	5.1.1	Table 33
34h	Fan Tachometer Sensors <sup>2</sup> (Sys Fan 6A)	5.1.1	Table 33
35h	Fan Tachometer Sensors <sup>2</sup> (Sys Fan 3B)	5.1.1	Table 33
35h	Fan Tachometer Sensors <sup>2</sup> (Sys Fan 6B)	5.1.1	Table 33
36h	Fan Tachometer Sensors <sup>2</sup> (Sys Fan 6)	5.1.1	Table 33
37h	Fan Tachometer Sensors <sup>2</sup> (Sys Fan 7)	5.1.1	Table 33
44h	EV CPU 1 VR Temperature (EV CPU1VR Temp)	5.2.1	Table 40
45h	Memory 0 VRD Temperature (Mem 0 VRD Temp)	5.2.1	Table 40
46h	Memory 1 VRD Temperature (Mem 1 VRD Temp)	5.2.1	Table 40
47h	M.2 NVMe* Temperature (M.2 Temp 2)	5.2.1	Table 40
50h	Power Supply 1 Status (PS1 Status)	4.5.1	Table 19
51h	Power Supply 2 Status (PS2 Status)	4.5.1	Table 19
54h	Power Supply 1 AC Power Input (PS1 Input Power)	4.5.2	Table 26
55h	Power Supply 2 AC Power Input (PS2 Input Power)	4.5.2	Table 26
58h	Power Supply 1 +12V % of Maximum Current Output (PS1 Curr Out %)	4.5.3	Table 28
59h	Power Supply 2 +12V % of Maximum Current Output (PS2 Curr Out %)	4.5.3	Table 28
5Ch	Power Supply 1 Temperature (PS1 Temperature)	4.5.4	Table 30
5Dh	Power Supply 2 Temperature (PS2 Temperature)	4.5.4	Table 30
60h	EDSFF Dock Temperature (Dock Temp)	5.2.1	Table 40
61h	Max RSSD temperature (RSSD Aggr Thrm 1)	5.2.1	Table 40
62h	Max RSSD temperature (RSSD Aggr Thrm 2)	5.2.1	Table 40
70h	Processor 1 Status (P1 Status)	6.1	Table 57
71h	Processor 2 Status (P2 Status)	6.1	Table 57
74h	Processor 1 Thermal Margin (P1 Therm Margin)	5.2.2	Table 43
75h	Processor 2 Thermal Margin (P2 Therm Margin)	5.2.2	Table 43
78h	Processor 1 Thermal Control % (P1 Therm Ctrl %)	5.2.3	Section 5.2.3.1
79h	Processor 2 Thermal Control % (P2 Therm Ctrl %)	5.2.3	Section 5.2.3.1
7Ch	Processor ERR2 Timeout (CPU ERR2)	6.5	Section 6.5.1
81h	MTM Level Change (MTM Lvl Change)	11.6	Not applicable
82h	Processor Population Fault (CPU Missing)	6.3	Section 6.3.1
83h-84h	Processor 1-2 DTS Thermal Margin (P1-P2 DTS Therm Mgn)	5.2.4	Not applicable
85h-86h	Processor 1-2 DTS Temperature (P1-P2 DTS Temperature)	5.2.1	Table 40
87h	Auto Config Status (AutoCfg Status)	11.10	Section 11.10.1
88h	GPGPU Riser Temperature (GPGPU Riser)	5.2.1	Table 40
90h	VRD Over Temperature (VRD Hot)	5.2.5	Section 5.2.6.3
91h	NVMe* 1 Therm Mgn	5.2.9.1	Section 5.2.9.1



## System Event Log (SEL) Troubleshooting Guide

Sensor #	Sensor Name	Details Section	Next Steps
93h	CPU0 VCCANA Temp	5.2.1	Table 40
94h	CPU1 VCCANA Temp	5.2.1	Table 40
A0h	Power Supply 1 Fan Fail <sup>3</sup> (PS1 Fan1 Fail)	4.5.5	Section 4.5.5.1
A1h	Power Supply 1 Fan 2 Fail <sup>3</sup> (PS1 Fan2 Fail)	4.5.5	Section 4.5.5.1
A4h	Power Supply 2 Fan Fail <sup>3</sup> (PS2 Fan1 Fail)	4.5.5	Section 4.5.5.1
A5h	Power Supply 2 Fan 2 Fail <sup>3</sup> (PS2 Fan2 Fail)	4.5.5	Section 4.5.5.1
B0h	Processor 1DIMM Aggregate Thermal Margin 1 (P1 DIMM Thrm 1)	5.2.2	Table 43
B1h	Processor 1 DIMM Aggregate Thermal Margin 2 (P1 DIMM Thrm 2)	5.2.2	Table 43
B2h	Processor 2 DIMM Aggregate Thermal Margin 1 (P2 DIMM Thrm 1)	5.2.2	Table 43
B3h	Processor 2 DIMM Aggregate Thermal Margin 2 (P2 DIMM Thrm 2)	5.2.2	Table 43
B8h	Node Auto-Shutdown Sensor (Auto Shutdown)	4.4.3	4.4.3.1
C0h	Processor 1 DIMM Thermal Trip (Mem P1 Thrm Trip)	5.2.8	Section 5.2.8.1
C1h	Processor 2 DIMM Thermal Trip (Mem P2 Thrm Trip)	5.2.8	Section 5.2.8.1
C8h	Global Aggregate Temperature Margin 1 (Agg Therm Mgn 1)	5.2.2	Table 43
C9h	Global Aggregate Temperature Margin 2 (Agg Therm Mgn 2)	5.2.2	Table 43
D0h	Baseboard +12V Right (BB +12.0V_R)	4.1	Table 14
D1h	Voltage Fault (Voltage Fault)	4.2	Table 16
D7h	Bad User Password Entered (Bad User PWD)	11.11	Section 11.11
DAh	KCS Policy	11.14	Section 11.14
DBh	Remote Debug	11.12	Section 11.12
DEh	Baseboard CMOS Battery (BB +3.3V Vbat)	4.1	Table 14
F0h–F5h	Hard Disk Drive 0–5 Status (HDD 0–5 Status)	12.2	Table 105

1. Redundancy sensors will be only present on systems with appropriate hardware to support redundancy (for instance, fan or power supply). Note that power supply redundancy may be lost even when both supplies are operational if the system is loaded beyond the capacity of a single power supply.
2. This is only applicable when the system doesn't support redundant fans. When fan redundancy is supported, then the contribution to system state is driven by the fan redundancy sensor, not individual sensors. On a system with fan redundancy, the individual sensor severities will read the same as the fan redundancy sensor's severity.
3. This is only applicable when the system doesn't support redundant power supplies. When redundancy is supported, then the contribution to system state is driven by the power unit redundancy sensor. On a system with power supply redundancy, the individual sensor severities will read the same as the power unit redundancy sensor's severity.

### 3.2 BIOS POST-Owned Sensors (GID = 0001h)

The following table can be used to find the details of sensors owned by BIOS POST.

**Table 7. BIOS POST Owned Sensors**

Sensor #	Sensor Name	Details Section	Next Steps
02h	Memory RAS Configuration Status/Memory ECC Error	7.1	Table 64
06h	BIOS POST Error	9.2	Section 9.2.1
09h	Intel® UPI Link Width Reduced	6.4.1	Section 6.4.1.1
12h	Memory RAS Mode Select	7.2	Not applicable
73h	OoB Firmware update/OoB BIOS Configuration		
83h	System Boot Event		

### 3.3 BIOS SMI Handler-Owned Sensors (GID = 0033h)

The following table can be used to find the details of sensors owned by BIOS System Management Interrupt (SMI) Handler.

**Table 8. BIOS SMI Handler Owned Sensors**

Sensor #	Sensor Name	Details Section	Next Steps
01h	Mirroring Redundancy State	7.3	Section 7.3.1
02h	Memory ECC Error	7.6.1	Table 71
03h	Legacy PCI Error	8.1	Section 8.1.1
04h	PCI Express* Fatal Error (Standard AER Errors) (see Sensor 14h for continuation)	8.2.1	Section 8.2.1.1
05h	PCI Express* Correctable Error (Standard AER Errors)	8.2.2	Section 8.2.2.1
06h	Intel UPI Correctable Error(reserved for validation)	6.4.2	Section 6.4.2.1
08h	IIO Internal Error		
10h	Memory Error Extension(reserved for validation)		
11h	Spring Redundancy State	7.4	7.4.1
12h	Memory RAS Mode select	7.2	Section 7.2
13h	Memory Parity Error	7.6.2	Section 7.6.2.1
14h	PCI Express* Fatal Error#2 (continuation of Sensor 04h)	8.2.1	Section 8.2.1.1
20h	ADDDC Error	7.5	Section 7.5

### 3.4 Intel® NM/Intel® ME Firmware-Owned Sensors (GID = 002Ch or 602Ch)

The following table can be used to find the details of sensors owned by the Intel® Node Manager (Intel® NM)/Intel® Management Engine (Intel® ME) firmware.

**Table 9. Intel® Management Engine Firmware-Owned Sensors**

Sensor #	Sensor Name	Details Section	Next Steps
17h	Intel® ME Firmware Health Events	13.1	Section 13.1.1
18h	Intel® Node Manager Exception Events	13.2	Section 13.2.1
19h	Intel® Node Manager Health Events	13.3	Section 13.3.1
1Ah	Intel® Node Manager Operational Capabilities Change Events	13.4	Section 13.4.1
1Bh	Intel® Node Manager Alert Threshold Exceeded Events	13.5	Section 13.5.1
B2h	Intel® Node Manager SmaRT/CLST Events	13.6	Section 13.6.1

### 3.5 Microsoft\* OS-Owned Events (GID = 0041h)

The following table can be used to find the details of records that are owned by the Microsoft\* Operating System (OS).

**Table 10. Microsoft\* OS-Owned Events**

Sensor Name	Record Type	Sensor Type	Details Section	Next Steps
Boot Event	02h	1Fh = OS Boot	Table 114	Not applicable
	DCh	Not applicable	Table 115	Not applicable
Shutdown Event	02h	20h = OS Stop/Shutdown	Table 116	Not applicable
	DDh	Not applicable	Table 117, Table 118	Not applicable
	02h	20h = OS Stop/Shutdown	Table 119	Not applicable

Sensor Name	Record Type	Sensor Type	Details Section	Next Steps
Bug Check/ Blue Screen	DEh	Not applicable	Table 120	Not applicable.

### 3.6 Linux\* Kernel Panic Events (GID = 0021h)

The following table can be used to find the details of records that can be generated when there is a Linux\* Kernel panic.

**Table 11. Linux\* Kernel Panic Events**

Sensor Name	Record Type	Sensor Type	Details Section	Next Steps
Linux* Kernel Panic	02h	20h = OS Stop/Shutdown	Table 121	Not applicable
	F0h	Not applicable	Table 122	Not applicable

## 4. Power Subsystems

The BMC monitors the power subsystem including power supplies, select onboard voltages, and related sensors.

### 4.1 Threshold-Based Voltage Sensors

The BMC monitors the main voltage sources in the system, including the baseboard, memory, and processors, using IPMI-compliant analog/threshold sensors. Some voltages are only on specific platforms. For details check the platform *Technical Product Specification (TPS)*.

**Note:** A voltage error can be caused by the device supplying the voltage or by the device using the voltage. For each sensor, it is noted who is supplying the voltage and who is using it.

**Table 12. Threshold-Based Voltage Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	02h = Voltage
12	Sensor Number	See Table 14
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 01h (Threshold)
14	Event Data 1	[7:6] – 01b = Trigger reading in Event Data 2 [5:4] – 01b = Trigger threshold in Event Data 3 [3:0] – Event Triggers as described in Table 13
15	Event Data 2	Reading that triggered event, FFh or not present if unspecified.
16	Event Data 3	Threshold value that triggered event, FFh or not present if unspecified. If present, byte 2 must be present.

The following table describes the severity of each of the event triggers for both assertion and deassertion.

**Table 13. Threshold-Based Voltage Sensors Event Triggers**

Event Trigger		Assertion Severity	Deassertion Severity	Description
00h	Lower non-critical going low	Degraded	OK	The voltage has dropped below its lower non-critical threshold.
02h	Lower critical going low	Non-fatal	Degraded	The voltage has dropped below its lower critical threshold.
07h	Upper non-critical going high	Degraded	OK	The voltage has gone over its upper non-critical threshold.
09h	Upper critical going high	Non-fatal	Degraded	The voltage has gone over its upper critical threshold.

**Table 14. Threshold-Based Voltage Sensors – Next Steps**

Sensor #	Sensor Name	Next Steps
0Bh	Voltage Regulator Watchdog (VR Watchdog)	
D0h	Baseboard +12V (BB +12.0V)	+12 V is supplied by the power supplies. +12 V is used by SATA drives, fans, and PCI-E cards. In addition, it is used to generate various processor voltages.  1. Ensure all cables are connected correctly. 2. Check connections on the fans and HDDs. 3. If the issue follows the component, swap it, otherwise, replace the board. 4. If the issue remains, replace the power supplies.
D1h	Voltage Fault (Voltage Fault)	The voltages in this sensor are all derived on the server board from the 12 V or 3.3 V power.  1. Remove all but minimum components for operation and check sensor. 2. Inspect for contamination in connectors (DIMMS, PCIe*). 3. If error remains, replace the board.
DEh	Baseboard CMOS Battery (BB +3.3V Vbat)	Vbat is supplied by the CMOS battery when AC power is off (Battery Voltage is 3.0 V) and by the main board when AC power is on (Battery Voltage is 3.3 V). Vbat is used by the CMOS and related circuits.  1. Replace the CMOS battery. Any battery of type CR2032 can be used. 2. If error remains (unlikely), replace the board.

## 4.2 Aggregate Voltage Fault Sensor

The discrete voltage sensor monitors multiple voltages from sensors around the baseboard and then asserts a bit in the SEL event data for each sensor that is out of range. The Voltage name for the asserted bit can be retrieved using the Get Voltage Name IPMI function. For details, check *BMC External Product Specification (EPS)*.

**Table 15. Aggregate Voltage Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	02h = Voltage
12	Sensor Number	D1h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 03h (Digital Discrete)
14	Event Data 1	[7:6] – 10b = OEM code in Byte2 [5:4] – 10b = unspecified byte 3 [3:0] – 01b = Offset from Event/Reading Code for discrete event state
15	Event Data 2	Voltage Fault Status [Bit 0] = Not Used [Bit 1] = +3.3V [Bit 2] = VNN PCH Aux [Bit 3] = +1.05V PCH Aux [Bit 4] = +0.83V LAN Aux [Bit 5] = 12V Aux [Bit 6] = +1.8V PCH Aux [Bit 7] = VCC In CPU0

System Event Log (SEL) Troubleshooting Guide

Byte	Field	Description
16	Event Data 3	Voltage Fault Status [Bit 0] = VCC In CPU1 [Bit 1] = VDDQ ABC CPU0 [Bit 2] = VDDQ DEF CPU0 [Bit 3] = VDDQ ABC CPU1 [Bit 4] = VDDQ DEF CPU1 [Bit 5] = VCCIO CPU0 [Bit 6] = VCCIO CPU1 [Bit 7] = Not Used
17	Extended Data 1	[7] - Reserved [6:4] - 110b = Extended SEL record length of 6 bytes [3:2] - Reserved [1:0] - Severity Status 10b = Severity Critical
18	Extended Data 2	Voltage Fault Status = Not Used
19	Extended Data 3	Voltage Fault Status = Not Used
20	Extended Data 4	Upper Non-Critical Voltage Fault Status [Bit 0] = Not Used [Bit 1] = +3.3V [Bit 2] = VNN PCH Aux [Bit 3] = +1.05V PCH Aux [Bit 4] = +0.83V LAN Aux [Bit 5] = 12V Aux [Bit 6] = +1.8V PCH Aux [Bit 7] = VCC In CPU0
21	Extended Data 5	Upper Non-Critical Voltage Fault Status [Bit 0] = VCC In CPU1 [Bit 1] = VDDQ ABC CPU0 [Bit 2] = VDDQ DEF CPU0 [Bit 3] = VDDQ ABC CPU1 [Bit 4] = VDDQ DEF CPU1 [Bit 5] = VCCIO CPU0 [Bit 6] = VCCIO CPU1 [Bit 7] = Not Used
22	Extended Data 6	Lower Non-Critical Voltage Fault Status [Bit 0] = Not Used [Bit 1] = +3.3V [Bit 2] = VNN PCH Aux [Bit 3] = +1.05V PCH Aux [Bit 4] = +0.83V LAN Aux [Bit 5] = 12V Aux [Bit 6] = +1.8V PCH Aux [Bit 7] = VCC In CPU0
23	Extended Data 7	Lower Non-Critical Voltage Fault Status [Bit 0] = VCC In CPU1 [Bit 1] = VDDQ ABC CPU0 [Bit 2] = VDDQ DEF CPU0 [Bit 3] = VDDQ ABC CPU1 [Bit 4] = VDDQ DEF CPU1 [Bit 5] = VCCIO CPU0 [Bit 6] = VCCIO CPU1 [Bit 7] = Not Used
24	Extended Data 8	Not used 0xFF

**Table 16. Discrete Voltage Sensors – Next Steps**

Voltage Name	Next Steps
<b>BB 1.8V P1 VCC</b>	<p>This 1.8 V line is supplied by the main board. This 1.8 V line is used by processor 1.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Check the processor is seated properly.</li> <li>3. Cross test the processors. If the issue remains with the processor socket, replace the main board, otherwise the processor.</li> </ol>
<b>BB 1.8V P2 VCC</b>	<p>This 1.8 V line is supplied by the main board. This 1.8 V line is used by processor 2.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Check the processor is seated properly.</li> <li>3. Cross test the processors. If the issue remains with the processor socket, replace the main board, otherwise the processor.</li> </ol>
<b>BB 1.2V P1DDR AB</b>	<p>This 1.2 V line is supplied by the main board. This 1.2 V line is used by processor 1 memory slots A and B.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Check the DIMMs are seated properly.</li> <li>3. Cross test the DIMMs. If the issue remains with the DIMMs on this socket, replace the main board, otherwise the DIMM.</li> </ol>
<b>BB 1.2V P1DDR CD</b>	<p>This 1.2 V line is supplied by the main board. This 1.2 V line is used by processor 1 memory slots C and D.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Check the DIMMs are seated properly.</li> <li>3. Cross test the DIMMs. If the issue remains with the DIMMs on this socket, replace the main board, otherwise the DIMM.</li> </ol>
<b>BB 1.2V P2DDR EF</b>	<p>This 1.2 V line is supplied by the main board. This 1.2 V line is used by processor 2 memory slots E and F.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Check the DIMMs are seated properly.</li> <li>3. Cross test the DIMMs. If the issue remains with the DIMMs on this socket, replace the main board, otherwise the DIMM.</li> </ol>
<b>BB 1.2V P2DDR GH</b>	<p>This 1.2 V line is supplied by the main board. This 1.2 V line is used by processor 2 memory slots G and H.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Check the DIMMs are seated properly.</li> <li>3. Cross test the DIMMs. If the issue remains with the DIMMs on this socket, replace the main board, otherwise the DIMM.</li> </ol>
<b>BB 2.62V VPP</b>	<p>This 2.62 V line is supplied by the main board. This 2.62 V line is used by memory.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Check the DIMMs are seated properly.</li> <li>3. Cross test the DIMMs. If the issue remains with the DIMMs on special socket, replace the main board, otherwise the DIMM.</li> </ol>
<b>BB 1.05V VCC IO</b>	<p>This 1.05 V line is supplied by the main board. This 1.05 V line is used by processor and PECL.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Check the processors are seated properly.</li> <li>3. Cross test the processors. If the issue remains with the processor on special socket, replace the main board, otherwise the Processor.</li> </ol>

## System Event Log (SEL) Troubleshooting Guide

Voltage Name	Next Steps
<b>BB 1.5V PCH</b>	<p>This 1.5 V line is supplied by the main board. This 1.5 V line is used by PCH.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. If the issue remains, replace the board.</li> </ol>
<b>BB 1.05V PCH</b>	<p>This 1.05 V line is supplied by the main board. This 1.05 V line is used by PCH.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. If the issue remains, replace the board.</li> </ol>
<b>BB 1.05V ASW PCH</b>	<p>This 1.05 V line is supplied by the main board. This 1.05 V line is used by PCH.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. If the issue remains, replace the board.</li> </ol>
<b>BB 0.9V IB CORE</b>	<p>+0.9 V Core IB is supplied by the main board on specific platforms. +0.9 V Core IB is used by the on-board Infiniband* controller on those specific platforms.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. If the issue remains, replace the board.</li> <li>3. If the issue remains, replace the power supplies.</li> </ol>
<b>BB 1.0V AUX LAN</b>	<p>+1.0 V AUX LAN is supplied by the main board. +1.0 V AUX LAN is used by on-board NIC Intel® X540.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. If the issue remains, replace the board.</li> <li>3. If the issue remains, replace the power supplies.</li> </ol>
<b>BB 5V AUX</b>	<p>This 5 V line is supplied by the HSBP (Platform Specific). This 5 V line is used optionally and depends on customer's design.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. If the issue remains, replace the board.</li> </ol>
<b>BB 3.3V AUX</b>	<p>+3.3 V AUX is supplied by the main board. +3.3 V AUX is used by the BMC, clock chips, PCI-E Slot, on-board NIC, PCH.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. If the issue remains, replace the board.</li> <li>3. If the issue remains, replace the power supplies.</li> </ol>
<b>BB 1.0V AUX</b>	<p>+1.0 V AUX is supplied by the main board. +1.0 V AUX is used by the BMC, on-board NIC.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. If the issue remains, replace the board.</li> <li>3. If the issue remains, replace the power supplies.</li> </ol>
<b>BB 12V AUX</b>	<p>+12 V AUX is supplied by the Power Supply. +12 V AUX is used by the BMC, clock chips, PCIe* Slot, on-board NIC, PCH.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. If the issue remains, replace the board.</li> <li>3. If the issue remains, replace the power supplies.</li> </ol>
<b>BB 3.3V</b>	<p>+3.3 V is supplied by the power supplies for pedestal systems, and supplied by the main board on rack-optimized systems. +3.3 V is used by the PCIe* and PCI-X slots.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Reseat any PCI-E cards.</li> <li>3. Try PCI-E cards in other PCI-E slots.</li> <li>4. If the issue follows the card, swap it; otherwise, replace the main board.</li> <li>5. If the issue remains, replace the power supplies.</li> </ol>



## System Event Log (SEL) Troubleshooting Guide

Voltage Name	Next Steps
<b>VNN PCH Aux</b>	<p>This VNN PCH Aux line is supplied by the main board. This VNN PCH Aux line is used by PCH.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. If the issue remains, replace the board.</li> </ol>
<b>BB 1.05V PCH Aux</b>	<p>This 1.05V Aux line is supplied by the main board. This 1.05V Aux line is used by PCH.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. If the issue remains, replace the board.</li> </ol>
<b>BB 0.83V LAN Aux</b>	<p>0.83V LAN AUX is supplied by the main board. 0.83V LAN AUX is used by on-board NIC controller</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. If the issue remains, replace the board.</li> <li>3. If the issue remains, replace the power supplies.</li> </ol>
<b>BB 1.8V PCH Aux</b>	<p>This 1.8V Aux line is supplied by the main board. This 1.8V Aux line is used by PCH.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. If the issue remains, replace the board.</li> </ol>
<b>VCC In CPU0</b>	<p>This 1.8 V line is supplied by the main board. This 1.8 V line is used by processor 1.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Check the processor is seated properly.</li> <li>3. Cross test the processors. If the issue remains with the processor socket, replace the main board, otherwise the processor.</li> </ol>
<b>VCC In CPU1</b>	<p>This 1.8 V line is supplied by the main board. This 1.8 V line is used by processor 2.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Check the processor is seated properly.</li> <li>3. Cross test the processors. If the issue remains with the processor socket, replace the main board, otherwise the processor.</li> </ol>
<b>VDDQ ABC CPU0</b>	<p>This 1.2 V line is supplied by the main board. This 1.2 V line is used by processor 1 memory slots A/B/C.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Check the DIMMs are seated properly.</li> <li>3. Cross test the DIMMs. If the issue remains with the DIMMs on this socket, replace the main board, otherwise the DIMM.</li> </ol>
<b>VDDQ DEF CPU0</b>	<p>This 1.2 V line is supplied by the main board. This 1.2 V line is used by processor 1 memory slots D/E/F.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Check the DIMMs are seated properly.</li> <li>3. Cross test the DIMMs. If the issue remains with the DIMMs on this socket, replace the main board, otherwise the DIMM.</li> </ol>
<b>VDDQ ABC CPU1</b>	<p>This 1.2 V line is supplied by the main board. This 1.2 V line is used by processor 2 memory slots A/B/C.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Check the DIMMs are seated properly.</li> <li>3. Cross test the DIMMs. If the issue remains with the DIMMs on this socket, replace the main board, otherwise the DIMM.</li> </ol>
<b>VDDQ DEF CPU1</b>	<p>This 1.2 V line is supplied by the main board. This 1.2 V line is used by processor 2 memory slots D/E/F.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Check the DIMMs are seated properly.</li> <li>3. Cross test the DIMMs. If the issue remains with the DIMMs on this socket, replace the main board, otherwise the DIMM.</li> </ol>

Voltage Name	Next Steps
VCCIO CPU0	<p>This 1.0 V line is supplied by the main board. This 1.0 V line is used by processor and PECL.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Check the processors are seated properly.</li> <li>3. Cross test the processors. If the issue remains with the processor on special socket, replace the main board, otherwise the Processor.</li> </ol>
VCCIO CPU1	<p>This 1.0 V line is supplied by the main board. This 1.0 V line is used by processor and PECL.</p> <ol style="list-style-type: none"> <li>1. Ensure all cables are connected correctly.</li> <li>2. Check the processors are seated properly.</li> <li>3. Cross test the processors. If the issue remains with the processor on special socket, replace the main board, otherwise the Processor.</li> </ol>

### 4.3 Voltage Regulator Watchdog Timer Sensor

The BMC firmware monitors that the power sequence for the board voltage regulator (VR) controllers is completed when a DC power-on is initiated. Incompletion of the sequence indicates a board problem, in which case the firmware powers down the system.

The sequence is as follows:

- BMC firmware monitors the `PowerSupplyPowerGood` signal for assertion, indicating a DC-power-on has been initiated, and starts a timer (VR Watchdog Timer). For Intel Server Systems supporting the Intel® Xeon® Scalable processor family, this timeout is one second.
- If the `SystemPowerGood` signal has not asserted by the time the VR Watchdog Timer expires, then the firmware powers down the system, logs a SEL entry, and emits a beep code (1-5-1-2). This failure is termed as VR Watchdog Timeout.

**Table 17. Voltage Regulator Watchdog Timer Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	02h = Voltage
12	Sensor Number	0Bh
13	Event Direction and Event Type	<p>[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 03h ("digital" Discrete)</p>
14	Event Data 1	<p>[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset = 1h = State Asserted</p>
15	Event Data 2	Not used
16	Event Data 3	Not used

#### 4.3.1 Voltage Regulator Watchdog Timer Sensor – Next Steps

1. Ensure that all the connectors from the power supply are well seated.
2. Cross test the baseboard. If the issue remains with the baseboard, replace the baseboard.

## 4.4 Power Unit

The power unit monitors the power state of the system and logs the state changes in the SEL.

### 4.4.1 Power Unit Status Sensor

The power unit status sensor monitors the power state of the system and logs state changes. Expected power-on events, such as DC ON/OFF, are logged and unexpected events, such as AC loss and power good loss, are also logged.

**Table 18. Power Unit Status Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	09h = Power Unit
12	Sensor Number	01h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] = Sensor Specific offset as described in Table 19
15	Event Data 2	Not used
16	Event Data 3	Not used

**Table 19. Power Unit Status Sensor – Sensor Specific Offsets – Next Steps**

Sensor Specific Offset		Description	Next Steps
00h	Power down	System is powered down.	Informational event
02h	240 VA power down	240 VA power limit was exceeded and the hardware forced a power down.	This could be caused by many things. <ol style="list-style-type: none"> <li>1. If hardware was recently added, try removing it.</li> <li>2. Remove/replace any add-in adapters.</li> <li>3. Remove/replace the power supply.</li> <li>4. Remove/replace the processors, DIMM, and/or hard drives.</li> <li>5. Remove/replace the boards in the system.</li> </ol>
04h	AC Lost	AC power was removed.	Informational event
05h	Soft Power Control Failure	Asserted if the system fails to power on due to the following power control sources: <ul style="list-style-type: none"> <li>• Chassis Control command</li> <li>• PEF action</li> <li>• BMC Watchdog Timer</li> <li>• Power State Retention</li> </ul>	This could be caused by the power supply subsystem or system components. <ol style="list-style-type: none"> <li>1. Verify all power cables and adapters are connected properly (AC cables as well as the cables between the power supply unit (PSU) and system components).</li> <li>2. Cross test the PSU if possible.</li> <li>3. Replace the power subsystem.</li> </ol>

## System Event Log (SEL) Troubleshooting Guide

Sensor Specific Offset		Description	Next Steps
06h	Power Unit Failure	<p>Power subsystem experienced a failure. Asserted for one of the following conditions:</p> <ul style="list-style-type: none"> <li>• Unexpected de-assertion of system POWER_GOOD signal.</li> <li>• System fails to respond to any power control source's attempt to power down the system.</li> <li>• System fails to respond to any hardware power control source's attempt to power on the system.</li> <li>• Power Distribution Board (PDB) failure is detected (applies only to systems that have a PDB).</li> </ul>	<p>Indicates a power supply failed.</p> <ol style="list-style-type: none"> <li>1. Remove and reapply AC power.</li> <li>2. Verify all power cables and adapters are connected properly (AC cables as well as the cables between the PSU and system components).</li> <li>3. Cross test the PSU if possible.</li> <li>4. If the power supply still fails, replace it.</li> <li>5. If the problems still exist, replace the baseboard.</li> </ol>

### 4.4.2 Power Unit Redundancy Sensor

This sensor is enabled on the systems that support redundant power supplies. When a system has AC applied or if it loses redundancy of the power supplies, a message is logged into the SEL.

**Table 20. Power Unit Redundancy Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	09h = Power Unit
12	Sensor Number	02h
13	Event Direction and Event Type	<p>[7] Event direction                      0b = Assertion Event                      1b = Deassertion Event                      [6:0] Event Type = 0Bh (Generic Discrete)</p>
14	Event Data 1	<p>[7:6] – 00b = Unspecified Event Data 2                      [5:4] – 00b = Unspecified Event Data 3                      [3:0] – Event Trigger Offset as described in Table 21</p>
15	Event Data 2	Not used
16	Event Data 3	Not used

**Table 21. Power Unit Redundancy Sensor – Event Trigger Offset – Next Steps**

Event Trigger Offset		Description	Next Steps
00h	Fully redundant	System is fully operational.	Informational Event
01h	Redundancy lost	System is not running in redundant power supply mode.	This event is accompanied by specific power supply errors (AC lost, PSU failure, and so on). Troubleshoot these events accordingly.
02h	Redundancy degraded		
03h	Non-redundant, sufficient from redundant		
04h	Non-redundant, sufficient from insufficient		
05h	Non-redundant, insufficient		
06h	Non-redundant, degraded from fully redundant		
07h	Redundant, degraded from non-redundant		

### 4.4.3 Node Auto Shutdown Sensor

The BMC supports a Node Auto Shutdown sensor for logging an SEL event due to an emergency shutdown of a node due to loss of power supply redundancy or PSU CLST throttling due to an over-current warning condition. This sensor is applicable only to multi-node systems.

The sensor is rearmed on power-on (AC or DC power-on transitions).

This sensor is only used for triggering SEL to indicate node or power auto shutdown assertion or deassertion.

**Table 22. Node Auto Shutdown Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	09h = Power Unit
12	Sensor Number	B8h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 03h ("digital" discrete)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset 1h = State Asserted
15	Event Data 2	Not used
16	Event Data 3	Not used

#### 4.4.3.1 Node Auto Shutdown Sensor – Next Steps

This event is accompanied by specific power supply errors (AC lost, PSU failure, and so on) or other system events. Troubleshoot these events accordingly.

## 4.5 Power Supply

The BMC monitors the power supply subsystem.

### 4.5.1 Power Supply Status Sensors

These sensors report the status of the power supplies in the system. When a system first has AC applied or removed, it can log an event. Also if there is a failure, predictive failure, or a configuration error, it can log an event.

**Table 23. Power Supply Status Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	08h = Power Supply
12	Sensor Number	50h = Power Supply 1 Status 51h = Power Supply 2 Status
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – ED2 data in Table 24 [5:4] – ED3 data in Table 24 [3:0] – Sensor Specific offset as described in Table 24
15	Event Data 2	As described in Table 24
16	Event Data 3	As described in Table 24

**Table 24. Power Supply Status Sensor – Sensor Specific Offsets – Next Steps**

Sensor Specific Offset		Description	ED2	ED3	Next Steps
00h	Presence	Power supply detected.	00b = Unspecified Event Data 2	00b = Unspecified Event Data 3	Informational Event
01h	Failure	Power supply failed. Check the data in ED2 and ED3 for more details.	10b = OEM code in Event Data 2 <ul style="list-style-type: none"> <li>• 01h – Output voltage fault</li> <li>• 02h – Output power fault</li> <li>• 03h – Output over-current fault</li> <li>• 04h – Over-temperature fault</li> <li>• 05h – Fan fault</li> </ul>	10b = OEM code in Event Data 3 Has the contents of the associated PMBus* Status register. For example, Data 3 will have the contents of the VOLTAGE_STATUS register at the time an Output Voltage fault was detected. Refer to the PMBus* Specification for details on specific register contents.	Indicates a power supply failed. <ol style="list-style-type: none"> <li>1. Remove and reapply AC.</li> <li>2. If the power supply still fails, replace it.</li> </ol>
02h	Predictive Failure	Check the data in ED2 and ED3 for more details.	10b = OEM code in Event Data 2 <ul style="list-style-type: none"> <li>• 01h – Output voltage warning</li> <li>• 02h – Output power warning</li> <li>• 03h – Output over-current warning</li> <li>• 04h – Over-temperature warning</li> <li>• 05h – Fan warning</li> <li>• 06h – Input under-voltage warning</li> <li>• 07h – Input over-current warning</li> <li>• 08h – Input over-power warning</li> </ul>	10b = OEM code in Event Data 3 Has the contents of the associated PMBus* Status register. For example, Data 3 will have the contents of the VOLTAGE_STATUS register at the time an Output Voltage warning was detected. Refer to the PMBus* Specification for details on specific register contents.	Depends on the warning event. <ol style="list-style-type: none"> <li>1. Replace the power supply.</li> <li>2. Verify proper airflow to the system.</li> <li>3. Verify the power source.</li> <li>4. Replace the system boards.</li> </ol>
03h	AC lost	AC removed.	00b = Unspecified Event Data 2	00b = Unspecified Event Data 3	Informational Event.
06h	Configuration error	Power supply configuration is not supported. Check the data in ED2 for more details.	10b = OEM code in Event Data 2 <ul style="list-style-type: none"> <li>• 01h – The BMC cannot access the PMBus* device on the PSU but its FRU device is responding.</li> <li>• 02h – The PMBUS*_REVISION command returns a version number that is not supported (only version 1.1 and 1.2 are supported).</li> <li>• 03h – The PMBus* device does not successfully respond to the PMBUS*_REVISION command.</li> <li>• 04h – The PSU is incompatible with one or more PSUs that are present in the system.</li> <li>• 05h – The PSU FW is operating in a degraded mode (likely due to a failed firmware update).</li> </ul>	00b = Unspecified Event Data 3	Indicates that at least one of the supplies is not correct for your system configuration. <ol style="list-style-type: none"> <li>1. Remove the power supply and verify compatibility.</li> <li>2. If the power supply is compatible, it may be faulty. Replace it.</li> </ol>

## 4.5.2 Power Supply Power in Sensors

These sensors log an event when a power supply in the system is exceeding its AC power in threshold.

**Table 25. Power Supply Power In Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	0Bh = Other Units
12	Sensor Number	54h = Power Supply 1 Status 55h = Power Supply 2 Status
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 01h (Threshold)
14	Event Data 1	[7:6] – 01b = Trigger reading in Event Data 2 [5:4] – 01b = Trigger threshold in Event Data 3 [3:0] – Event Trigger Offset as described in Table 26
15	Event Data 2	Reading that triggered event
16	Event Data 3	Threshold value that triggered event

The following table describes the severity of each of the event triggers for both assertion and deassertion.

**Table 26. Power Supply Power In Sensor – Event Trigger Offset – Next Steps**

Event Trigger Offset		Assertion Severity	Deassertion Severity	Description	Next Steps
07h	Upper non-critical going high	Degraded	OK	PMBus* feature to monitor power supply power consumption.	If you see this event, the system is pulling too much power on the input for the PSU rating. <ul style="list-style-type: none"> <li>Verify the power budget is within the specified range.</li> <li>Check <a href="http://www.intel.com/p/en_US/support/">http://www.intel.com/p/en_US/support/</a> for the power budget tool for your system.</li> </ul>
09h	Upper critical going high	Non-fatal	Degraded		

## 4.5.3 Power Supply Current Out % Sensors

PMBus\*-compliant power supplies may monitor the current output of the main 12 V voltage rail and report the current usage as a percentage of the maximum power output for that rail.

**Table 27. Power Supply Current Out % Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	03h = Current
12	Sensor Number	58h = Power Supply 1 Current Out % 59h = Power Supply 2 Current Out %
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 01h (Threshold)
14	Event Data 1	[7:6] – 01b = Trigger reading in Event Data 2 [5:4] – 01b = Trigger threshold in Event Data 3 [3:0] – Event Trigger Offset as described in Table 28
15	Event Data 2	Reading that triggered event
16	Event Data 3	Threshold value that triggered event

The following table describes the severity of each of the event triggers for both assertion and deassertion.

**Table 28: Power Supply Current Out % Sensor – Event Trigger Offset – Next Steps**

Event Trigger Offset		Assertion Severity	Deassertion Severity	Description	Next Steps
07h	Upper non-critical going high	Degraded	OK	PMBus* feature to monitor power supply power consumption.	If you see this event, the system is using too much power on the output for the PSU rating. <ol style="list-style-type: none"> <li>Verify the power budget is within the specified range.</li> <li>Check <a href="http://www.intel.com/p/en_US/support/">http://www.intel.com/p/en_US/support/</a> for the power budget tool for your system.</li> </ol>
09h	Upper critical going high	Non-fatal	Degraded		

#### 4.5.4 Power Supply Temperature Sensors

The BMC monitors one or two power supply temperature sensors for each installed PMBus\*-compliant power supply.

**Table 29. Power Supply Temperature Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	01h = Temperature
12	Sensor Number	5Ch = Power Supply 1 Temperature 5Dh = Power Supply 2 Temperature
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 01h (Threshold)
14	Event Data 1	[7:6] – 01b = Trigger reading in Event Data 2 [5:4] – 01b = Trigger threshold in Event Data 3 [3:0] – Event Trigger Offset as described in Table 30
15	Event Data 2	Reading that triggered event
16	Event Data 3	Threshold value that triggered event

The following table describes the severity of each of the event triggers for both assertion and deassertion.

**Table 30. Power Supply Temperature Sensor – Event Trigger Offset – Next Steps**

Event Trigger Offset		Assertion Severity	Deassertion Severity	Description	Next Steps
07h	Upper non-critical going high	Degraded	OK	An upper non-critical or critical temperature threshold has been crossed.	Check for clear and unobstructed airflow into and out of the chassis. <ol style="list-style-type: none"> <li>Ensure the SDR is programmed and correct chassis has been selected.</li> <li>Ensure there are no fan failures.</li> <li>Ensure the air used to cool the system is within the thermal specifications for the system (typically below 35°C).</li> </ol>
09h	Upper critical going high	Non-fatal	Degraded		



### 4.5.5 Power Supply Fan Tachometer Sensors

The BMC polls each installed power supply using the PMBus\* fan status commands to check for failure conditions for the power supply fans.

**Table 31. Power Supply Fan Tachometer Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	04h = Fan
12	Sensor Number	A0h = Power Supply 1 Fan Fail <sup>3</sup> (PS1 Fan1 Fail) A1h = Power Supply 1 Fan 2 Fail <sup>3</sup> (PS1 Fan2 Fail) A4h = Power Supply 2 Fan Fail <sup>3</sup> (PS2 Fan1 Fail) A5h = Power Supply 2 Fan 2 Fail <sup>3</sup> (PS2 Fan2 Fail)
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 03h ("digital" Discrete)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset = 1h = State Asserted
15	Event Data 2	Not used
16	Event Data 3	Not used

#### 4.5.5.1 Power Supply Fan Tachometer Sensors – Next Steps

These events only get generated in systems with PMBus\*-capable power supplies and, normally, when the airflow is obstructed to the power supply:

1. Remove and then reinstall the power supply to see whether something might have temporarily caused the fan failure.
2. Swap the power supply with another one to see whether the problem stays with the location or follows the power supply.
3. Replace the power supply depending on the outcome of steps 1 and 2.
4. Ensure the latest FRUSDR update has been run and the correct chassis is detected or selected.

## 5. Cooling Subsystem

### 5.1 Fan Sensors

There are three types of fan sensors that can be present on Intel® Server Systems: speed, presence, and redundancy. The last two are only present in systems with hot-swap redundant fans.

#### 5.1.1 Fan Tachometer Sensors

Fan tachometer sensors monitor the rpm signal on the relevant fan headers on the platform. Fan speed sensors are threshold-based sensors. Usually, they only have lower (critical) thresholds set, so that an SEL entry is only generated if the fan spins too slowly.

**Table 32. Fan Tachometer Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	04h = Fan
12	Sensor Number	30h-3Fh (Chassis specific)
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 01h (Threshold)
14	Event Data 1	[7:6] – 01b = Trigger reading in Event Data 2 [5:4] – 01b = Trigger threshold in Event Data 3 [3:0] – Event Trigger Offset as described in Table 33
15	Event Data 2	Reading that triggered event
16	Event Data 3	Threshold value that triggered event

The following table describes the severity of each of the event triggers for both assertion and deassertion.

**Table 33. Fan Tachometer Sensor – Event Trigger Offset – Next Steps**

Event Trigger Offset		Assertion Severity	Deassertion Severity	Description	Next Steps
00h	Lower non-critical going low	Degraded	OK	The fan speed has dropped below its lower non-critical threshold.	A fan speed error on a new system build is typically not caused by the fan spinning too slowly; instead it is caused by the fan being connected to the wrong header (the BMC expects them on certain headers for each chassis and logs this event if there is no fan on that header).  <ol style="list-style-type: none"> <li>1. Refer to the Quick Start Guide or the Service Guide to identify the correct fan headers to use.</li> <li>2. Ensure the latest FRUSDR update has been run and the correct chassis is detected or selected.</li> <li>3. If this was done already, the event may be a sign of impending fan failure (although this only normally applies if the system has been in use for a while). Replace the fan.</li> </ol>
02h	Lower critical going low	non-fatal	Degraded	The fan speed has dropped below its lower critical threshold.	

## 5.1.2 Fan Presence and Redundancy Sensors

Fan presence sensors are only implemented for hot-swap fans, and require an additional pin on the fan header. Fan redundancy is an aggregate of the fan presence sensors and warn when redundancy is lost. Typically, the redundancy mode on Intel Server Systems is an n+1 redundancy. Meaning, if one fan fails, there are still sufficient fans to cool the system, but it is no longer redundant. Although, other modes are also possible.

**Table 34. Fan Presence Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	04h = Fan
12	Sensor Number	40h-45h (Chassis specific)
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 08h (Generic "digital" Discrete)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset as described in Table 35
15	Event Data 2	Not used
16	Event Data 3	Not used

The following table describes the severity of each of the event triggers for both assertion and deassertion.

**Table 35. Fan Presence Sensors – Event Trigger Offset – Next Steps**

Event Trigger Offset		Assertion Severity	Deassertion Severity	Description	Next Steps
01h	Device Present	OK	Degraded	Assertion – A fan was inserted. This event may also get logged when the BMC initializes when AC is applied.	Informational only.
				Deassertion – A fan was removed, or was not present at the expected location when the BMC initialized.	These events only get generated in the systems with hot-swappable fans, and normally only when a fan is physically inserted or removed. If fans were not physically removed: <ol style="list-style-type: none"> <li>1. Use the Quick Start Guide to check whether the right fan headers were used.</li> <li>2. Swap the fans round to see whether the problem stays with the location or follows the fan.</li> <li>3. Replace the fan or fan wiring/housing depending on the outcome of step 2.</li> <li>4. Ensure the latest FRUSDR update has been run and the correct chassis is detected or selected.</li> </ol>

**Table 36. Fan Redundancy Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	04h = Fan
12	Sensor Number	0Ch
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 0Bh (Generic Discrete)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset as described in Table 37
15	Event Data 2	Not used
16	Event Data 3	Not used

The following table describes the severity of each of the event triggers for both assertion and deassertion.

**Table 37. Fan Redundancy Sensor – Event Trigger Offset – Next Steps**

Event Trigger Offset		Description	Next Steps
00h	Fully redundant	The system has lost one or more fans and is running in non-redundant mode. There are enough fans to keep the system properly cooled, but fan speeds will boost.	Fan redundancy loss indicates failure of one or more fans. Look for lower (non-) critical fan errors, or fan removal errors in the SEL, to indicate which fan is causing the problem, and follow the troubleshooting steps for these event types.
01h	Redundancy lost		
02h	Redundancy degraded		
03h	Non-redundant, sufficient from redundant		
04h	Non-redundant, sufficient from insufficient		
05h	Non-redundant, insufficient	The system has lost fans and may no longer be able to cool itself adequately. Overheating may occur if this situation remains for a longer period of time.	
06h	Non-redundant, degraded from fully redundant	The system has lost one or more fans and is running in non-redundant mode. There are enough fans to keep the system properly cooled, but fan speeds will boost.	
07h	Redundant, degraded from non-redundant	The system has lost one or more fans and is running in a degraded mode, but still is redundant. There are enough fans to keep the system properly cooled.	

## 5.2 Temperature Sensors

There are a variety of temperature sensors that can be implemented on Intel® Server Systems. They are split into various types each with their own events that can be logged.

- Threshold-based Temperature
- Thermal Margin
- Processor Thermal Control %
- Processor DTS Thermal Margin (Monitor only)
- Discrete Thermal
- DIMM Thermal Trip

### 5.2.1 Threshold-based Temperature Sensors

Threshold-based temperature sensors are sensors that report an actual temperature. These are linear, threshold-based sensors. In most Intel Server Systems, multiple sensors are defined: front panel temperature and baseboard temperature. There are also multiple other sensors that can be defined and are platform-specific. Most of these sensors typically have upper and lower thresholds set – upper to warn in case of an over-temperature situation and lower to warn against sensor failure (temperature sensors typically read out 0 if they stop working).

**Table 38. Temperature Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	01h = Temperature
12	Sensor Number	See Table 40
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 01h (Threshold)
14	Event Data 1	[7:6] – 01b = Trigger reading in Event Data 2 [5:4] – 01b = Trigger threshold in Event Data 3 [3:0] – Event Trigger Offset as described in Table 39
15	Event Data 2	Reading that triggered event
16	Event Data 3	Threshold value that triggered event

**Table 39. Temperature Sensors Event Triggers**

Event Trigger		Assertion Severity	Deassertion Severity	Description
00h	Lower non-critical going low	Degraded	OK	The temperature has dropped below its lower non-critical threshold.
02h	Lower critical going low	Non-fatal	Degraded	The temperature has dropped below its lower critical threshold.
07h	Upper non-critical going high	Degraded	OK	The temperature has gone over its upper non-critical threshold.
09h	Upper critical going high	Non-fatal	Degraded	The temperature has gone over its upper critical threshold.

**Table 40. Temperature Sensors – Next Steps**

Sensor #	Sensor Name	Next Steps
21h (M50CYP)	Front Panel Temp	<p>If the front panel temperature reads zero, check:</p> <ul style="list-style-type: none"> <li>• It is connected properly.</li> <li>• The SDR has been programmed correctly for your chassis.</li> </ul> <p>If the front panel temperature is too high:</p> <ul style="list-style-type: none"> <li>• Check the cooling of your server room.</li> </ul>
14h (M50CYP)	Baseboard Temperature 5 (BB Lft Rear Temp)	<p>Check for clear and unobstructed airflow into and out of the chassis.</p> <ul style="list-style-type: none"> <li>• Ensure the SDR is programmed and correct chassis has been selected.</li> <li>• Ensure there are no fan failures.</li> <li>• Ensure the air used to cool the system is within the thermal specifications for the system (typically below 35°C).</li> </ul>
14h (D50TNP)	Baseboard Temperature 5 (BB Outlet Temp)	
20h (M50CYP)	Baseboard Temperature 1 (BB P0 VR Temp)	
21h (D50TNP)	Baseboard Temperature 2 (BB inlet Temp)	
22h	PCH Temperature(PCH Temp)	
23h (M50CYP)	Baseboard Temperature 2 (BB P1 VR Temp))	
24h (M50CYP)	Baseboard Temperature 3 (BB BMC Temp)	
24h (D50TNP)	Baseboard Temperature3 (CPU0 VR Temp)	
25h (M50CYP)	Baseboard Temperature 4 (BB M.2 Temp)	
25h (D50TNP)	Network Interface Controller Temperature (LAN Temp)	
26h (M50CYP)	OCF Module Temperature (OCF Mod Temp)	
26h (D50TNP)	Baseboard Temperature (CPU1 VR Temp)	
27h (D50TNP)	PCI Riser 1 Temperature (Riser 1 Temp)	
28h (D50TNP)	U.2 NVMe* Temperature (U.2 SSD Temp1)	
29h (D50TNP)	M.2 NVMe* Temperature (M.2 Temp1)	
2Ah (D50TNP)	PDB Temperature (PDB Temperature)	
2Ch (M50CYP)	PCI Riser 1 Temperature (Riser 1 Temp)	
2Ch (D50TNP)	PCI Riser 2 Temperature (Riser 2 Temp)	
2Dh (M50CYP)	PCI Riser 2 Temperature (Riser 2 Temp)	
2Dh (D50TNP)	U.2 NVMe* Temperature (U.2 SSD Temp2)	
2Eh	Exit Air Temperature (Exit Air Temp)	

System Event Log (SEL) Troubleshooting Guide

Sensor #	Sensor Name	Next Steps
2Fh (M50CYP)	PCI Riser 3 Temperature (Riser 3 Temp)	
2Fh (D50TNP)	Network Interface Controller Temperature (LAN NIC Temp)	
44h (D50TNP)	EV CPU 1 VR Temperature (EV CPU1VR Temp)	
45h (D50TNP)	Memory 0 VRD Temperature (Mem 0 VR Temp)	
46h (D50TNP)	Memory 1 VRD Temperature (Mem 1 VRD Temp)	
47h (D50TNP)	M.2 NVMe* Temperature (M.2 Temp 2)	
4Ch (M50CYP)	Processor 1 VR controller temp (P0 VR Ctrl Temp)	
4Dh (M50CYP)	Processor 2 VR controller temp (P1 VR Ctrl Temp)	
60h (D50TNP)	EDSFF Dock Temperature (Dock Temp)	
61h (D50TNP)	Max RSSD temperature (RSSD Aggr Thrm 1)	
62h (D50TNP)	Max RSSD temperature (RSSD Aggr Thrm 2)	
69h (M50CYP)	Midplane 1 Temp (Left Swch Temp)	
6Ah (M50CYP)	Midplane 2 Temp (Right Swch Temp)	
6Bh (M50CYP)	SAS Module Temperature (SAS Mod Temp)	
85h (M50CYP)	Processor 1 DTS Temperature (P0 D1 Abs Temp)	
85h (D50TNP)	Processor 1 DTS Temperature (P1 Temperature)	
86h (D50TNP)	Processor 2 DTS Temperature (P2 Temperature)	
88h (D50TNP)	GPGPU Riser Temperature (GPGPU Riser)	
8Ah (M50CYP)	Processor 2 DTS Temperature (P1 D1 Abs Temp)	
93h (D50TNP)	CPU0 VCCANA Temp	
94h (D50TNP)	CPU1 VCCANA Temp	

## 5.2.2 Thermal Margin Sensors

Margin sensors are also linear sensors but typically report a negative value. This is not an actual temperature, but in fact an offset to a critical temperature. Values reported are seen as number of degrees below a critical temperature for the particular component.

The BMC supports DIMM aggregate temperature margin IPMI sensors. The temperature readings from the physical temperature sensors on each DIMM, such as temperature sensor on DIMM (TSOD), are aggregated into IPMI temperature margin sensors for groupings of DIMM slots, the partitioning of which is platform/SKU specific and generally corresponding to fan domains.

The BMC supports global aggregate temperature margin IPMI sensors. There may be as many unique global aggregate sensors as there are fan domains. Each sensor aggregates the readings of multiple other IPMI temperature sensors supported by the BMC firmware. The mapping of child-sensors into each global aggregate sensor is SDR-configurable. The primary usage for these sensors is to trigger turning off fans when a lower threshold is reached.

**Table 41. Thermal Margin Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	01h = Temperature
12	Sensor Number	See Table 43
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 01h (Threshold)
14	Event Data 1	[7:6] – 01b = Trigger reading in Event Data 2 [5:4] – 01b = Trigger threshold in Event Data 3 [3:0] – Event Triggers as described in Table 42
15	Event Data 2	Reading that triggered event
16	Event Data 3	Threshold value that triggered event

**Table 42. Thermal Margin Sensors Event Triggers**

Event Trigger		Assertion Severity	Deassertion Severity	Description
07h	Upper non-critical going high	Degraded	OK	The thermal margin has gone over its upper non-critical threshold.
09h	Upper critical going high	non-fatal	Degraded	The thermal margin has gone over its upper critical threshold.

**Table 43. Thermal Margin Sensors – Next Steps**

Sensor #	Sensor Name	Next Steps
74h	P1 Therm Margin	Not a logged SEL event. Sensor is used for thermal management of the processor.
75h	P2 Therm Margin	
76h	P3 Therm Margin	
77h	P4 Therm Margin	
5Eh	PCIe* Aggregate Thermal Margin (PCIe* Aggr Margin)	<ol style="list-style-type: none"> <li>1. Check for clear and unobstructed airflow into and out of the chassis.</li> <li>2. Ensure the SDR is programmed and correct chassis has been selected.</li> <li>3. Ensure there are no fan failures.</li> </ol>
B0h	P1 DIMM Thrm Mrgn1	



Sensor #	Sensor Name	Next Steps
B1h	P1 DIMM Thrm Mrgn2	Ensure the air used to cool the system is within the thermal specifications for the system (typically below 35°C).
B2h	P2 DIMM Thrm Mrgn1	
B3h	P2 DIMM Thrm Mrgn2	
C8h	Global Aggregate Temperature Margin 1 (Agg Therm Mgn 1)	
C9h	Global Aggregate Temperature Margin 2 (Agg Therm Mgn 2)	

### 5.2.3 Processor Thermal Control Sensors

The BMC firmware monitors the percentage of time that a processor has been operationally constrained over a given time window (nominally six seconds) due to internal thermal management algorithms engaging to reduce the temperature of the device. This monitoring is instantiated as one IPMI analog/threshold sensor per processor package.

If this is not addressed, the processor will overheat and shut down the system to protect itself from damage.

**Table 44. Processor Thermal Control Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	01h = Temperature
12	Sensor Number	78h = Processor 1 Thermal Control % (P1 Therm Ctrl %) 79h = Processor 2 Thermal Control % (P2 Therm Ctrl %)
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 01h (Threshold)
14	Event Data 1	[7:6] – 01b = Trigger reading in Event Data 2 [5:4] – 01b = Trigger threshold in Event Data 3 [3:0] – Event Triggers as described in Table 45
15	Event Data 2	Reading that triggered event
16	Event Data 3	Threshold value that triggered event

**Table 45. Processor Thermal Control Sensors Event Triggers**

Event Trigger		Assertion Severity	Deassertion Severity	Description
07h	Upper non-critical going high	Degraded	OK	The thermal margin has gone over its upper non-critical threshold.
09h	Upper critical going high	Non-fatal	Degraded	The thermal margin has gone over its upper critical threshold.

#### 5.2.3.1 Processor Thermal Control % Sensors – Next Steps

These events normally occur due to failures of the thermal solution:

1. Verify heat sink is properly attached and has thermal grease.
2. If the system has a heat sink fan, ensure the fan is spinning.
3. Check all system fans are operating properly.
4. Check that the air used to cool the system is within limits (typically 35 °C).

## 5.2.4 Processor DTS Thermal Margin Sensors

The Intel® Xeon® Scalable processor family incorporates a DTS-based thermal specification conformance capability. This capability allows a much more accurate control of the thermal solution and will enable lower fan speeds and lower fan power consumption. The BMC accesses the margin reading via PECL commands to the processor.

The main usage of this sensor is as an input to the BMC's fan control algorithms. Thresholds are not set and alert generation is not enabled for these sensors.

**Table 46. Processor DTS Thermal Margin Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	01h = Temperature
12	Sensor Number	M50TNP: 83h = Processor 1 DTS Thermal Margin 88h = Processor 2 DTS Thermal Margin D50TNP: 83h = Processor 1 DTS Thermal Margin 84h = Processor 2 DTS Thermal Margin
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 01h (Threshold)
14	Event Data 1	[7:6] – 01b = Trigger reading in Event Data 2 [5:4] – 01b = Trigger threshold in Event Data 3 [3:0] – Event Triggers as described in Table 13
15	Event Data 2	Reading that triggered event, FFh or not present if unspecified.
16	Event Data 3	Threshold value that triggered event, FFh or not present if unspecified. If present, byte 2 must be present.

## 5.2.5 Aggregate VRD-Hot Sensor

The BMC monitors processor and memory VRD\_HOT\_N signals. The VRD\_HOT\_N signals are routed to the associated processor PROCHOT\_N or MEMHOT#\_N input in order to initiate throttling to reduce the power draw, thereby indirectly lowering the VRD temperature.

There is one processor and two memory VRD\_HOT# signals per CPU slot. The BMC manifests one discrete IPMI sensor that aggregates the status of all of the VRD\_HOT\_N signals in the system. The associated SEL record includes an OEM bit-map indicating the state of each VRD\_HOT\_N signal when the record was logged. The sensor will only go into a de-asserted state when all signals have de-asserted.

**Table 47. VRD-Hot Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	01h = Temperature
12	Sensor Number	90h = VRD-Hot
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 05h (Digital Discrete)
14	Event Data 1	[7:6] - 10b = OEM code in Byte 2 [5:4] - 10b = OEM code in Byte 3 [3:0] - Offset from Event/Reading code
15	Event Data 2	[7:0] - CPU VRHOT Map [Bit 0] = CPU 0 [Bit 1] = CPU 1

Byte	Field	Description
16	Event Data 3	[7:0] - Memory VRHOT Map [Bit 0] = CPU 0 Memory A/B/C [Bit 1] = CPU 0 Memory D/E/F [Bit 2] = CPU 1 Memory A/B/C [Bit 3] = CPU 1 Memory D/E/F

## 5.2.6 Discrete Thermal Sensors

Discrete thermal sensors do not report a temperature at all; instead they report an overheating event of some kind. For example, VRD Hot (voltage regulator is overheating) or processor Thermal Trip (the processor got so hot that its over-temperature protection was triggered and the system was shut down to prevent damage).

### 5.2.6.1 PCH Thermal Trip Sensor

**Table 48. PCH Thermal Trip Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	19h = Chip Set
12	Sensor Number	0Dh = PCH Thermal Trip
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] - 00b = Unspecified Event Data 2 [5:4] - 00b = Unspecified Event Data 3 [3:0] - Event Trigger Offset = 01h (State Asserted, South Side Bridge (SSB) overheated)
15	Event Data 2	Not used
16	Event Data 3	Not used

### 5.2.6.2 VRD HOT Sensor

**Table 49. VRD HOT Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	01h = Temperature
12	Sensor Number	90h = SSB Thermal Trip
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 05h (Digital Discrete)
14	Event Data 1	[7:6] - 10b = OEM code in Event Data 2 [5:4] - 10b = OEM code in Event Data 3 [3:0] - Event Trigger Offset = 01h (Limit Exceeded)
15	Event Data 2	Processor VRD HOT bitmap [7:4] - Reserved [3] - CPU4 [2] - CPU3 [1] - CPU2 [0] - CPU1
16	Event Data 3	Memory VRD HOT bitmap [7] - CPU4, DIMM Channel3/4 [6] - CPU4, DIMM Channel1/2

Byte	Field	Description
		[5] – CPU3, DIMM Channel3/4 [4] – CPU3, DIMM Channel1/2 [3] – CPU2, DIMM Channel3/4 [2] – CPU2, DIMM Channel1/2 [1] – CPU1, DIMM Channel3/4 [0] – CPU1, DIMM Channel1/2

### 5.2.6.3 Discrete Thermal Sensors – Next Steps

1. Check for clear and unobstructed airflow into and out of the chassis.
2. Ensure the SDR is programmed and correct chassis has been selected.
3. Ensure there are no fan failures.
4. Ensure the air used for cooling the system is within the thermal specifications for the system (typically below 35 °C).

### 5.2.7 Liquid Cooling

The liquid cooling solution falls into two categories: the Liquid Assisted Air Cooling (LAAC) and Liquid Cooling Rack(LCR). The LAAC consists of components such as a cold plate, pump, Heat Exchanger (HEX), liquid tube, coolant etc. The LCR consists of components such as a cold plate, pump, liquid tubes, coolant, rack CDU, even facility cooling devices, etc.

For the BMC to support liquid cooling, it must provide the following functionalities:

- Pump tachometer sensor
- System shutdown when pump reading crosses critical high or critical low

For Intel® Server Systems supporting the Intel® Xeon® processor Scalable family to support a liquid cooling feature, a special FRU is needed.

#### 5.2.7.1 Pump Tachometer Sensors

The pump tachometer sensor reading is proportional to the pump speed. This monitoring capability is instantiated in the form of IPMI analog/threshold sensors. Sensor reading is available only during DC-on.

The pump sensor is a manual re-arm sensor. Once the sensor status crosses critical high or critical low, the sensor status can't auto-recover because it may be damaged. The BMC will shut the system down in this situation and the user should check and replace the sensor if it is damaged. The BMC will re-initialize the sensor at the next system power-on after the problem has been handled.

#### 5.2.7.2 IPMI Sensor Characteristics

- Event reading type code: 01h (Threshold)
- Sensor type code: 0Ah (Cooling Device)
- Re-arm type: Manual
- Configured thresholds: Lower/Upper critical/non-critical
- Event generation: Assertion/de-assertion events for all supported thresholds

**Table 50. Threshold-Based Voltage Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	0Ah = Cooling Device
12	Sensor Number	3Ch–3Dh= Pump Tachometer Sensors
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event

Byte	Field	Description
		1b = Deassertion Event [6:0] Event Type = 01h (Threshold)
14	Event Data 1	[7:6] – 01b = Trigger reading in Event Data 2 [5:4] – 01b = Trigger threshold in Event Data 3 [3:0] – Event Triggers as described in Table 13
15	Event Data 2	Reading that triggered event, FFh or not present if unspecified.
16	Event Data 3	Threshold value that triggered event, FFh or not present if unspecified. If present, byte 2 must be present.

The following table describes the severity of each of the event triggers for both assertion and deassertion.

**Table 51. Threshold-Based Voltage Sensors Event Triggers**

Event Trigger		Assertion Severity	Deassertion Severity	Description
00h	Lower non-critical going low	Degraded	OK	The voltage has dropped below its lower non-critical threshold.
02h	Lower critical going low	Non-fatal	Degraded	The voltage has dropped below its lower critical threshold.
07h	Upper non-critical going high	Degraded	OK	The voltage has gone over its upper non-critical threshold.
09h	Upper critical going high	Non-fatal	Degraded	The voltage has gone over its upper critical threshold.

### 5.2.8 DIMM Thermal Trip Sensors

The BMC supports DIMM Thermal Trip monitoring that is instantiated as one aggregate IPMI discrete sensor per processor. When a DIMM Thermal Trip occurs, the system hardware automatically powers down the server and the BMC asserts the sensor offset and logs an event.

**Table 52. DIMM Thermal Trip Typical Characteristics**

Byte	Field	Description
11	Sensor Type	0Ch = Memory
12	Sensor Number	C0h = Processor 1 DIMM Thermal Trip C1h = Processor 2 DIMM Thermal Trip
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset = 0A = Critical over temperature
15	Event Data 2	Not used
16	Event Data 3	[7:5] – Socket ID 0–3 = CPU1-4 [4:3] – Channel 0–3 = Channel A, B, C, D for CPU1 Channel E, F, G, H for CPU2 Channel J, K, L, M for CPU3 Channel N, P, R, T for CPU4 [2:0] – DIMM 0–2 = DIMM 1–3 on Channel

### 5.2.8.1 DIMM Thermal Trip Sensors – Next Steps

1. Check for clear and unobstructed airflow into and out of the chassis.
2. Ensure the SDR is programmed and correct chassis has been selected.
3. Ensure there are no fan failures.
4. Ensure the air used to cool the system is within the thermal specifications for the system (typically below 35 °C).

### 5.2.9 NVMe\* Thermal Status

The BMC supports NVMe\* temperature and critical warning monitoring that is instantiated as one aggregate IPMI discrete sensor per HSBP. Each backplane provides a single temperature sensor. The aggregate sensor reports the temperature of the hottest drive inserted into the HSBP. The BMC uses the NVMe\* drive's SMBus\* Management Interface (I<sup>2</sup>C address 0xD4 byte 3) to retrieve temperature data. Because discrete temperature sensors were deprecated early in the NVMe\* drive life-cycle, drive temperature is never acquired from a discrete sensor on the drive. The BMC, as a result, can only rely on temperature data acquired via the Management Interface.

#### 5.2.9.1 NVMe\* Temperature Sensor

The NVMe\* temperature SEL occurs when the aggregate temperature sensor reading reaches the upper critical threshold. In order to report which of several drives are over temp, OEM Extended data bytes are used. The remainder of the SEL uses standard temperature sensor decoding rules. The NVMe\* Temperature SEL uses a new format for the OEM Extended data bytes.

**Table 53. NVMe\* Temperature Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	01h = Temperature
12	Sensor Number	91h = NVMe 1 Therm Mgn 92h = NVMe 2 Therm Mgn 93h = NVMe 3 Therm Mgn
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 01h (Threshold)
14	Event Data 1	[7:6] – 10b = Trigger reading in Event Data 2 [5:4] – 10b = Trigger threshold in Event Data 3 [3:0] – 0001b = OEM Event Trigger in Table 39
15	Event Data 2	Reading that triggered event
16	Event Data 3	Threshold value that triggered event
17	Extended Data 1	[7] = Extended format indicator [6:4] = # Extended Data byte [3:2] = reserved [1:0] = Existing severity encoding
18	Extended Data 2	0 = Reserved 1 = Drive Position Format 2 = Critical Warning Format 3 = Add in card format 4-0xff = Reserved
19	Extended Data 3	For Format = 1 (Drive Position Format), ExtData[2] is a bitfield indicating which drives are over temperature. Bit 0 set indicates Drive 0 is over temp. Bit 7 set indicates Drive 7 is over temp.
20	Extended Data 4	If Extended Data 1 indicate this byte is included, same format with above byte.
21	Extended Data 5	If Extended Data 1 indicate this byte is included, same format with above byte.
22	Extended Data 6	If Extended Data 1 indicate this byte is included, same format with above byte.

Byte	Field	Description
23	Extended Data 7	If Extended Data 1 indicate this byte is included, same format with above byte.
24	Extended Data 8	If Extended Data 1 indicate this byte is included, same format with above byte.

### 5.2.9.2 NVMe\* Critical Warning Sensor

The critical warning sensor aggregates a set of SMART drive warning flags. For the first warning bit asserted for a drive, a corresponding critical warning SEL is generated.

**Table 54. NVMe\* Critical Warning Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	0Dh=Disk drive
12	Sensor Number	94h = NVMe* 1 Crit Warn 95h = NVMe* 2 Crit Warn 96h = NVMe* 3 Crit Warn
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 73h (OEM Discrete)
14	Event Data 1	0x8x (low nibble is the drive causing the event, zero based count)
15	Event Data 2	SMART warning byte defined in Table 55 for the drive number indicated by the low nibble of ED1.
16	Event Data 3	Not used

**Table 55. SMART Warning Bits**

Bit	Assertion value	Message
0	1	Spare space below threshold
1	1	Temperature above or below threshold
2	1	NVM reliability degraded
3	1	In read-only mode
4	1	Volatile backup service failed
5-7	X	Reserved

## 5.3 System Airflow Monitoring Sensor

The BMC provides an IPMI sensor to report the volumetric system airflow in cubic feet per minute (CFM). The airflow in CFM is calculated based on the system fan pulse width modulation (PWM) values. The specific PWM used to determine the CFM is SDR-configurable. The relationship between PWM and CFM is based on a lookup table in an OEM SDR.

The airflow data is used in the calculation for exit air temperature monitoring. It is exposed as an IPMI sensor to allow a data center management application to access this data for use in rack-level thermal management.

This sensor is informational only and does not log events into the SEL.

## 6. Processor Subsystem

Intel® Server Systems report multiple processor-centric sensors in the SEL.

### 6.1 Processor Status Sensor

The BMC provides an IPMI sensor of type processor for monitoring status information for each processor slot. If an event state (sensor offset) has been asserted, it remains asserted until one of the following happens:

- A rearm Sensor Events command is executed for the processor status sensor.
- AC or DC power cycle, system reset, or system boot occurs.

CPU Presence status is not saved across AC power cycles and therefore does not generate a deassertion after cycling AC power.

**Table 56. Process Status Sensors Typical Characteristics**

Byte	Field	Description
11	Sensor Type	07h = Processor
12	Sensor Number	70h = Processor 1 Status 71h = Processor 2 Status
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] 10b = OEM code in Byte 2 [5:4] 00b = Unspecified Byte 3 [3:0] – Event Trigger Offset as described in Table 57
15	Event Data 2	IERR Type [7:5] – Reserved [4:0] – Type 00000b = Unspecified 00001b = CPU/VR mismatch 00010b = Non-boot core FIVR fault 00011b = Non-boot uncore FIVR fault Other values reserved Processor ThermTrip cause [7:2] – Reserved [1:0] – Type 00b = Processor non-recoverable ThermTrip temperature reached. 01b = boot FIVR fault Other values reserved Configuration Error FFh
16	Event Data 3	FFh



**Table 57. Processor Status Sensors – Next Steps**

Event Trigger Offset	Processor Status	Next Steps
0h	Internal error (IERR)	<ol style="list-style-type: none"> <li>1. Cross test the processors.</li> <li>2. Replace the processors depending on the results of the test.</li> </ol>
1h	Thermal trip/FIVR	<p>This event normally only happens due to failures of the thermal solution:</p> <ol style="list-style-type: none"> <li>1. Verify heat sink is properly attached and has thermal grease.</li> <li>2. If the system has a heat sink fan, ensure the fan is spinning.</li> <li>3. Check all system fans are operating properly.</li> <li>4. Check that the air used to cool the system is within limits (typically 35 °C).</li> </ol>
5h	Configuration error	<ol style="list-style-type: none"> <li>1. Cross test the processors.</li> <li>2. Replace the processors depending on the results of the test.</li> </ol>
7h	Processor presence detected	Informational Event

## 6.2 Internal Error Sensor

When the Catastrophic Error signal (CATERR#) stays asserted, it is a sign that something serious has gone wrong in the hardware. The BMC monitors this signal and reports when it stays asserted.

**Table 58. Internal Error Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	07h = Processor
12	Sensor Number	80h
13	Event Direction and Event Type	<p>[7] Event direction  0b = Assertion Event  1b = Deassertion Event  [6:0] Event Type = 03h (Digital Discrete)</p>
14	Event Data 1	<p>[7:6] – 10b = OEM code in Event Data 2  [5:4] – 10b = OEM code in Event Data 3  [3:0] – Event Trigger Offset = 1h (State Asserted)</p>
15	Event Data 2	Event Data 2 values as described in Table 59.
16	Event Data 3	<p>Bitmap of the CPU that causes the system CATERR.  [0]: CPU1  [1]: CPU2</p> <hr/> <p><b>Note:</b> If more than one bit is set, the BMC cannot determine the source of the CATERR.</p>

**Table 59. Internal Error Sensor – Event Data 2 Values – Next Steps**

ED2	Description	Next Steps
00h	Unknown	<ol style="list-style-type: none"> <li>1. Cross test the processors.</li> <li>2. Replace the processors depending on the results of the test.</li> </ol>
01h	CATERR	<p>This error is typically caused by other platform components.</p> <ol style="list-style-type: none"> <li>1. Check for other errors near the time of the CATERR event.</li> <li>2. Verify all peripherals are plugged in and operating correctly, particularly hard drives, optical drives, and I/O.</li> <li>3. Update system firmware and drivers.</li> </ol>
2h	CPU Core Error	<ol style="list-style-type: none"> <li>1. Cross test the processors.</li> <li>2. Replace the processors depending on the results of the test.</li> </ol>
3h	MSID Mismatch	Verify the processor is supported by the baseboard. Check the board <i>Technical Product Specification (TPS)</i> .

## 6.3 CPU Missing Sensor

The CPU Missing sensor is a discrete sensor that only reports if the processor is not installed. The most common instance of this event is due to a processor populated in an incorrect socket.

**Table 60. CPU Missing Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	07h = Processor
12	Sensor Number	82h
13	Event Direction and Event Type	<p>[7] Event direction  0b = Assertion Event  1b = Deassertion Event  [6:0] Event Type = 03h (Digital Discrete)</p>
14	Event Data 1	<p>[7:6] – 00b = Unspecified Event Data 2  [5:4] – 00b = Unspecified Event Data 3  [3:0] – Event Trigger Offset = 1h (State Asserted)</p>
15	Event Data 2	Not used
16	Event Data 3	Not used

### 6.3.1 CPU Missing Sensor – Next Steps

The following steps are used to correct the fault condition and clear the sensor state:

1. AC power down the server.
2. Install the missing processor into the correct slot.
3. AC power on the server.

## 6.4 Intel® UPI Interconnect Sensors

The Intel UPI Link Width Reduced sensor is used by the BIOS POST to report when the link width has been reduced. Therefore, the Generator ID is 01h.

The Intel UPI Error sensors are reported by the BIOS SMI Handler to the BMC, so the Generator ID is 33h.

### 6.4.1 Intel® UPI Link Width Reduced Sensor

BIOS POST has reduced the Intel® UPI Link Width because of an error condition seen during initialization.

**Table 61. Intel® UPI Link Width Reduced Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0001h = BIOS POST
11	Sensor Type	13h = Critical Interrupt
12	Sensor Number	09h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 77h (OEM Discrete)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset 1h = Reduced to ½ width 2h = Reduced to ¼ width
15	Event Data 2	0–3 = CPU0-3
16	Event Data 3	Not used

#### 6.4.1.1 Intel® UPI Link Width Reduced Sensor – Next Steps

If the error continues:

1. Check if the processor is installed correctly.
2. Inspect the socket for bent pins.
3. Cross test the processor. If the issue remains with the processor socket, replace the main board; otherwise replace the processor.

### 6.4.2 Intel® UPI Correctable Error Sensor

The system detected an error and corrected it. This is an informational event.

**Table 62. Intel UPI® Correctable Error Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0033h = BIOS SMI Handler
11	Sensor Type	13h = Critical Interrupt
12	Sensor Number	06h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 72h (OEM Discrete)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset = Reserved
15	Event Data 2	0–3 = CPU1-4
16	Event Data 3	Not used

### 6.4.2.1 Intel® UPI Correctable Error Sensor – Next Steps

This is an Informational event only. Correctable errors are acceptable and normal at a low rate of occurrence. If the error continues:

1. Check if the processor is installed correctly.
2. Inspect the socket for bent pins.
3. Cross test the processor. If the issue remains with the processor socket, replace the main board, otherwise the processor.

## 6.5 Processor ERR2 Timeout Sensor

The BMC supports an ERR2 Timeout Sensor that asserts if any CPU's ERR2 signal has been asserted for longer than a fixed time period (> 90 seconds). ERR[2] is a processor signal that indicates when the IIO (Integrated IO module in the processor) has a fatal error which could not be communicated to the core to trigger SMI. ERR[2] events are fatal error conditions, where the BIOS and OS will attempt to gracefully handle error, but may not always do so reliably. A continuously asserted ERR2 signal is an indication that the BIOS cannot service the condition that caused the error. This is usually because that condition prevents the BIOS from running.

When an ERR2 timeout occurs, the BMC asserts/deasserts the ERR2 Timeout Sensor, and logs a SEL event for that sensor. The default behavior for BMC core firmware is to initiate a system reset upon detection of an ERR2 timeout. The BIOS setup utility provides an option to disable or enable system reset by the BMC on detection of this condition.

**Table 63. Processor ERR2 Timeout Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	07h = Processor
12	Sensor Number	7Ch = Processor ERR2 Timeout
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 03h ("digital" discrete)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset = 1h (State Asserted)
15	Event Data 2	[7:4] – Not used [3:0] – Bitmap of the CPU that causes the ERR2 timeout. [0]: CPU1 [1]: CPU2
16	Event Data 3	Not used

### 6.5.1 Processor ERR2 Timeout – Next Steps

Check the SEL for any other events around the time of the failure.

Take note of all IPMI activity that was occurring around the time of the failure. Capture a System BMC Debug Log as soon as possible after experiencing this failure. This log can be captured from the Integrated BMC Web Console or by using the Syscfg utility (`syscfg/sbmcd1 Public filename.zip`). Send the log file to the system manufacturer or Intel representative for failure analysis.

## 7. Memory Subsystem

Intel servers report memory errors, status, and configuration in the SEL.

### 7.1 Memory RAS Configuration Status

A Memory RAS Configuration Status event is logged after an AC power-on occurs, only if any RAS Mode is currently configured, and only if RAS Mode is successfully initiated.

This is to make sure that there is a record in the SEL telling what the RAS Mode was at the time that the system started up. This is only logged after AC power-on, not DC power-on.

The Memory RAS Configuration Status Sensor is also used to log an event during POST whenever there is a RAS configuration error. This is a case where a RAS Mode has been selected but when the system boots, the memory configuration cannot support the RAS Mode. The memory configuration fails, and operates in Independent Channel Mode.

In the SEL record logged, the ED1 Offset value is “RAS Configuration Disabled”, and ED3 contains the RAS Mode that is currently selected but could not be configured. ED2 gives the reason for the RAS configuration failure – at present, only two “RAS Configuration Error Type” values are implemented:

0 = None – This is used for an AC power-on log record when the RAS configuration is successfully configured.

3 = Invalid DIMM Configuration for RAS Mode – The installed DIMM configuration cannot support the currently selected RAS Mode. This may be due to DIMMs that have failed or been disabled, so when this reason has been logged, the user should check the preceding SEL events to see whether there are DIMM error events.

**Table 64. Memory RAS Configuration Status Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0001h = BIOS POST
11	Sensor Type	0Ch = Memory
12	Sensor Number	02h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 09h (digital Discrete)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset as described in Table 65
15	Event Data 2	RAS Configuration Error Type [7:4] = Reserved [3:0] = Configuration Error 0 = None 3 = Invalid DIMM Configuration for RAS Mode All other values are reserved.
16	Event Data 3	RAS Mode Configured [7:4] = Reserved [3:0] = RAS Mode 0h = None (Independent Channel Mode) 1h = Mirroring Mode 4h = Rank Sparing Mode

**Table 65. Memory RAS Configuration Status Sensor – Event Trigger Offset – Next Steps**

Event Trigger Offset		Description	Next Steps
01h	RAS configuration enabled.	User enabled mirrored channel mode in setup.	Informational event only.
00h	RAS configuration disabled.	Mirrored channel mode is disabled (either in setup or due to unavailability of memory at post, in which case post error 8500 is also logged).	<ul style="list-style-type: none"> <li>If this event is accompanied by a post error 8500, there was a problem applying the mirroring configuration to the memory. Check for other errors related to the memory and troubleshoot accordingly.</li> <li>If there is no post error, mirror mode was simply disabled in BIOS setup and this should be considered informational only.</li> </ul>

## 7.2 Memory RAS Mode Select

Memory RAS Mode Select events are logged to record changes in RAS Mode.

When a RAS Mode selection is made that changes the RAS Mode (including selecting a RAS Mode from or to Independent Channel Mode), that change is logged to SEL in a Memory RAS Mode Select event message, which records the previous RAS Mode (from) and the newly selected RAS Mode (to). The event also includes an Offset value in ED1, which indicates whether the mode change left the system with a RAS Mode active (Enabled), or not (Disabled – Independent Channel Mode selected). This sensor provides the Spare Channel mode RAS Configuration status. Memory RAS Mode Select is an informational event.

**Table 66. Memory RAS Mode Select Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0001h = BIOS POST
11	Sensor Type	0Ch = Memory
12	Sensor Number	12h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 09h (digital Discrete)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset 0h = RAS Configuration Disabled 1h = RAS Configuration Enabled
15	Event Data 2	Prior RAS Mode [7:4] = Reserved [3:0] = RAS Mode 0h = None (Independent Channel Mode) 1h = Mirroring Mode 4h = Rank Sparing Mode
16	Event Data 3	Selected RAS Mode [7:4] = Reserved [3:0] = RAS Mode 0h = None (Independent Channel Mode) 1h = Mirroring Mode 4h = Rank Sparing Mode

## 7.3 Mirroring Redundancy State

Mirroring Mode protects memory data by full redundancy – keeping complete copies of all data on both channels of a Mirroring Domain (channel pair). If an Uncorrectable Error, which is normally fatal, occurs on one channel of a pair, and the other channel is still intact and operational, then the Uncorrectable Error is “demoted” to a Correctable Error, and the failed channel is disabled. Because the Mirror Domain is no longer redundant, a Mirroring Redundancy State SEL Event is logged.

For different platforms, there are some differences in the event definition. For the following product families, refer to Table 67.

**Table 67. Mirroring Redundancy State Sensor Typical Characteristics For Intel® Server Boards Based On Intel® Server Board Based On The 3rd Gen Intel® Scalable Processor Family**

Byte	Field	Description
8, 9	Generator ID	0033h = BIOS SMI Handler
11	Sensor Type	0Ch = Memory
12	Sensor Number	01h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 0Bh (Generic Discrete)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset 0h = Fully Redundant 1h = Redundancy Degraded
15	Event Data 2	Location [7:4] = DIMM index 0–1 = DIMM 1–2, DIMM index per channel [3:0] = Rank index (Physical rank index per DIMM)
16	Event Data 3	Location [7:4] = Socket index 0–3 = CPU0-3 [3:0] = Channel index 0–5 = Channel A-H, Channel index for socket

### 7.3.1 Mirroring Redundancy State Sensor – Next Steps

This event is accompanied by memory errors indicating the source of the issue. Troubleshoot accordingly (probably replace affected DIMM).

For boards with DIMM Fault LEDs, the appropriate Fault LED is lit to indicate which DIMM was the source of the error triggering the Mirroring Failover action, that is, the failing DIMM.

## 7.4 Sparing Redundancy State

Rank Sparing Mode is a Memory RAS configuration option that reserves one memory rank per channel as a “spare rank”. If any rank on a given channel experiences enough Correctable ECC Errors to cross the Correctable Error Threshold, the data in that rank is copied to the spare rank, and then the spare rank is mapped into the memory array to replace the failing rank.

Rank Sparing Mode protects memory data by reserving a “Spare Rank” on each channel that has memory installed on it. If a Correctable Error Threshold event occurs, the data from the failing rank is copied to the Spare Rank on the same channel, and the failing DIMM is disabled. Because the Sparing Domain is no longer redundant, a Sparing Redundancy State SEL Event is logged.

**Table 68. Sparing Redundancy State Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0033h = BIOS SMI Handler
11	Sensor Type	0Ch = Memory
12	Sensor Number	11h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 0Bh (Generic Discrete)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset 0h = Fully Redundant 1h = Redundancy Degraded
15	Event Data 2	Location [7:4] = DIMM index 0–1 = DIMM 1–2, DIMM index per channel [3:0] = Rank index (Physical rank index per DIMM)
16	Event Data 3	Location [7:4] = Socket index 0–3 = CPU0-3 [3:0] = Channel index 0–5 = Channel A-H, Channel index for socket

### 7.4.1 Sparing Redundancy State Sensor – Next Steps

This event is accompanied by memory errors indicating the source of the issue. Troubleshoot accordingly (probably replace affected DIMM).

For boards with DIMM Fault LEDs, the appropriate Fault LED is lit to indicate which DIMM was the source of the error triggering the Mirroring Failover action, that is, the failing DIMM.

## 7.5 Memory RAS ADC/ADDDC Mode

ADDDC memory RAS supports x4 DIMM and is enabled by default when x4 DIMM plugged in. ADDDC can do bank level VLS (Virtual Lockstep), and rank VLS. ADDDC works on channel level granularity. On single rank, it has a maximum tolerance of three hard errors. There are several factors that impact VLS create. Rank number on channel, ADDDC region number, and failed error location are the three most likely factors. ICX standard RAS SKU has one ADDDC region per channel and can only support bank level VLS. Advance RAS SKU has two ADDDC regions per channel and can support bank, rank level VLS.

**Table 69. Memory ADDDC Mode Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0033h = BIOS SMI Handler
11	Sensor Type	0Ch = Memory
12	Sensor Number	20h



Byte	Field	Description
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Generic Discrete)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset 0h = Fully Redundant 1h = Redundancy Degraded
15	Event Data 2	Location [7:4] = DIMM index 0–1 = DIMM 1–2, DIMM index per channel [3:0] = Rank index (Physical rank index per DIMM)
16	Event Data 3	Location [7:4] = Socket index 0–3 = CPU0-3 [3:0] = Channel index 0–5 = Channel A-H, Channel index for socket

## 7.6 ECC and Address Parity

1. Memory data errors are logged as correctable or uncorrectable.
2. Uncorrectable errors are fatal.
3. Memory addresses are protected with parity bits and a parity error is logged. This is a fatal error.

### 7.6.1 Memory Correctable and Uncorrectable ECC Error

ECC errors are divided into Uncorrectable ECC Errors and Correctable ECC Errors. A “Correctable ECC Error” actually represents a threshold overflow. More Correctable Errors are detected at the memory controller level for a given DIMM within a given timeframe. In both cases, the error can be narrowed down to particular DIMM(s). The BIOS SMI error handler uses this information to log the data to the BMC SEL and identify the failing DIMM module.

**Table 70. Correctable And Uncorrectable ECC Error Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0033h = BIOS SMI Handler
11	Sensor Type	0Ch = Memory
12	Sensor Number	02h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset as described in table 81
15	Event Data 2	[7:4] = DIMM index 0–1 = DIMM1-2, DIMM index per Channel [3:0] = Physical rank index per DIMM.
16	Event Data 3	[7:4] = Socket index 0–3 = CPU0-3 [3:0] = Channel index 0–5 = Channel A-H Channel index for Socket

**Table 71. Correctable And Uncorrectable ECC Error Sensor Event Trigger Offset – Next Steps**

Event Trigger Offset		Description	Next Steps
01h	Uncorrectable ECC Error	An uncorrectable (multi-bit) ECC error has occurred. This is a fatal issue that will typically lead to an OS crash (unless memory has been configured in a RAS mode). The system will generate a CATERR# (catastrophic error) and an MCE (Machine Check Exception Error). While the error may be due to a failing DRAM chip on the DIMM, it can also be caused by incorrect seating or improper contact between socket and DIMM, or by bent pins in the processor socket.	<ol style="list-style-type: none"> <li>1. If needed, decode DIMM location from hex version of SEL.</li> <li>2. Verify the DIMM is seated properly.</li> <li>3. Examine gold fingers on edge of the DIMM to verify contacts are clean.</li> <li>4. Inspect the processor socket this DIMM is connected to for bent pins, and if found, replace the board.</li> <li>5. Consider replacing the DIMM as a preventative measure. For multiple occurrences, replace the DIMM.</li> </ol>
00h	Correctable ECC Error threshold reached	There have been too many (10 or more) correctable ECC errors for this particular DIMM since last boot. This event in itself does not pose any direct problems because the ECC errors are still being corrected. Depending on the RAS configuration of the memory, the IMC may take the affected DIMM offline.	<p>Even though this event doesn't immediately lead to problems, it can indicate one of the DIMM modules is slowly failing. If this error occurs more than once:</p> <ol style="list-style-type: none"> <li>1. If needed, decode DIMM location from hex version of SEL.</li> <li>2. Verify the DIMM is seated properly.</li> <li>3. Examine gold fingers on edge of the DIMM to verify contacts are clean.</li> <li>4. Inspect the processor socket this DIMM is connected to for bent pins, and if found, replace the board.</li> <li>5. Consider replacing the DIMM as a preventative measure. For multiple occurrences, replace the DIMM.</li> </ol>

## 7.6.2 Memory Address Parity Error

Address Parity errors are errors detected in the memory addressing hardware. Because these affect the addressing of memory contents, they can potentially lead to the same sort of failures as ECC errors. They are logged as a distinct type of error because they affect memory addressing rather than memory contents, but otherwise they are treated exactly the same as Uncorrectable ECC Errors. Address Parity errors are logged to the BMC SEL, with Event Data to identify the failing address by channel and DIMM to the extent that it is possible to do so.

For different platforms, there are some differences in the event definition. For the following product families, refer to Table 72.

**Table 72. Address Parity Error Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0033h = BIOS SMI Handler
11	Sensor Type	0Ch = Memory
12	Sensor Number	13h
13	Event Direction and Event Type	<p>[7] Event direction  0b = Assertion Event  1b = Deassertion Event  [6:0] Event Type = 6Fh (Sensor Specific)</p>
14	Event Data 1	<p>[7:6] – 10b = OEM code in Event Data 2  [5:4] – 10b = OEM code in Event Data 3  [3:0] – Event Trigger Offset  3h = Command and Address Parity Error</p>

Byte	Field	Description
15	Event Data 2	[7:4] = Dimm index 0-1 = DIMM1-2, DIMM index per Channel [3:0] = Physical rank index per DIMM
16	Event Data 3	[7:4] = Socket index 0-3 = CPU0-3 [3:0] = Channel index 0-5 = Channel A-H, Channel index for Socket

### 7.6.2.1 Memory Address Parity Error Sensor – Next Steps

These are bit errors that are detected in the memory addressing hardware. An Address Parity Error implies that the memory address transmitted to the DIMM addressing circuitry has been compromised, and data read or written is compromised in turn. An Address Parity Error is logged as such in SEL but in all other ways, is treated the same as an Uncorrectable ECC Error.

While the error may be due to a failing DRAM chip on the DIMM, it can also be caused by incorrect seating or improper contact between the socket and DIMM, or by the bent pins in the processor socket.

1. If needed, decode DIMM location from hex version of SEL.
2. Verify the DIMM is seated properly.
3. Examine gold fingers on edge of the DIMM to verify contacts are clean.
4. Inspect the processor socket this DIMM is connected to for bent pins, and if found, replace the board.
5. Consider replacing the DIMM as a preventative measure. For multiple occurrences, replace the DIMM.

## 8. PCI Express\* and Legacy PCI Subsystem

The *PCI Express\* (PCIe\*) Specification* defines standard error types under the Advanced Error Reporting (AER) capabilities. The BIOS logs AER events into the SEL.

The *Legacy PCI Specification* error types are parity error (PERR) and system error (SERR). These errors are supported and logged into the SEL.

### 8.1 Legacy PCI Errors

Legacy PCI errors include PERR and SERR; both are fatal errors.

**Table 73. Legacy PCI Error Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0033h = BIOS SMI Handler
11	Sensor Type	13h = Critical Interrupt
12	Sensor Number	03h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset 4h = PCI PERR 5h = PCI SERR
15	Event Data 2	PCI Bus number
16	Event Data 3	[7:3] – PCI Device number [2:0] – PCI Function number

#### 8.1.1 Legacy PCI Error Sensor – Next Steps

1. Decode the bus, device, and function to identify the card.
2. If this is an add-in card:
  - a. Verify the card is inserted properly.
  - b. Install the card in another slot and check whether the error follows the card or stays with the slot.
  - c. Update all firmware and drivers, including non-Intel components.
3. If this is an on-board device:
  - a. Update all BIOS, firmware, and drivers.
  - b. Replace the board.

### 8.2 PCIe\* Errors

PCIe\* error events are either correctable (informational event) or fatal. In both cases information is logged to help identify the source of the PCIe\* error and the bus, device, and function is included in the extended data fields. The PCIe\* devices are mapped in the operating system by bus, device, and function. Each device is uniquely identified by the bus, device, and function. PCIe\* device information can be found in the operating system.

## 8.2.1 PCIe\* Fatal Errors and Fatal Error #2

When a PCIe\* fatal error is reported to the BIOS SMI handler, it records the error as shown in Table 74.

**Table 74. PCIe\* Fatal Error Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0033h = BIOS SMI Handler
11	Sensor Type	13h = Critical Interrupt
12	Sensor Number	04h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 70h (OEM Specific)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger 0h = Data Link Layer Protocol Error 1h = Surprise Link Down Error 2h = Completer Abort 3h = Unsupported Request 4h = Poisoned TLP 5h = Flow Control Protocol 6h = Completion Timeout 7h = Receiver Buffer Overflow 8h = ACS Violation 9h = Malformed TLP Ah = ECRC Error Bh = Received Fatal Message From Downstream Ch = Unexpected Completion Dh = Received ERR_NONFATAL Message Eh = Uncorrectable Internal Fh = MC Blocked TLP
15	Event Data 2	PCI Bus number
16	Event Data 3	[7:3] – PCI Device number [2:0] – PCI Function number

The PCIe\* Fatal Error #2 is a continuation of the PCIe\* Fatal Error.

**Table 75. Pcie\* Fatal Error #2 Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0033h = BIOS SMI Handler
11	Sensor Type	13h = Critical Interrupt
12	Sensor Number	14h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 76h (OEM Specific)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset 0h = Atomic Egress Blocked 1h = TLP Prefix Blocked Fh = Unspecified Non-AER Fatal Error
15	Event Data 2	PCI Bus number
16	Event Data 3	[7:3] – PCI Device number [2:0] – PCI Function number

### 8.2.1.1 PCIe\* Fatal Error and Fatal Error #2 Sensor – Next Steps

1. Decode the bus, device, and function to identify the card.
2. If this is an add-in card:
  - a. Verify the card is inserted properly.
  - b. Install the card in another slot and check if the error follows the card or stays with the slot.
  - c. Update all firmware and drivers, including non-Intel components.
3. If this is an on-board device:
  - a. Update all BIOS, firmware, and drivers.
  - b. Replace the board.

### 8.2.2 PCIe\* Correctable Errors

When a PCIe\* correctable error is reported to the BIOS SMI handler, it records the error as shown in Table 76.

**Table 76. PCIe\* Correctable Error Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0033h = BIOS SMI Handler
11	Sensor Type	13h = Critical Interrupt
12	Sensor Number	05h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 71h (OEM Specific)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset 0h = Receiver Error 1h = Bad DLLP 2h = Bad TLP 3h = Replay Num Rollover 4h = Replay Timer timeout 5h = Advisory Non-fatal 6h = Link BW Changed 7h = Correctable Internal 8h = Header Log Overflow
15	Event Data 2	PCI Bus number
16	Event Data 3	[7:3] – PCI Device number [2:0] – PCI Function number

#### 8.2.2.1 PCIe\* Correctable Error Sensor – Next Steps

This is an informational event only. Correctable errors are acceptable and normal at a low rate of occurrence. If the error continues:

1. Decode the bus, device, and function to identify the card.
2. If this is an add-in card:
  - a. Verify the card is inserted properly.
  - b. Install the card in another slot and check if the error follows the card or stays with the slot.
  - c. Update all firmware and drivers, including non-Intel components.
3. If this is an on-board device:
  - a. Update all BIOS, firmware, and drivers.
  - b. Replace the board.

### 8.2.3 IIO Internal Error

In addition to PCIe\* Root Port, there are several components inside IIO Subsystem, such as VTD, CBDMA, M2PCIE, IRP, RING, ITC, OTC, etc. This error records the error as shown in Table 85:

**Table 77. IIO Internal Error Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0033h = BIOS SMI Handler
11	Sensor Type	19h = IIO Internal Error
12	Sensor Number	08h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 75h (OEM Discrete)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset 0h = VTD 1h = CBDMA 2h = M2PCIE 3h = IRP 4h = RING 5h = ITC 6h = OTC
15	Event Data 2	PCI Bus number
16	Event Data 3	[7:3] – PCI Device number [2:0] – PCI Function number

## 9. System BIOS Events

There are a number of events that are owned by the system BIOS. These events can occur during Power On Self Test (POST) or when coming out of a sleep state. Not all of these events signify errors. Some events are described in other chapters in this document (for example, memory events).

### 9.1 System Boot

At the end of POST, just before the actual OS boot occurs, a System Boot Event is logged. This basically serves to mark the transition of control from completed POST to OS Loader. It is an information only event.

**Table 78. System Event Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0001h = BIOS POST
11	Sensor Type	12h = System Event
12	Sensor Number	83h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset 01h = System Boot
15	Event Data 2	Not used
16	Event Data 3	Not used

### 9.2 System Firmware Progress (Formerly POST Error)

The BIOS logs any POST errors to the SEL. The two-byte POST code gets logged in the ED2 and ED3 bytes in the SEL entry. This event is not logged every time a POST error is displayed. Even though this event indicates an error, it may not be a fatal error. If this is a serious error, there is typically also a corresponding SEL entry logged for whatever was the cause of the error; this event may contain more information about what happened than the POST error event.

**Table 79. POST Error Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0001h = BIOS POST
11	Sensor Type	0Fh = System Firmware Progress (formerly POST Error)
12	Sensor Number	06h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset = 0h
15	Event Data 2	Low Byte of POST Error Code
16	Event Data 3	High Byte of POST Error Code



## 9.2.1 System Firmware Progress (Formerly POST Error) – Next Steps

See the following table for POST Error Codes.

**Table 80. POST Error Codes**

Error Code	Error Message	Action message	Response
0012	System RTC date/time not set		Major
0048	Password check failed	Put right password.	Major
0140	PCI component encountered a PERR error		Major
0141	PCI resource conflict		Major
0146	PCI out of resources error	Enable Memory Mapped I/O above 4 GB item at SETUP to use 64-bit MMIO.	Major
0191	Processor core/thread count mismatch detected	Use identical CPU type.	Fatal
0192	Processor cache size mismatch detected	Use identical CPU type.	Fatal
0194	Processor family mismatch detected	Use identical CPU type.	Fatal
0195	Processor Intel(R) UPI link frequencies unable to synchronize		Fatal
0196	Processor model mismatch detected	Use identical CPU type.	Fatal
0197	Processor frequencies unable to synchronize	Use identical CPU type.	Fatal
5220	BIOS Settings reset to default settings		Major
5221	Passwords cleared by jumper		Major
5224	Password clear jumper is Set	Recommend reminding user to install BIOS password as BIOS admin password is the master keys for several BIOS security features.	Major
8130	CPU0 disabled		Major
8131	CPU1 disabled		Major
8160	CPU0 unable to apply microcode update		Major
8161	CPU1 unable to apply microcode update		Major
8170	CPU0 failed Self-Test (BIST)		Major
8171	CPU1 failed Self-Test (BIST)		Major
8180	CPU0 microcode update not found		Minor
8181	CPU1 microcode update not found		Minor
8190	Watchdog timer failed on last boot.		Major
8198	OS boot watchdog timer failure.		Major
8300	Baseboard Management Controller failed self-test.		Major
8305	Hot Swap Controller failure		Major
83A0	Management Engine (ME) failed self-test.		Major
83A1	Management Engine (ME) Failed to respond.		Major
84F2	Baseboard management controller failed to respond		Major
84F3	Baseboard Management Controller in Update Mode.		Major
84F4	Baseboard Management Controller Sensor Data Record empty.	Update right SDR.	Major
84FF	System Event Log full	Clear SEL through EWS or SELVIEW utility.	Minor
85FC	Memory component could not be configured in the selected RAS mode		Major
8501	Memory Population Error	Plug DIMM at right population.	Major

## System Event Log (SEL) Troubleshooting Guide

Error Code	Error Message	Action message	Response
<b>8502</b>	PMem invalid DIMM population found on the system.	Populate valid POR pmem DIMM population.	Major
<b>8520</b>	Memory failed test/initialization CPU0_DIMM_A1	Remove the disabled DIMM.	Major
<b>8521</b>	Memory failed test/initialization CPU0_DIMM_A2	Remove the disabled DIMM.	Major
<b>8522</b>	Memory failed test/initialization CPU0_DIMM_A3	Remove the disabled DIMM.	Major
<b>8523</b>	Memory failed test/initialization CPU0_DIMM_B1	Remove the disabled DIMM.	Major
<b>8524</b>	Memory failed test/initialization CPU0_DIMM_B2	Remove the disabled DIMM.	Major
<b>8525</b>	Memory failed test/initialization CPU0_DIMM_B3	Remove the disabled DIMM.	Major
<b>8526</b>	Memory failed test/initialization CPU0_DIMM_C1	Remove the disabled DIMM.	Major
<b>8527</b>	Memory failed test/initialization CPU0_DIMM_C2	Remove the disabled DIMM.	Major
<b>8528</b>	Memory failed test/initialization CPU0_DIMM_C3	Remove the disabled DIMM.	Major
<b>8529</b>	Memory failed test/initialization CPU0_DIMM_D1	Remove the disabled DIMM.	Major
<b>852A</b>	Memory failed test/initialization CPU0_DIMM_D2	Remove the disabled DIMM.	Major
<b>852B</b>	Memory failed test/initialization CPU0_DIMM_D3	Remove the disabled DIMM.	Major
<b>852C</b>	Memory failed test/initialization CPU0_DIMM_E1	Remove the disabled DIMM.	Major
<b>852D</b>	Memory failed test/initialization CPU0_DIMM_E2	Remove the disabled DIMM.	Major
<b>852E</b>	Memory failed test/initialization CPU0_DIMM_E3	Remove the disabled DIMM.	Major
<b>852F</b>	Memory failed test/initialization CPU0_DIMM_F1	Remove the disabled DIMM.	Major
<b>8530</b>	Memory failed test/initialization CPU0_DIMM_F2	Remove the disabled DIMM.	Major
<b>8531</b>	Memory failed test/initialization CPU0_DIMM_F3	Remove the disabled DIMM.	Major
<b>8532</b>	Memory failed test/initialization CPU0_DIMM_G1	Remove the disabled DIMM.	Major
<b>8533</b>	Memory failed test/initialization CPU0_DIMM_G2	Remove the disabled DIMM.	Major
<b>8534</b>	Memory failed test/initialization CPU0_DIMM_G3	Remove the disabled DIMM.	Major
<b>8535</b>	Memory failed test/initialization CPU0_DIMM_H1	Remove the disabled DIMM.	Major
<b>8536</b>	Memory failed test/initialization CPU0_DIMM_H2	Remove the disabled DIMM.	Major
<b>8537</b>	Memory failed test/initialization CPU0_DIMM_H3	Remove the disabled DIMM.	Major
<b>8538</b>	Memory failed test/initialization CPU1_DIMM_A1	Remove the disabled DIMM.	Major
<b>8539</b>	Memory failed test/initialization CPU1_DIMM_A2	Remove the disabled DIMM.	Major
<b>853A</b>	Memory failed test/initialization CPU1_DIMM_A3	Remove the disabled DIMM.	Major
<b>853B</b>	Memory failed test/initialization CPU1_DIMM_B1	Remove the disabled DIMM.	Major
<b>853C</b>	Memory failed test/initialization CPU1_DIMM_B2	Remove the disabled DIMM.	Major
<b>853D</b>	Memory failed test/initialization CPU1_DIMM_B3	Remove the disabled DIMM.	Major
<b>853E</b>	Memory failed test/initialization CPU1_DIMM_C1	Remove the disabled DIMM.	Major
<b>853F</b> <b>(Go to 85C0)</b>	Memory failed test/initialization CPU1_DIMM_C2	Remove the disabled DIMM.	Major
<b>8540</b>	Memory disabled.CPU0_DIMM_A1	Remove the disabled DIMM.	Major
<b>8541</b>	Memory disabled.CPU0_DIMM_A2	Remove the disabled DIMM.	Major
<b>8542</b>	Memory disabled.CPU0_DIMM_A3	Remove the disabled DIMM.	Major
<b>8543</b>	Memory disabled.CPU0_DIMM_B1	Remove the disabled DIMM.	Major
<b>8544</b>	Memory disabled.CPU0_DIMM_B2	Remove the disabled DIMM.	Major
<b>8545</b>	Memory disabled.CPU0_DIMM_B3	Remove the disabled DIMM.	Major
<b>8546</b>	Memory disabled.CPU0_DIMM_C1	Remove the disabled DIMM.	Major
<b>8547</b>	Memory disabled.CPU0_DIMM_C2	Remove the disabled DIMM.	Major
<b>8548</b>	Memory disabled.CPU0_DIMM_C3	Remove the disabled DIMM.	Major
<b>8549</b>	Memory disabled.CPU0_DIMM_D1	Remove the disabled DIMM.	Major
<b>854A</b>	Memory disabled.CPU0_DIMM_D2	Remove the disabled DIMM.	Major

## System Event Log (SEL) Troubleshooting Guide

Error Code	Error Message	Action message	Response
<b>854B</b>	Memory disabled.CPU0_DIMM_D3	Remove the disabled DIMM.	Major
<b>854C</b>	Memory disabled.CPU0_DIMM_E1	Remove the disabled DIMM.	Major
<b>854D</b>	Memory disabled.CPU0_DIMM_E2	Remove the disabled DIMM.	Major
<b>854E</b>	Memory disabled.CPU0_DIMM_E3	Remove the disabled DIMM.	Major
<b>854F</b>	Memory disabled.CPU0_DIMM_F1	Remove the disabled DIMM.	Major
<b>8550</b>	Memory disabled.CPU0_DIMM_F2	Remove the disabled DIMM.	Major
<b>8551</b>	Memory disabled.CPU0_DIMM_F3	Remove the disabled DIMM.	Major
<b>8552</b>	Memory disabled.CPU0_DIMM_G1	Remove the disabled DIMM.	Major
<b>8553</b>	Memory disabled.CPU0_DIMM_G2	Remove the disabled DIMM.	Major
<b>8554</b>	Memory disabled.CPU0_DIMM_G3	Remove the disabled DIMM.	Major
<b>8555</b>	Memory disabled.CPU0_DIMM_H1	Remove the disabled DIMM.	Major
<b>8556</b>	Memory disabled.CPU0_DIMM_H2	Remove the disabled DIMM.	Major
<b>8557</b>	Memory disabled.CPU0_DIMM_H3	Remove the disabled DIMM.	Major
<b>8558</b>	Memory disabled.CPU1_DIMM_A1	Remove the disabled DIMM.	Major
<b>8559</b>	Memory disabled.CPU1_DIMM_A2	Remove the disabled DIMM.	Major
<b>855A</b>	Memory disabled.CPU1_DIMM_A3	Remove the disabled DIMM.	Major
<b>855B</b>	Memory disabled.CPU1_DIMM_B1	Remove the disabled DIMM.	Major
<b>855C</b>	Memory disabled.CPU1_DIMM_B2	Remove the disabled DIMM.	Major
<b>855D</b>	Memory disabled.CPU1_DIMM_B3	Remove the disabled DIMM.	Major
<b>855E</b>	Memory disabled.CPU1_DIMM_C1	Remove the disabled DIMM.	Major
<b>855F</b> <b>(Go to 85D0)</b>	Memory disabled.CPU1_DIMM_C2	Remove the disabled DIMM.	Major
<b>8560</b>	Memory encountered a Serial Presence Detection(SPD) failure.CPU0_DIMM_A1		Major
<b>8561</b>	Memory encountered a Serial Presence Detection(SPD) failure.CPU0_DIMM_A2		Major
<b>8562</b>	Memory encountered a Serial Presence Detection(SPD) failure.CPU0_DIMM_A3		Major
<b>8563</b>	Memory encountered a Serial Presence Detection(SPD) failure.CPU0_DIMM_B1		Major
<b>8564</b>	Memory encountered a Serial Presence Detection(SPD) failure.CPU0_DIMM_B2		Major
<b>8565</b>	Memory encountered a Serial Presence Detection(SPD) failure.CPU0_DIMM_B3		Major
<b>8566</b>	Memory encountered a Serial Presence Detection(SPD) failure.CPU0_DIMM_C1		Major
<b>8567</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU0_DIMM_C2		Major
<b>8568</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU0_DIMM_C3		Major
<b>8569</b>	Memory encountered a Serial Presence Detection(SPD) failure.CPU0_DIMM_D1		Major
<b>856A</b>	Memory encountered a Serial Presence Detection(SPD) failure.CPU0_DIMM_D2		Major
<b>856B</b>	Memory encountered a Serial Presence Detection(SPD) failure.CPU0_DIMM_D3		Major
<b>856C</b>	Memory encountered a Serial Presence Detection(SPD) failure.CPU0_DIMM_E1		Major

## System Event Log (SEL) Troubleshooting Guide

Error Code	Error Message	Action message	Response
<b>856D</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU0_DIMM_E2		Major
<b>856E</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU0_DIMM_E3		Major
<b>856F</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU0_DIMM_F1		Major
<b>8570</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU0_DIMM_F2		Major
<b>8571</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU0_DIMM_F3		Major
<b>8572</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU0_DIMM_G1		Major
<b>8573</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU0_DIMM_G2		Major
<b>8574</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU0_DIMM_G3		Major
<b>8575</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU0_DIMM_H1		Major
<b>8576</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU0_DIMM_H2		Major
<b>8577</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU0_DIMM_H3		Major
<b>8578</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_A1		Major
<b>8579</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_A2		Major
<b>857A</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_A3		Major
<b>857B</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_B1		Major
<b>857C</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_B2		Major
<b>857D</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_B3		Major
<b>857E</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_C1		Major
<b>857F (Go to 85E0)</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_C2		Major
<b>85C0</b>	Memory failed test/initialization CPU1_DIMM_C3	Remove the disabled DIMM.	Major
<b>85C1</b>	Memory failed test/initialization CPU1_DIMM_D1	Remove the disabled DIMM.	Major
<b>85C2</b>	Memory failed test/initialization CPU1_DIMM_D2	Remove the disabled DIMM.	Major
<b>85C3</b>	Memory failed test/initialization CPU1_DIMM_D3	Remove the disabled DIMM.	Major
<b>85C4</b>	Memory failed test/initialization CPU1_DIMM_E1	Remove the disabled DIMM.	Major
<b>85C5</b>	Memory failed test/initialization CPU1_DIMM_E2	Remove the disabled DIMM.	Major
<b>85C6</b>	Memory failed test/initialization CPU1_DIMM_E3	Remove the disabled DIMM.	Major
<b>85C7</b>	Memory failed test/initialization CPU1_DIMM_F1	Remove the disabled DIMM.	Major
<b>85C8</b>	Memory failed test/initialization CPU1_DIMM_F2	Remove the disabled DIMM.	Major
<b>85C9</b>	Memory failed test/initialization CPU1_DIMM_F3	Remove the disabled DIMM.	Major
<b>85CA</b>	Memory failed test/initialization CPU1_DIMM_G1	Remove the disabled DIMM.	Major
<b>85CB</b>	Memory failed test/initialization CPU1_DIMM_G2	Remove the disabled DIMM.	Major

## System Event Log (SEL) Troubleshooting Guide

Error Code	Error Message	Action message	Response
85CC	Memory failed test/initialization CPU1_DIMM_G3	Remove the disabled DIMM.	Major
85CD	Memory failed test/initialization CPU1_DIMM_H1	Remove the disabled DIMM.	Major
85CE	Memory failed test/initialization CPU1_DIMM_H2	Remove the disabled DIMM.	Major
85CF	Memory failed test/initialization CPU1_DIMM_H3	Remove the disabled DIMM.	Major
85D0	Memory disabled.CPU1_DIMM_C3	Remove the disabled DIMM.	Major
85D1	Memory disabled.CPU1_DIMM_D1	Remove the disabled DIMM.	Major
85D2	Memory disabled.CPU1_DIMM_D2	Remove the disabled DIMM.	Major
85D3	Memory disabled.CPU1_DIMM_D3	Remove the disabled DIMM.	Major
85D4	Memory disabled.CPU1_DIMM_E1	Remove the disabled DIMM.	Major
85D5	Memory disabled.CPU1_DIMM_E2	Remove the disabled DIMM.	Major
85D6	Memory disabled.CPU1_DIMM_E3	Remove the disabled DIMM.	Major
85D7	Memory disabled.CPU1_DIMM_F1	Remove the disabled DIMM.	Major
85D8	Memory disabled.CPU1_DIMM_F2	Remove the disabled DIMM.	Major
85D9	Memory disabled.CPU1_DIMM_F3	Remove the disabled DIMM.	Major
85DA	Memory disabled.CPU1_DIMM_G1	Remove the disabled DIMM.	Major
85DB	Memory disabled.CPU1_DIMM_G2	Remove the disabled DIMM.	Major
85DC	Memory disabled.CPU1_DIMM_G3	Remove the disabled DIMM.	Major
85DD	Memory disabled.CPU1_DIMM_H1	Remove the disabled DIMM.	Major
85DE	Memory disabled.CPU1_DIMM_H2	Remove the disabled DIMM.	Major
85DF	Memory disabled.CPU1_DIMM_H3	Remove the disabled DIMM.	Major
85E0	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_C3		Major
85E1	Memory encountered a Serial Presence Detection (SPD) failure. CPU1_DIMM_D1		Major
85E2	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_D2		Major
85E3	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_D3		Major
85E4	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_E1		Major
85E5	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_E2		Major
85E6	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_E3		Major
85E7	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_F1		Major
85E8	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_F2		Major
85E9	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_F3		Major
85EA	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_G1		Major
85EB	Memory encountered a Serial Presence Detection (SPD) failure. CPU1_DIMM_G2		Major
85EC	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_G3		Major
85ED	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_H1		Major

## System Event Log (SEL) Troubleshooting Guide

Error Code	Error Message	Action message	Response
<b>85EE</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_H2		Major
<b>85EF</b>	Memory encountered a Serial Presence Detection (SPD) failure.CPU1_DIMM_H3		Major
<b>8604</b>	POST Reclaim of non-critical NVRAM variables		Minor
<b>8605</b>	BIOS Settings are corrupted		Major
<b>8606</b>	NVRAM variable space was corrupted and has been reinitialized		Major
<b>8607</b>	Recovery boot has been initiated. Note: The Primary BIOS image may be corrupted or the system may hang during POST. A BIOS update is required.		Fatal
<b>A100</b>	BIOS ACM Error		Major
<b>A421</b>	PCI component encountered a SERR error		Fatal
<b>A5A0</b>	PCI Express component encountered a PERR error		Minor
<b>A5A1</b>	PCI Express component encountered an SERR error		Fatal
<b>A6A0</b>	DXE Boot Services driver: Not enough memory available to shadow a Legacy Option ROM.	Disable oprom at SETUP to save runtime memory.	Minor

## 10. Chassis Subsystem

The BMC monitors several aspects of the chassis. Next to logging when the power and reset buttons get pressed, the BMC also monitors chassis intrusion if a chassis intrusion switch is included in the chassis, as well as looking at the network connections, and logging an event whenever the physical network link is lost.

### 10.1 Physical Security

Two sensors are included in the physical security subsystem: chassis intrusion and LAN leash lost.

#### 10.1.1 Chassis Intrusion

Chassis Intrusion is monitored on supported chassis, and the BMC logs corresponding events when the chassis lid is opened and closed.

#### 10.1.2 LAN Leash Lost

The LAN Leash lost sensor monitors the physical connection on the on-board network ports. If a LAN Leash lost event is logged, this means the network port lost its physical connection.

**Table 81. Physical Security Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	05h = Physical Security
12	Sensor Number	04h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset as described in Table 82
15	Event Data 2	Not used
16	Event Data 3	Not used

**Table 82. Physical Security Sensor Event Trigger Offset – Next Steps**

Event Trigger Offset		Description	Next Steps
00h	Chassis intrusion	The chassis has been opened (or the chassis intrusion sensor is not connected).	<ol style="list-style-type: none"> <li>1. Use the Quick Start Guide and the Service Guide to determine whether the chassis intrusion switch is connected properly.</li> <li>2. If this is the case, make sure it makes proper contact when the chassis is closed.</li> <li>3. If this is also the case, someone has opened the chassis. Ensure nobody has access to the system that should not.</li> </ol>
04h	LAN leash lost	A LAN cable that was present when the BMC initialized has been unplugged. This event gets logged when the electrical connection on the NIC connector gets lost.	<p>This is most likely due to unplugging the cable but can also happen if there is an issue with the cable or switch.</p> <ol style="list-style-type: none"> <li>1. Check the LAN cable and connector for issues.</li> <li>2. Investigate switch logs where possible.</li> <li>3. Ensure nobody has access to the server that should not.</li> </ol>

## 10.2 Front Panel (NMI) Interrupt

The BMC supports a non-maskable interrupt (NMI) sensor for logging an event when a diagnostic interrupt is generated for the following cases:

- The front panel diagnostic interrupt button is pressed.
- The BMC receives an IPMI Chassis Control command that requests this action.

The front panel interrupt button (also referred to as NMI button) is a recessed button on the front panel that allows the user to force a critical interrupt that causes a crash error or kernel panic.

**Table 83. Front Panel (NMI) Interrupt Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	13h = Critical Interrupt
12	Sensor Number	05h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset = 0h 00 = Front Panel NMI / Diagnostic Interrupt
15	Event Data 2	Not used
16	Event Data 3	Not used

### 10.2.1 Front Panel (NMI) Interrupt – Next Steps

The purpose of this button is for diagnosing software issues. When a critical interrupt is generated, the operating system typically saves a memory dump. This allows for exact analysis of what is going on in system memory, which can be useful for software developers, or for troubleshooting the operating system, software, and driver issues.

If this button was not actually pressed, ensure there is no physical fault with the front panel.

This event only gets logged if a user pressed the NMI button or sent an IPMI Chassis Control command requesting this action and, although it causes the operating system to crash, is not an error.



### 10.3 Button Sensor

The BMC logs when the front panel power and reset buttons get pressed. This is purely for informational purposes and these events do not indicate errors.

**Table 84. Button Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	14h = Button/Switch
12	Sensor Number	09h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset 0h = Power Button 2h = Reset Button
15	Event Data 2	Not used
16	Event Data 3	Not used

## 11. Miscellaneous Events

The miscellaneous events section addresses sensors not easily grouped with other sensor types.

### 11.1 IPMI Watchdog

Intel® Server Systems support an IPMI watchdog timer that can check to see whether the OS is still responsive. The timer is disabled by default, and has to be enabled manually. It then requires an IPMI-aware utility in the operating system that resets the timer before it expires. If the timer does expire, the BMC can take action if it is configured to do so (reset, power down, power cycle, or generate a critical interrupt).

**Table 85. IPMI Watchdog Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	23h = Watchdog 2
12	Sensor Number	03h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 11B = Sensor-specific event extension code in Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset as described in Table 86
15	Event Data 2	[7:4] – Interrupt type 0h = None 1h = SMI 2h = NMI 3h = Messaging Interrupt Fh = Unspecified All other = Reserved [3:0] – Timer use at expiration 0h = Reserved 1h = BIOS FRB2 2h = BIOS/POST 3h = OS Load 4h = SMS/OS 5h = OEM Fh = Unspecified All other = Reserved
16	Event Data 3	[7:0] – 0xFF

**Table 86. IPMI Watchdog Sensor Event Trigger Offset – Next Steps**

Event Trigger Offset	Description	Next Steps
00h	Timer expired, status only	<p>If this event is being logged, it is because the BMC has been configured to check the watchdog timer.</p> <ol style="list-style-type: none"> <li>1. Make sure to have support for this in the OS (typically using a third-party IPMI-aware utility such as <code>ipmitool</code> or <code>ipmiutil</code> along with the OpenIPMI driver).</li> <li>2. If this is the case, it is likely the OS has hung, and investigate OS event logs need to be investigated to determine what may have caused this.</li> </ol>
01h	Hard reset	
02h	Power down	
03h	Power cycle	
08h	Timer interrupt	

## 11.2 System Management Interrupt (SMI) Timeout

System management interrupt (SMI) is an interrupt that gets generated so the processor can service server management events (typically memory or PCI errors, or other forms of critical interrupts), in order to log them to the SEL. If this interrupt times out, the system is frozen. The BMC resets the system after logging the event.

**Table 87. SMI Timeout Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	F3h = SMI Timeout
12	Sensor Number	06h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 03h ("digital" Discrete)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset = 1h = State Asserted
15	Event Data 2	Not used
16	Event Data 3	Not used

### 11.2.1 SMI Timeout – Next Steps

This event normally only occurs after another more critical event.

1. Check the SEL for any critical interrupts, memory errors, bus errors, PCI errors, or any other serious errors.
2. If these are not present, the system locked up before it was able to log the original issue. In this case, low level debug is normally required.

## 11.3 System Event Log Cleared

The BMC logs an SEL clear event. This is only ever the first event in the SEL. The cause of this event is either a manual SEL clear using `selview` or some other IPMI-aware utility, or is done in the factory as one of the last steps in the manufacturing process.

This is an informational event only.

**Table 88. System Event Log Cleared Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	10h = Event Logging Disabled
12	Sensor Number	07h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset = 2h = Log area reset/cleared
15	Event Data 2	Not used
16	Event Data 3	Not used

## 11.4 System Event Sensor

The BMC supports a System Event sensor and logs an SEL event for a Platform Event Filter (PEF) action, BIOS/Intel® ME out-of-band (OOB) update, and BIOS configuration change from the BMC embedded web server (EWS).

### 11.4.1 System Event – PEF Action

The BMC is configurable to send alerts for events logged into the SEL. These alerts are called Platform Event Filters (PEFs) and are disabled by default. The user must configure and enable this feature. PEF events are logged if the BMC takes action due to a PEF configuration. The BMC event triggering the PEF action is also in the SEL.

This is functionality built into the BMC to allow it to send alerts (SNMP or other) for any event that gets logged to the SEL. PEF filters are turned off by default and have to be enabled manually using a deployment assistant, the syscfg utility, or an IPMI-aware utility.

**Table 89. System Event – PEF Action Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	12h = System Event
12	Sensor Number	08h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 11B = Sensor-specific event extension code in Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset = 4h = PEF Action
15	Event Data 2	[7:6] – Reserved [5] – 1b = Diagnostic Interrupt (NMI) [4] – 1b = OEM action [3] – 1b = Power cycle [2] – 1b = Reset [1] – 1b = Power off [0] – 1b = Alert
16	Event Data 3	[7:0] – 0xFF
<b>If Event Data 1 [3:0] equals 07h or 08h, Event definition will follow below.</b>		
17	Extended Data 1	[7:6] - 11b = OEM code in Byte2 [5:4] - 00b = unspecified byte 3 [3:0] – 07h = image is uploaded [3:0] – 08h = image is lost
18	Extended Data 2	[7:0] 00h = BIOS Configuration Table 01h = BIOS Configuration change 02h = BIOS Image 03h = ME Image 04h = FD Image
19	Extended Data 3	[7:0] 00h = Firmware Update 01h = BIOS Configuration

This event gets logged if the BMC takes an action due to PEF configuration. Actions can be sending an alert, along with possibly resetting, power cycling, or powering down the system. There is another event that has led to the action; investigate the SEL and PEF settings to identify this event, and troubleshoot accordingly.

## 11.4.2 System Event – OOB Update and BIOS Configuration Change

This event gets logged if the OOB BIOS/ Intel® ME update or BIOS configuration change is triggered from the BMC EWS.

**Table 90. System Event – BIOS/Intel® ME OOB Update And BIOS Configuration Change**

Byte	Field	Description
11	Sensor Type	12h = System Event
12	Sensor Number	08h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] - 11b = OEM code in Byte2 [5:4] - 00b = unspecified byte 3 [3:0] - 07h = image is uploaded [3:0] - 08h = image is lost
15	Event Data 2	[7:0] 00h = BIOS Configuration Table 01h = BIOS Configuration change 02h = BIOS Image 03h = ME Image 04h = FD Image
16	Event Data 3	[7:0] 00h = Firmware Update 01h = BIOS Configuration

## 11.5 BMC Hardware Watchdog Sensor

The BMC supports an IPMI sensor to report that a BMC reset has occurred due to an action taken by the BMC Watchdog feature. A SEL event is logged when either the BMC FW stack is reset or the BMC CPU itself is reset.

**Table 91. BMC Hardware Watchdog Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	28h = Management Subsystem Health
12	Sensor Number	0Ah
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 03h ("digital" Discrete)
14	Event Data 1	[7:6] - 10b = OEM code in Byte2 [5:4] - 10b = OEM code in Byte 3 [3:0] - 01h = Event Trigger Offset - State asserted
15	Event Data 2	[7:2] - Reserved [1:0] - Threshold Crossed 01h = Normal Mode Unstable Boot Threshold 02h = Safe Mode Unstable Boot Threshold All other = Reserved
16	Event Data 3	[7:0] - Number of successive unstable boot attempts prior to crossing the threshold.
17	Extended Data 1	[7] Reserved [6:4] 110b = 6 valid extended data bytes following

Byte	Field	Description
		[3:2] 00b = Reserved [1:0] 00b = Severity = OK for this sensor (that is, failures should not result in Front Panel status LED to show a warning or fault). General encoding for severity is defined as: 00b = OK or non-specified 01b = Degraded 10b = Warning 11b = Failure
18	Extended Data 2~7	Firmware revision in use at the time of the fault: Byte 2 = Major rev (binary encoded) Byte 3 = Minor rev (BCD encoded) Byte 4~7 = Build ID (binary) – LSB first

### 11.5.1 BMC Watchdog Sensor – Next Steps

A SEL event is logged when either the BMC FW stack is reset or the BMC CPU itself is reset.

1. Check the SEL for any other events around the time of the failure.
2. Take note of all IPMI activity that was occurring around the time of the failure. Capture a System BMC Debug Log as soon as possible after the failure. This log can be captured from the Integrated BMC Web Console or by using the syscfg utility (`syscfg/sbmcdl Public filename.zip`). Send the log file to the system manufacturer or Intel representative for failure analysis.

## 11.6 MTM Level Change Sensor

The BMC logs a SEL record when any BMC Manufacturing Test Mode is entered.

**Table 92. MTM Level Change Sensor**

Byte	Field	Description
11	Sensor Type	28h = Mgmt Health
12	Sensor Number	81h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 03h ("digital" Discrete)
14	Event Data 1	[7:6] - 10b = OEM code in Byte2 [5:4] - 00b = unspecified byte 3 [3:0] - 0x01 = Offset from Event/Reading code
15	Event Data 2	[7:0] - MTM Level entered
16	Event Data 3	[7:0] - 0xFF

## 11.7 Add-In Module/Board Presence Sensor

Some server baseboards provide dedicated slots for add-in modules/boards (e.g. SAS, IO) or support one or more PCIe\* riser boards. For these baseboards, the BMC provides an individual presence sensor to indicate if the module/board is installed.

**Table 93. Add-In Module Presence Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	15h = Module/Board
12	Sensor Number	0Eh = OCP Module Presence

Byte	Field	Description
		0Fh = SAS Module Presence
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 08h (Digital Discrete)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset = 01h (Inserted/Present)
15	Event Data 2	Not used
16	Event Data 3	Not used

### 11.7.1 Add-In Module Presence – Next Steps

If an unexpected device is removed or inserted, ensure that the module has been seated properly.

## 11.8 BMC Firmware Health Sensor

The BMC tracks the health of each of its IPMI sensors and reports failures by providing a “BMC FW Health” sensor of the IPMI 2.0 sensor type Management Subsystem Health with support for the Sensor Failure offset. Only assertions are logged into the SEL for the Sensor Failure offset. The BMC Firmware Health sensor asserts for any sensor when ten consecutive sensor errors are read. These are not standard sensor events (that is, threshold crossings or discrete assertions). These are BMC Hardware Access Layer (HAL) errors such as I<sup>2</sup>C NAKs or internal errors while attempting to read a register. If a successful sensor read is completed, the counter resets to zero.

**Table 94. BMC Firmware Health Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	28h = Management Subsystem Health
12	Sensor Number	10h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 11b = Sensor-specific event extension code in Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset = 4h = Sensor failure
15	Event Data 2	[7:0] - Sensor number that triggered the failure
16	Event Data 3	[7:0] – 0xFF

### 11.8.1 BMC Firmware Health Sensor – Next Steps

1. Check the SEL for any other events around the time of the failure.
2. Take note of all IPMI activity that was occurring around the time of the failure. Capture a System BMC Debug Log as soon as possible after the failure. This log can be captured from the Integrated BMC Web Console or by using the syscfg utility (`syscfg/sbmcdl Public filename.zip`). Send the log file to the system manufacturer or Intel representative for failure analysis.
3. If the failure continues around a specific sensor, replace the board with that sensor.

## 11.9 Firmware Update Status Sensor

The BMC firmware supports a single Firmware Update Status sensor. This sensor is used to generate SEL events related to updates of embedded firmware on the platform. This includes updates to the BMC, BIOS, CPLD and Intel® ME firmware.

This sensor is an event-only sensor that is not readable. Event generation is only enabled for assertion events.

**Table 95. Firmware Update Status Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	2Bh (Version Change)
12	Sensor Number	12h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 70h = OEM defined
14	Event Data 1	[Bits 7:6] - 10b = OEM code in Byte2 [Bits 5:4] - 00b = unspecified Byte3 [Bits 3:0] - Offset from Event/Reading code Event Trigger Offset 00h = Update started 01h = Update completed successfully 02h = Update failure
15	Event Data 2	[Bits 7:4] Target of update 0000b = BMC 0001b = BIOS 0010b = ME 0011b = EWS (Embedded Web server) 0101b = CPLD 0110b = PCIe* Switch 0111b = FD [Bits 3:1] Target instance (zero-based) [Bits 0:0] Reserved
16	Event Data 3	Reserved

**Note:** All reserved bits must be set to zero.

17	Extended Data 1	[Bits 7] Reserved [Bits 6:4] = Number of valid extended data bytes following [Bits 3:2] = Reserved [Bits 1:0] Severity = OK for this sensor (that is, failures should not result in Front Panel status LED to show a warning or fault). General encoding for severity is defined as: 00b = OK or non-specified 01b = Degraded 10b = Non-fatal 11b = Fatal
18	Extended Data 2–7	Firmware revision information (target-specific) If Target of Update is “BMC” then Byte 2 = Major rev (binary encoded) Byte 3 = Minor rev (BCD encoded) Byte 4–7 = Build ID (binary) – LSB first If Target of Update is “BIOS” then Byte 2 = Major rev (BCD encoded) Byte 3 = Minor rev (BCD encoded)



Byte	Field	Description
		Bytes 4–7 = Build ID (ASCII encoded) If Target of Update is "ME" then Byte 2 = Major rev (binary encoded) Byte 3 = Minor rev1 (BCD encoded) Byte 4 = Minor rev2 (BCD encoded) Byte 5–6 = Build number (BCD Encoded) Byte 7 = Reserved. If Target of Update is "CPLD" then Byte 2 = Major rev (binary encoded)

## 11.10 Sensor Data Record (SDR) Auto-Config Fault

The BMC provides monitoring of the health status of the sensor data record (SDR) auto-configuration feature. The BMC firmware supports a discrete IPMI sensor for reporting and logging this fault condition.

The single supported sensor offset is asserted when both of the following are true:

- The BMC's SDR auto-configuration feature fails and
- The BMC's SDR auto-configuration feature is set to 'enabled'.

The offset is set to a de-asserted state when either of the following is true:

- The BMC successfully completes an SDR auto-configuration cycle (resulting in auto-detecting the chassis and updating the SDR repository accordingly), regardless of the triggering event or
- The BMC's SDR auto-configuration feature is set to 'disable'.

**Table 96. SDR Auto-Config Fault Sensor**

Byte	Field	Description
11	Sensor Type	28h = Mgmt Health
12	Sensor Number	87h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 03h ("digital" Discrete)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset = 1h = State Asserted
15	Event Data 2	Not used
16	Event Data 3	[7:3] – reserved [2:0]: - OEM code for type of auto-config error 0h = CFG syntax error 1h = Chassis auto-detect error 2h = SDR/CFG file mismatch 3h = SDR or CFG file corrupted 4h = SDR syntax error 5h = Parse error All other values reserved

### 11.10.1 SDR Auto-Config Fault Sensor – Next Steps

1. Check update/upload SDR file and Config file correctly.
2. Check if FRU is valid.
3. Check cable connection especially PSU PMBus cable.

## 11.11 Invalid user name or password sensor

The BMC firmware supports a single Bad User Password sensor. This sensor is used to generate SEL events related to invalid user name or password attempts for BMC access with an IPMI message encapsulated in RMCP/RMCP+. SEL logging will follow the bad password threshold setting from the LAN parameters, and the end user can set/get the bad password threshold by set/getting the LAN configuration command.

**Table 97. Bad User PWD sensor**

Byte	Field	Description
11	Sensor Type	2Ah = Session Audit
12	Sensor Number	D7h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset 02h - Invalid Username or Password 03h – Invalid password disable
15	Event Data 2	[7:6] Reserved [5:0] User ID 0x00 = unspecified
16	Event Data 3	[7:4] Reserved [3:0] Channel number

## 11.12 Remote debug sensor

To reduce the risk of an administrator unknowingly exposing the Remote PECCI Debug as a potential attack point, the BMC supports an IPMI sensor to report the configuration state of Remote Debug features

**Table 98. Remote Debug Sensor**

Byte	Field	Description
11	Sensor Type	DBh - OEM Defined.
12	Sensor Number	DBh
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 7Bh(OEM Defined)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset 00h - Remote JTAG Consent 01h - Remote JTAG Enabled 02h - Remote JTAG Session 03h - Remote PECCI Enabled 04h - Remote PECCI Session
15	Event Data 2	[7:5] – Reserved [4] – PECCI Enabled 0b: Disabled 1b: Enabled [3] – PECCI Session State 0b: Idle

## System Event Log (SEL) Troubleshooting Guide

Byte	Field	Description
		1b: Session in progress [2] – JTAG Debug Consent 0b: Consent not given 1b: Consent given [1] – JTAG Enabled 0b: Disabled 1b: Enabled [0] – JTAG Session State 0b: Idle 1b: Session in progress
16	Event Data 3	[7:0] –FFh Unspecified.
17	Extended Byte1	[Bit 7] Reserved [Bits 6:4] 110b = 6 valid extended data bytes following [Bits 3:2] 00b = Reserved [Bits 1:0] 00b = Severity = OK for this sensor
18	Extended Byte 2–7	Six bytes of last client network connection address. May represent IP address or MAC.

### 11.13 System Firmware Security Sensor

The BMC supports a Firmware Security Sensor for logging a SEL event for security of BMC Firmware image authentication result in different phase.

**Table 99. System Firmware Security Sensor**

Byte	Field	Description
11	Sensor Type	C3h – OEM defined
12	Sensor Number	1Ah
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 71h (OEM Defined)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset 00h Authentication Failure of BMC Firmware Image During Boot 01h Invalid Security Revision of BMC Firmware Image During Boot 02h Authentication Failure of BMC Firmware Image During Update 03h Invalid Security Revision of BMC Firmware Image During Update 04h Authentication Failure of Signed Region During Update 05h Authentication Failure of Signed Region During Boot or Runtime 06h Invalid Security Revision of Signed Region During Update 07h Invalid Security Revision of Signed Region During Boot or Runtime 0Ch Factory Image Booted 0Dh Factory Security Revision Downgraded
15	Event Data 2	[7:0] - Image Type
16	Event Data 3	[7:0] –FFh Unspecified.

## 11.14 KCS Policy Sensor

KCS (Keyboard Controller Style) interface is the single-wire bus which directly connecting the BMC and the host CPU. Host software including operating system, applications, and BIOS access the BMC through KCS. There is no authentication established for KCS. Communication through this bus is in plain raw data without any authentication and authorization needed. Through KCS, host software can perform operations, which should be in highest privilege. This exposes security risks, as any compromised OS will allow a potential hacker to gain control of the BMC.

To mitigate the security risk, the BMC firmware implements KCS Policy Control Modes to allow an authenticated BMC administrative user to control the level of protection from IPMI commands executed over the KCS channels. Within this generation of BMC firmware, 3 different KCS Policy Control Modes are supported:

### KCS Policy Control Mode – Allow All

This configuration setting is intended for normal IPMI compliant communications between the Host OS and the BMC. This mode should be used when provisioning the BMC configuration for deployment.

### KCS Policy Control Mode – Deny All

This configuration setting disables the IPMI KCS command interfaces between the Host OS and the BMC. This is a non-compliant IPMI configuration that will impact the operation of the Server Management Software running on the Host OS. This only applies to the IPMI commands over the KCS interfaces, and does not apply to the authenticated network interfaces to the BMC.

### KCS Policy Control Mode – Restricted

This configuration setting enables the use of an Access Control List by the BMC Firmware that allows applications executing on the host OS to have access to a limited set of IPMI commands using the KCS interfaces. This is a non-compliant IPMI configuration that may impact the operation of the Server Management Software running on the Host OS. For example, the IPMI commands that are used to provision the BMC configuration settings, or control the state of the Host OS, will be disallowed when the BMC KCS interface is in restricted mode. This only applies to the IPMI commands over the KCS interfaces, and does not apply to the authenticated network interfaces to the BMC.

KCS access is required for the host BIOS during Pre-Boot phase. BIOS communicates with BMC for platform configurations through these channels. Thus BIOS use of KCS is trusted between a platform reset and the end of the BIOS DXE phase. For unconditional and conditional KCS access, two host phases are needed:

1. Pre-Boot phase. This is the phase between platform reset and the end of DXE signaled by the CORE-BIOS-DONE signal before option ROMs are executed. BMC has the below assumptions and KCS handling policies:
  - Core BIOS is trusted
  - KCS commands accepted from BIOS without authentication
  - Transitions to Post-Boot after BIOS sends CORE-BIOS-DONE signal to BMC
2. Post-Boot phase. This is the phase for BIOS to load option ROMs and boot the host OS and host OS execution. BMC assumptions and KCS handling policies are as below:
  - Triggered by CORE-BIOS-DONE signal from BIOS
  - When KCS Policy Control Mode is set to “Allow All”
    - KCS commands accepted from BIOS/EFI, Host OS (Ring0) without authentication
    - Warning Indicator set (EWS banner with explanatory help text, security sensor)
    - Transitions to “Restricted” or “Deny All” with IPMI command from any interface

- When KCS Policy Control Mode is set to “Restricted” or “Deny All”:
  - Triggered by IPMI Command to set KCS Policy Control Mode out of “Allow All”
  - In KCS Restricted Mode, only KCS commands listed in the Access Control List (ACL) are accepted from BIOS/EFI, Host OS (Ring 0) without authentication, or no KCS commands in “Deny All” Mode.
  - May transition back to KCS “Allow All” Mode with:
    - Authenticated IPMI/RMCP+ command from OOB (LAN etc.)
    - Authenticated EWS/Redfish operations
    - Force Firmware Update Jumper (safe mode) allows reset mode from KCS

The following table shows under each KCS Policy Control Mode and host booting phase, KCS commands will be serviced or not.

**Table 100. BMC KCS Policy Control Modes and KCS command service definition**

KCS Policy Control Modes	Description	Pre-Boot	Post-Boot
<b>Allow All</b>	<ul style="list-style-type: none"> <li>• Default state when customer receives board</li> <li>• Alerts on EWS page and/or security sensor warn owner that the BMC is an unsafe state</li> <li>• Can re-enter KCS Policy Control Mode “Allow All” through authenticated OOB interface or through FFUJ (KCS allowed in safe mode)</li> </ul>	All KCS Commands Permitted	All KCS Commands Permitted
<b>Restricted</b>	<ul style="list-style-type: none"> <li>• Transitions from “Allow All” when platform owner issues command to set KCS Policy Control Mode (or EWS)</li> </ul>	All KCS Commands Permitted	Only commands in the Access Control List are permitted
<b>Deny All</b>	<ul style="list-style-type: none"> <li>• Transitions from other modes when platform owner issues commands to set KCS Policy Control Mode (EWS).</li> </ul>	All KCS Commands Permitted	No KCS Commands Permitted

BMC implements OEM type sensor with offsets set to 3 KCS Policy Control Mode. SEL will be captured if KCS Policy Control Mode is changed.

**Table 101. KCS Policy Sensor**

Byte	Field	Description
<b>11</b>	Sensor Type	DAh - KCS Mode
<b>12</b>	Sensor Number	DAh
<b>13</b>	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 7Ah(OEM Defined)
<b>14</b>	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset 03h = KCS Allow all Mode 04h = KCS Restricted mode 05h = KCS Deny all mode
<b>15</b>	Event Data 2	[7:0] –FFh Unspecified.
<b>16</b>	Event Data 3	[7:0] –FFh Unspecified.

## 12. Hot-Swap Controller Backplane Events

In all Intel® Server Systems product families, the backplanes follow a hybrid architecture, in which the IPMI functionality previously supported in the hot-swap controller (HSC) is integrated into the BMC family.

### 12.1 Hot-Swap Controller (HSC) Backplane Temperature Sensor

There is a thermal sensor on the Hot-Swap Backplane to measure the ambient temperature.

**Table 102. HSC Backplane Temperature Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	01h = Temperature
12	Sensor Number	27h = Hot-swap Backplane 1 Temperature (1U HSBP Temp) 29h = Hot-swap Backplane 1 Temperature (2U HSBP 1 Temp) 2Ah = Hot-swap Backplane 2 Temperature (2U HSBP 2 Temp) 2Bh = Hot-swap Backplane 3 Temperature (2U HSBP 3 Temp) E0h = Hot-swap Backplane 4 Temperature (HSBP 4 Temp)
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 01h (Threshold)
14	Event Data 1	[7:6] – 01b = Trigger reading in Event Data 2 [5:4] – 01b = Trigger threshold in Event Data 3 [3:0] – Event Trigger Offset as described in Table 103
15	Event Data 2	Reading that triggered event
16	Event Data 3	Threshold value that triggered event

**Table 103. HSC Backplane Temperature Sensor – Event Trigger Offset – Next Steps**

Event Trigger		Assertion Severity	Deassertion Severity	Description	Next Steps
00h	Lower non-critical going low	Degraded	OK	The temperature has dropped below its lower non-critical threshold.	<ol style="list-style-type: none"> <li>1. Check for clear and unobstructed airflow into and out of the chassis.</li> <li>2. Ensure the SDR is programmed and correct chassis has been selected.</li> <li>3. Ensure there are no fan failures.</li> <li>4. Ensure the air used to cool the system is within the thermal specifications for the system (typically below 35 °C).</li> </ol>
02h	Lower critical going low	Non-fatal	Degraded	The temperature has dropped below its lower critical threshold.	
07h	Upper non-critical going high	Degraded	OK	The temperature has gone over its upper non-critical threshold.	
09h	Upper critical going high	Non-fatal	Degraded	The temperature has gone over its upper critical threshold.	

### 12.2 Hard Disk Drive Monitoring Sensor

The new backplane design for Intel® Server Systems based on the 3rd Gen Intel® Xeon® Scalable processor family, moves IPMI ownership of the HDD sensors to the BMC. Systems may have multiple storage backplanes. Hard Disk Drive status monitoring is supported through disk status sensors owned by the BMC.

**Table 104. Hard Disk Drive Monitoring Sensor Typical Characteristics**

Byte	Field	Description
11	Sensor Type	0Dh = Drive Slot (Bay)
12	Sensor Number	60h-68h = Hard Disk Drive 15–23 Status

## System Event Log (SEL) Troubleshooting Guide

Byte	Field	Description
		E2h-E3h = Rear Hard Disk Drive 0-1 Status F0h-FEh = Hard Disk Drive 0-14 Status
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] - 00b = Unspecified Event Data 2 [5:4] - 00b = Unspecified Event Data 3 [3:0] - Event Trigger Offset as described in Table 105
15	Event Data 2	Not used
16	Event Data 3	Not used

**Table 105. Hard Disk Drive Monitoring Sensor – Event Trigger Offset – Next Steps**

Event Trigger	Description	Next Steps
00h	Drive Presence	If during normal operation the state changes unexpectedly, ensure that the drive is seated properly and the drive carrier is properly latched. If that does not work, replace the drive.
01h	Drive Fault	
07h	Rebuild/Remap in progress	<ul style="list-style-type: none"> <li>• This is expected after replacing a hard drive.</li> <li>• This is expected if the system has a hot spare and one of the drives failed. Check logs for which drive has failed.</li> <li>• If this is seen unexpectedly, it could be an indication of a drive that is close to failing.</li> </ul>

## 13. Intel® Management Engine (Intel® ME) Events

The Intel® Management Engine (Intel® ME) controls the platform environmental control interface (PECI) and also contains the Intel® Node Manager (Intel® NM) functionality.

### 13.1 Intel® ME Firmware Health Event

This sensor is used in Platform Event messages to the BMC containing health information including but not limited to firmware upgrade and application errors.

**Table 106. Intel® ME Firmware Health Event Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	002Ch or 602Ch – Intel® ME Firmware
11	Sensor Type	DCh = OEM
12	Sensor Number	17h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 75h (OEM)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Health event type – 0h (Firmware Status)
15	Event Data 2	See Table 107
16	Event Data 3	See Table 107

#### 13.1.1 Intel® ME Firmware Health Event – Next Steps

In Table 107, Event Data 3 is only noted for specific errors.

If the issue continues to be persistent, provide the content of Event Data 3 to Intel support team for interpretation. Event Data 3 codes are in general not documented, because their meaning only provides some clues, varies, and usually needs to be individually interpreted.

**Table 107. Intel® ME Firmware Health Event Sensor – Next Steps**

ED2	ED3	Description	Next Steps
00h		Recovery GPIO forced. Recovery Image loaded due to recovery MGPIO pin asserted. Pin number is configurable in factory presets. Default recovery pin is MGPIO1.	Deassert MGPIO1 and reset the Intel® ME.
01h		Image execution failed. Recovery Image or backup operational image loaded because operational image is corrupted. This may be either caused by flash device corruption or failed upgrade procedure.	Either the flash device must be replaced (if error is persistent) or the upgrade procedure must be started again.
02h		Flash erase error. Error during flash erasure procedure.	The flash device must be replaced.
03h	00h	Flash state information.	Flash partition table, recovery image or factory presets image corrupted.
	01h	Check extended info byte in ED3 whether this is wear-out protection causing this event. If so just wait until wear-out protection expires, otherwise probably the flash device must be replaced (if error is persistent).	Flash erase limit has been reached.
	02h		Flash write limit has been reached; writing to flash has been disabled.
	03h		Writing to the flash has been enabled.



## System Event Log (SEL) Troubleshooting Guide

ED2	ED3	Description	Next Steps
04h		Internal error. Error during firmware execution – FW Watchdog Timeout.	Operational image needs to be updated to other version or hardware board repair is needed (if error is persistent).
05h		BMC did not respond to cold reset request and Intel® ME rebooted the platform.	Verify the Intel® Node Manager configuration.
06h		Direct Flash update requested by the BIOS. Intel® ME firmware will switch to recovery mode to perform full update from the BIOS.	This is transient state. Intel® ME firmware will return to operational mode after successful image update performed by the BIOS.
07h		Manufacturing error. Wrong manufacturing configuration detected by Intel® ME firmware.	The flash device must be replaced (if error is persistent).
	00h	Generic error	
	01h	Wrong or missing VSCC table	
	02h	Wrong sensor scanning period in PIA	
	03h	Wrong device definition in PIA	
	04h	Wrong SMART/CLST configuration	
	05h	Intel® ME FW configuration is inconsistent or out of range	
	0Ah	Percentage of flash write operations, which have been conducted	
08h		Persistent storage integrity error. Flash file system error detected.	If error is persistent, restore factory presets using “Force ME Recovery” IPMI command or by doing AC power cycle with Recovery jumper asserted.
09h		Firmware Exception.	Restore factory presets using “Force ME Recovery” IPMI command or by doing AC power cycle with Recovery jumper asserted. If this does not clear the issue, reflash the SPI flash.
0Ah		Flash Wear-Out Protection Warning. Warning threshold for number of flash operations has been exceeded.	No immediate repair action needed. This is just a warning event.
0Ch		Invalid SCMP interface state.	This is a warning event that indicates that the SCMP interface was in a wrong state. The interface shall normally recover from such a state. It likely indicates an SW or FW defect. SW or FW fix is needed in such a situation.
0Dh		PECI over DMI interface error. This is a notification that PECI over DMI interface failure was detected and it is not functional anymore. It may indicate the situation when PECI over DMI was not configured by BIOS or a defect, which may require a CPU Host reset to recover from.	ME FW will switch to Serial PECI interface when connected directly to chipset. Recovery via CPU Host reset or platform reset.
0Eh		MCTP interface error. This is a notification that MCTP interface failure was detected and it is not functional anymore. It may indicate the situation when MCTP was not configured by BIOS or a defect, which may need a Host reset to recover from.	Recovery via CPU Host reset or platform reset.
0Fh–FFh		Reserved.	

## 13.2 Intel® Node Manager Exception Event

An Intel® Node Manager exception event is sent each time maintained policy power limit is exceeded over Correction Time Limit.

**Table 108. Intel® Node Manager Exception Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	002Ch or 602Ch – Intel® ME Firmware
11	Sensor Type	DCh = OEM
12	Sensor Number	18h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 72h (OEM)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3] – Node Manager Policy event 0 – Reserved 1 – Policy Correction Time Exceeded – Policy did not meet the contract for the defined policy. The policy continues to limit the power or shut down the platform based on the defined policy action. [2] – Reserved [1:0] – 00b
15	Event Data 2	[4:7] – Reserved [0:3] – Domain Id 00h – Entire platform. 01h – CPU subsystem. 02h – Memory subsystem. 03h – HW Protection. 04h – High Power I/O subsystem. Others – Reserved
16	Event Data 3	Policy Id

### 13.2.1 Intel® Node Manager Exception Event – Next Steps

This is an informational event. Next steps depend on the policy that was set. See the *Intel® Node Manager Specification* for more details.

## 13.3 Intel® Node Manager Health Event

An Intel® Node Manager Health Event message provides a runtime error indication about Intel® Intelligent Power Node Manager's health. Types of service that can send an error are defined as follows:

- Misconfigured policy Error reading power data.
- Error reading inlet temperature.

**Table 109. Intel® Node Manager Health Event Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	002Ch or 602Ch – Intel® ME Firmware
11	Sensor Type	DCh = OEM
12	Sensor Number	19h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 73h (OEM)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Health Event Type = 02h (Sensor Node Manager)
15	Event Data 2	[7:4] – Error type 0–7 – Reserved 8 – Outlet Temperature Reading Failure 9 – Volumetric Airflow Reading Failure 10 – Policy Misconfiguration 11 – Power Sensor Reading Failure 12 – Inlet Temperature Reading Failure 13 – Host Communication error 14 – Real-time clock synchronization failure 15 – Platform shutdown initiated by NM policy due to execution of action defined by Policy Exception Action [3:0] – Domain Id 00h – Entire platform 01h – CPU subsystem 02h – Memory subsystem 03h – HW Protection 04h – High Power I/O subsystem Others – Reserved
16	Event Data 3	If Error type = 10 or 15 <Policy Id> If Error type = 11 <Power Sensor Address> If Error type = 12 <Inlet Sensor Address> Otherwise set to 0.

### 13.3.1 Intel® Node Manager Health Event – Next Steps

Misconfigured policy can happen if the max/min power consumption of the platform exceeds the values in policy due to hardware reconfiguration.

First occurrence of not acknowledged event will be retransmitted no faster than every 300 milliseconds.

Real-time clock synchronization failure alert is sent when Intel® NM is enabled and capable of limiting power, but within 10 minutes the firmware cannot obtain valid calendar time from the host side, so Intel® NM cannot handle suspension periods.

Next steps depend on the policy that was set. See the *Intel® Node Manager Specification* for more details.

### 13.4 Intel® Node Manager Operational Capabilities Change

This message provides a runtime error indication about Intel® Intelligent Power Node Manager's operational capabilities. This applies to all domains.

Assertion and deassertion of these events are supported.

**Table 110. Intel® Node Manager Operational Capabilities Change Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	002Ch or 602Ch – Intel® ME Firmware
11	Sensor Type	DCh = OEM
12	Sensor Number	1Ah
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 74h (OEM)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Current state of Operational Capabilities. Bit pattern: 0 – Policy interface capability 0 – Not Available 1 – Available 1 – Monitoring capability 0 – Not Available 1 – Available 2 – Power limiting capability 0 – Not Available 1 – Available
15	Event Data 2	Not used
16	Event Data 3	Not used

### 13.4.1 Intel® Node Manager Operational Capabilities Change – Next Steps

Policy Interface available indicates that Intel® Intelligent Power Node Manager is able to respond to the external interface about querying and setting Intel® Intelligent Power Node Manager policies. This is generally available as soon as the microcontroller is initialized.

Monitoring Interface available indicates that Intel® Intelligent Power Node Manager has the capability to monitor power and temperature. This is generally available when firmware is operational.

Power limiting interface available indicates that Intel® Intelligent Power Node Manager can do power limiting and is indicative of an Advanced Configuration and Power Interface (ACPI)-compliant OS loaded (unless the OEM has indicated support for non-ACPI compliant OS).

Current value of not acknowledged capability sensor is retransmitted no faster than every 300 milliseconds.

Next steps depend on the policy that was set. See the *Intel® Node Manager Specification* for more details.

## 13.5 Intel® Node Manager Alert Threshold Exceeded

Policy Correction Time Exceeded Event is sent each time maintained policy power limit is exceeded over Correction Time Limit.

**Table 111. Intel® Node Manager Alert Threshold Exceeded Sensor Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	002Ch or 602Ch – Intel® ME Firmware
11	Sensor Type	DCh = OEM
12	Sensor Number	1Bh
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 72h (OEM)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3] = Node Manager Policy event 0 – Threshold exceeded 1 – Policy Correction Time Exceeded – Policy did not meet the contract for the defined policy. The policy continues to limit the power or shut down the platform based on the defined policy action. [2] – Reserved [1:0] – Threshold Number. 0 to 2 – Threshold index
15	Event Data 2	[7:4] – Reserved [3:0] – Domain Id 00h – Entire platform 01h – CPU subsystem 02h – Memory subsystem 03h – HW Protection 04h – High Power I/O subsystem Others – Reserved
16	Event Data 3	Policy ID

### 13.5.1 Intel® Node Manager Alert Threshold Exceeded – Next Steps

First occurrence of not acknowledged event will be retransmitted no faster than every 300 milliseconds.

First occurrence of Threshold exceeded event assertion/deassertion will be retransmitted no faster than every 300 milliseconds.

Next steps depend on the policy that was set. See the *Node Manager Specification* for more details.

## 13.6 Intel® Node Manager SmarT and CLST Sensor

The Intel® Node Manager monitors the power supplies in the system for an SMBALERT# assertion in the power supplies. If it deems that this is caused by what would be considered a system SmarT/CLST event, then it throttles the total system power to prevent the system failure. This is logged as a SmarT/CLST event.

**Table 112. Intel® Node Manager Smart/CLST Event Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	002Ch or 602Ch – Intel® ME Firmware
11	Sensor Type	DCh = OEM
12	Sensor Number	B2h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 03h (Digital Discrete)
14	Event Data 1	[7:6] – 01b = Previous state and/or severity in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Offset from Event/Reading Code 0h – State Deasserted 1h – State Asserted
15	Event Data 2	[7:4] – Optional offset from ‘Severity’ Event/Reading Code. 00h - transition to OK 01h - transition to noncritical from OK 02h - transition to critical from less severe 03h - transition to unrecoverable from less severe 04h - transition to noncritical from more severe 05h - transition to critical from unrecoverable 06h - transition to unrecoverable 07h - monitor 08h - informational [3:0] - Fh
16	Event Data 3	Corresponding Power Supply Status sensor number or 0 if the source of Smart&CLST assertion is external (for example BMC).

**Table 113. Smart And CLST Sensor Severity Codes**

Severity Code	Description	PSU Condition
00h	Transition to OK	All present PSU faults disappeared.
01h	Transition to noncritical from OK	SMBAlert# has been asserted by PSU but it should be ignored (e.g. PSU goes to off state due insufficient input voltage)
02h	Transition to critical from less severe	SMBAlert# was asserted due to one of the following PSU events: <ul style="list-style-type: none"> <li>• UV_Fault or</li> <li>• OT_Warning or</li> <li>• OC_Warning</li> </ul>
04h	Transition to noncritical from more severe	There has been a critical condition and one of the following events happened: <ul style="list-style-type: none"> <li>• UV Fault lasted more than preconfigured time (default 500ms) or</li> <li>• PSU causing disappeared or</li> <li>• PSU unit become off or</li> <li>• OT warning lasted more than 500ms for one PSU and there is another PSU present with no OT warning.</li> </ul>

### 13.6.1 Intel® Node Manager Smart/CLST Event – Next Steps

1. Look for any other events in the System Event Log for correlation.
2. Ensure that there are no issues with any of the installed power supplies.
3. If there is only one power supply then consider adding an additional power supply to handle the required load.

## 14. Microsoft Windows\* Records

With Microsoft Windows Server\* 2003 R2 and later versions, an Intelligent Platform Management Interface (IPMI) driver was added. This added the capability of logging some operating system events to the SEL. The driver can write multiple records to the SEL for the following events:

- Boot-up
- Shutdown
- Bug Check / Blue Screen

### 14.1 Boot Up Event Records

When the system boots into the Microsoft Windows\* OS, two events can be logged. The first is a boot-up record and the second is an OEM event. These are informational only records.

**Table 114. Boot Up Event Record Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0041h – System Software with an ID = 20h
11	Sensor Type	1Fh = OS Boot
12	Sensor Number	00h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset = 1h = C: boot completed
15	Event Data 2	Not used
16	Event Data 3	Not used

**Table 115. Boot Up OEM Event Record Typical Characteristics**

Byte	Field	Description
1, 2	Record ID	ID used for SEL Record access.
3	Record Type	[7:0] – DC h = OEM timestamped, bytes 8–16 OEM defined.
4–7	Timestamp	Time when the event was logged. The least significant byte is first.
8–10	IPMI Manufacturer ID	0137h (311d) = IANA enterprise number for Microsoft.
11	Record ID	Sequential number reflecting the order in which the records are read. The numbers start at one for the first entry in the SEL and continue sequentially to n, the number of entries in the SEL.
12–15	Boot Time	Timestamp of when the system booted into the OS.
16	Reserved	00h

### 14.2 Shutdown Event Records

When the system shuts down from the Microsoft Windows\* OS, multiple events can be logged. The first is an OS Stop/Shutdown Event Record; this can be followed by a shutdown reason code OEM record, and then zero or more shutdown comment OEM records. These are all informational only records.

**Table 116. Shutdown Reason Code Event Record Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0041h – System Software with an ID = 20h
11	Sensor Type	20h = OS Stop/Shutdown
12	Sensor Number	00h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset = 3h = OS Graceful Shutdown
15	Event Data 2	Not used
16	Event Data 3	Not used

**Table 117. Shutdown Reason OEM Event Record Typical Characteristics**

Byte	Field	Description
1, 2	Record ID	ID used for SEL Record access
3	Record Type	[7:0] – DDh = OEM timestamped, bytes 8–16 OEM defined
4–7	Timestamp	Time when the event was logged. LS byte first.
8–10	IPMI Manufacturer ID	0137h (311d) = IANA enterprise number for Microsoft
11	Record ID	Sequential number reflecting the order in which the records are read. The numbers start at one for the first entry in the SEL and continue sequentially to n, the number of entries in the SEL.
12–15	Shutdown Reason	Shutdown Reason code from the registry (LSB first): HKLM/Software/Microsoft/Windows/CurrentVersion/Reliability/shutdown/ReasonCode
16	Reserved	00h

**Table 118. Shutdown Comment OEM Event Record Typical Characteristics**

Byte	Field	Description
1, 2	Record ID	ID used for SEL Record access
3	Record Type	[7:0] – DDh = OEM timestamped, bytes 8–16 OEM defined
4–7	Timestamp	Time when the event was logged. The least significant byte is first.
8–10	IPMI Manufacturer ID	0137h (311d) = IANA enterprise number for Microsoft 0157h (343d) = IANA enterprise number for Intel The value logged depends on the Intelligent Management Bus Driver (IMBDRV) that is loaded.
11	Record ID	Sequential number reflecting the order in which the records are read. The numbers start at one for the first entry in the SEL and continue sequentially to n, the number of entries in the SEL.
12–15	Shutdown Comment	Shutdown Comment from the registry (least significant bit first): HKLM/Software/Microsoft/Windows/CurrentVersion/Reliability/shutdown/Comment
16	Reserved	00h

### 14.3 Bug Check/Blue Screen Event Records

When the system experiences a bug check (blue screen), multiple records are written to the event log. The first record could be a Bug Check, Blue Screen OS Stop, or Shutdown Event Record followed by multiple Bug



Check/Blue Screen code OEM records that contain the Bug Check/Blue Screen codes. This information can be used to determine what caused the failure.

**Table 119. Bug Check/Blue Screen – OS Stop Event Record Typical Characteristics**

Byte	Field	Description
8, 9	Generator ID	0041h – System Software with an ID = 20h
11	Sensor Type	20h = OS Stop/Shutdown
12	Sensor Number	00h
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 00b = Unspecified Event Data 2 [5:4] – 00b = Unspecified Event Data 3 [3:0] – Event Trigger Offset = 1h = Runtime Critical Stop (that is, “core dump”, “blue screen”)
15	Event Data 2	Not used
16	Event Data 3	Not used

**Table 120. Bug Check/Blue Screen Code OEM Event Record Typical Characteristics**

Byte	Field	Description
1, 2	Record ID	ID used for SEL Record access
3	Record Type	[7:0] – DEh = OEM timestamped, bytes 8–16 OEM defined
4–7	Timestamp	Time when the event was logged. The least significant byte is first.
8–10	IPMI Manufacturer ID	0137h (311d) = IANA enterprise number for Microsoft 0157h (343d) = IANA enterprise number for Intel The value logged depends on the Intelligent Management Bus Driver (IMBDRV) that is loaded.
11	Sequence Number	Sequential number reflecting the order in which the records are read. The numbers start at 1 for the first entry in the SEL and continue sequentially to n, the number of entries in the SEL.
12–15	Bug Check/Blue Screen Data	The first record of this type contains the Bug Check/Blue Screen Stop code and is followed by the four Bug Check/Blue Screen parameters. The east significant byte is first. Each of the Bug Check/Blue Screen parameters requires two records each. Both of the two records for each parameter have the same Record ID. There is a total of nine records.
16	Operating system type	00 = 32-bit OS 01 = 64-bit OS

## 15. Linux\* Kernel Panic Records

The Open IPMI driver supports the ability to put semi-custom and custom events in the system event log if a panic occurs. Enable the “Generate a panic event to all BMCs on a panic” option to get one event on a panic in a standard IPMI event format. Enable the “Generate OEM events containing the panic string” option to get a set of OEM events holding the panic string.

**Table 121. Linux\* Kernel Panic Event Record Characteristics**

Byte	Field	Description
8, 9	Generator ID	0021h – Kernel
10	EvM Rev	03h = IPMI 1.0 format
11	Sensor Type	20h = OS Stop/Shutdown
12	Sensor Number	The first byte of the panic string (0 if no panic string)
13	Event Direction and Event Type	[7] Event direction 0b = Assertion Event 1b = Deassertion Event [6:0] Event Type = 6Fh (Sensor Specific)
14	Event Data 1	[7:6] – 10b = OEM code in Event Data 2 [5:4] – 10b = OEM code in Event Data 3 [3:0] – Event Trigger Offset = 1h = Runtime Critical Stop (a.k.a. “core dump”, “blue screen”)
15	Event Data 2	The second byte of the panic string
16	Event Data 3	The third byte of the panic string

**Table 122. Linux\* Kernel Panic String Extended Record Characteristics**

Byte	Field	Description
1, 2	Record ID	ID used for SEL Record access
3	Record Type	[7:0] – F0h = OEM non-timestamped, bytes 4–16 OEM defined
4	Slave Address	The slave address of the card saving the panic
5	Sequence Number	A sequence number (starting at zero)
6–16	Kernel Panic Data	These hold the panic sting. If the panic string is longer than 11 bytes, multiple messages are sent with increasing sequence numbers.

## Appendix A. Glossary

Term	Definition
<b>ACPI</b>	Advanced Configuration and Power Interface
<b>AER</b>	Advanced Error Reporting
<b>BIOS</b>	Basic Input/Output System
<b>BMC</b>	Baseboard Management Controller
<b>CATERR</b>	Catastrophic Error
<b>CFM</b>	Cubic Feet per Minute
<b>CLST</b>	Closed Loop System Throttling
<b>DIMM</b>	Dual Inline Memory Module
<b>DLLP</b>	Data Link Layer Packet
<b>DTS</b>	Digital Thermal Sensor
<b>ECC</b>	Error Correction Code
<b>EWS</b>	Embedded Web Server
<b>FP</b>	Front Panel
<b>FRU</b>	Field Replaceable Unity
<b>GPGPU</b>	General-purpose computing on graphics processing unit
<b>HDD</b>	Hard Disk Drive
<b>HSC</b>	Hot-Swap Controller
<b>HSBP</b>	Hot-Swap Backplane
<b>IANA</b>	Internet Assigned Numbers Authority
<b>IERR</b>	Internal Error
<b>IPMI</b>	Intelligent Platform Management Interface
<b>IPMB</b>	Intelligent Platform Management Bus
<b>LUN</b>	Logical Unit Number
<b>MCTP</b>	Management Component Transport Protocol
<b>Intel® ME</b>	Intel® Management Engine
<b>MSR</b>	Model Specific Register
<b>NIC</b>	Network Interface Controller
<b>Intel® NM</b>	Intel® Node Manager
<b>NMI</b>	Non-Maskable Interrupt
<b>OEM</b>	Original Equipment Manufacturer
<b>OOB</b>	Out-of-band
<b>OS</b>	Operating System
<b>PCH</b>	Platform Controller Hub
<b>PCIe*</b>	PCI Express*
<b>PECI</b>	Platform Environmental Control Interface
<b>PEF</b>	Platform Event Filters
<b>PERR</b>	Parity Error
<b>POST</b>	Power On Self Test
<b>PSU</b>	Power Supply Unit
<b>PWM</b>	Pulse Width Modulation
<b>Intel® QPI</b>	Intel® QuickPath Interconnect
<b>RAS</b>	Reliability, Availability, Serviceability
<b>RqSA</b>	Requester's Slave Address

## System Event Log (SEL) Troubleshooting Guide

Term	Definition
<b>SAS</b>	Serial Attached SCSI
<b>SATA</b>	Serial ATA
<b>SCMP</b>	Software Configuration Management Plan
<b>SDR</b>	Sensor Data Record
<b>SmaRT</b>	Smart Ride Through
<b>SEL</b>	System Event Log
<b>SERR</b>	System Error
<b>SMI</b>	System Management Interrupt
<b>SSB</b>	South Side Bridge
<b>TLP</b>	Transaction Layer Packet
<b>TPS</b>	Technical Product Specification
<b>TSOD</b>	Temperature Sensor on DIMM
<b>VR</b>	Voltage Regulator
<b>VSCC</b>	Vendor Specific Component Capabilities